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April 1st, 2010
Renesas Electronics Corporation

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April 1, 2003

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HD404328 Series

RENESAS

Rev. 6.0
Sept. 1998

Description

The HD404328 Series is an HMCS400-Series microcomputer designed to increase program productivity and also to incorporate large-capacity memory. Each microcomputer has an LCD controller/driver, A/D converter, and zero-crossing detection circuit. Each also has a 32.768-kHz oscillator and low-power dissipation modes.

The HD404328 Series includes eight chips: the HD404324 and HD404324U with 4-kword ROM; the HD404326 and HD404326U with 6-kword ROM; the HD404328 and HD404328U with 8-kword ROM; the HD4074329 and HD4074329U with 16-kword PROM. The HD404324U, HD404326U, HD404328U and HD4074329U are designed to reduce current dissipation in subactive mode and watch mode.

The HD4074329 and HD4074329U, which include PROM, are ZTAT™ microcomputers that can dramatically shorten system development periods and smooth the process from debugging to mass production. (The PROM program specifications are the same as for the 27256.)

Features

- 4,096-word × 10-bit ROM (HD404324, HD404324U)
  6,144-word × 10-bit ROM (HD404326, HD404326U)
- 8,192-word × 10-bit ROM (HD404328, HD404328U)
  16,384-word × 10-bit PROM (HD4074329, HD4074329U)
- 280-digit × 4-bit RAM (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
  536-digit × 4-bit RAM (HD4074329, HD4074329U)
- 35 I/O pins
  - 2 input pins
  - 33 input/output pins, including 8 high-current pins (15 mA, max.) and 16 pins multiplexed with LCD segment pins
- Three timer/counters
- 8-bit clock-synchronous serial interface
- 8-bit × 4-channel A/D converter
- 12-digit LCD controller/driver (24 SEG × 4 COM)
  (HD404324U, HD404326U, HD404328U, HD4074329U: External LCD voltage division resistors are required)

- Zero-crossing detection circuit
- Eight interrupt sources
  - — Two external sources, including one double-edge function
  - — Six internal sources
- Subroutine stack
  - — Up to 16 levels, including interrupts
- Four low-power dissipation modes
  - — Subactive mode
  - — Standby mode
  - — Watch mode
  - — Stop mode
- Built-in oscillator
  - — Crystal or ceramic oscillator (external clock also enabled)
  - — 32.768 kHz crystal subclock
- Instruction cycle time: 2 µs (f_{OSC} = 4 MHz)
- Two operating modes
  - — MCU mode
  - — PROM mode (HD4074329, HD4074329U)

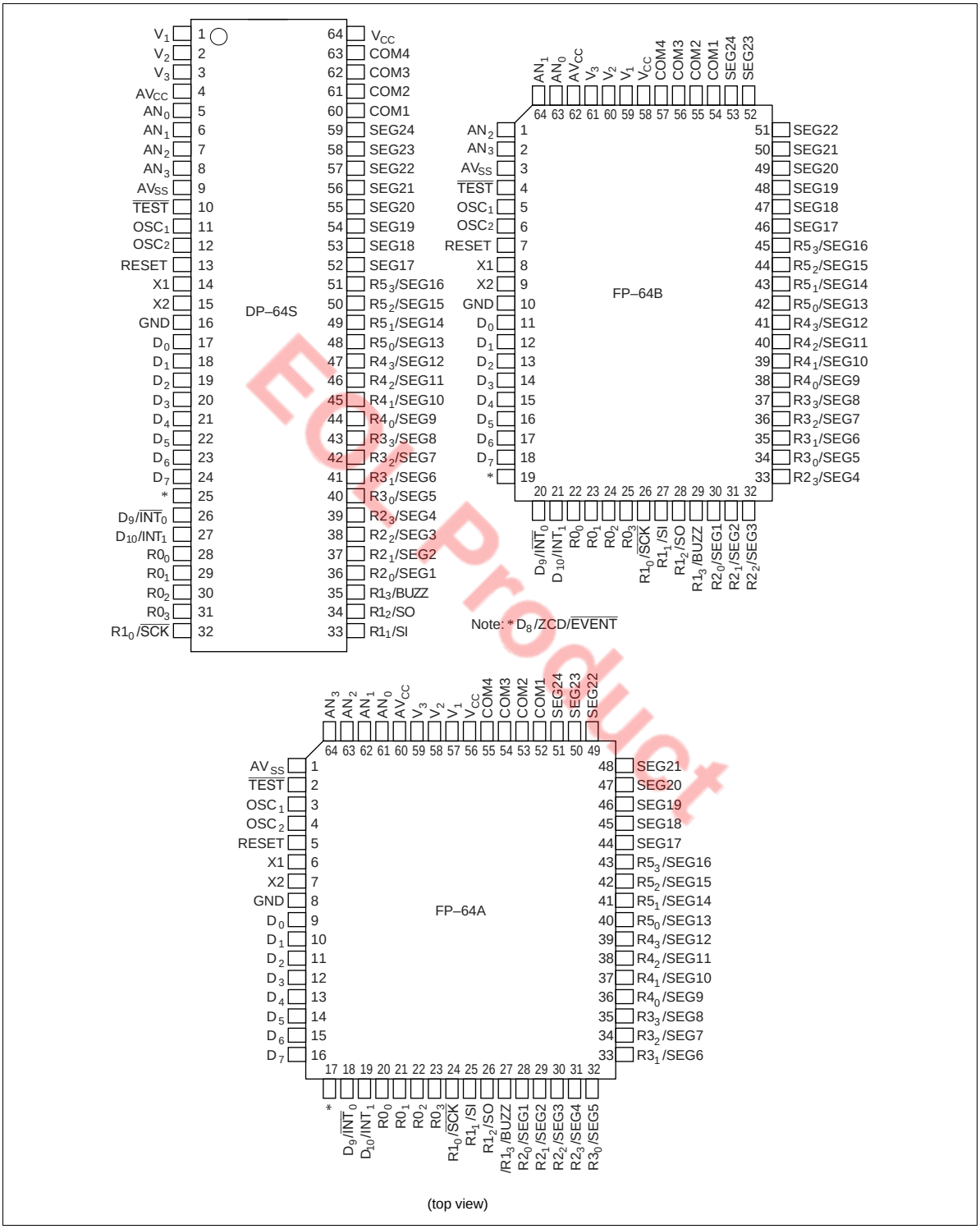
ZTAT™ is a trademark of Hitachi Ltd.

Ordering Information

Type	Product Name	Model Name	ROM (Words)	RAM (Digits)	Package
Mask ROM	HD404324	HD404324S	4,096	280	DP-64S
		HD404324FS			FP-64B
		HD404324H			FP-64A
	HD404326	HD404326S	6,144		DP-64S
		HD404326FS			FP-64B
		HD404326H			FP-64A
	HD404328	HD404328S	8,192		DP-64S
		HD404328FS			FP-64B
		HD404328H			FP-64A
	HD404324U*	HD404324US	4,096		DP-64S
		HD404324UFS			FP-64B
		HD404324UH			FP-64A
	HD404326U*	HD404326US	6,144		DP-64S
		HD404326UFS			FP-64B
		HD404326UH			FP-64A
	HD404328U*	HD404328US	8,192		DP-64S
		HD404328UFS			FP-64B
		HD404328UH			FP-64A
ZTAT™	HD4074329	HD4074329S	16,384	536	DP-64S
		HD4074329FS			FP-64B
	HD4074329U*	HD4074329US			DP-64S
		HD4074329UFS			FP-64B

Note: * Type with external LCD voltage-dividing resistor.

Pin Arrangement

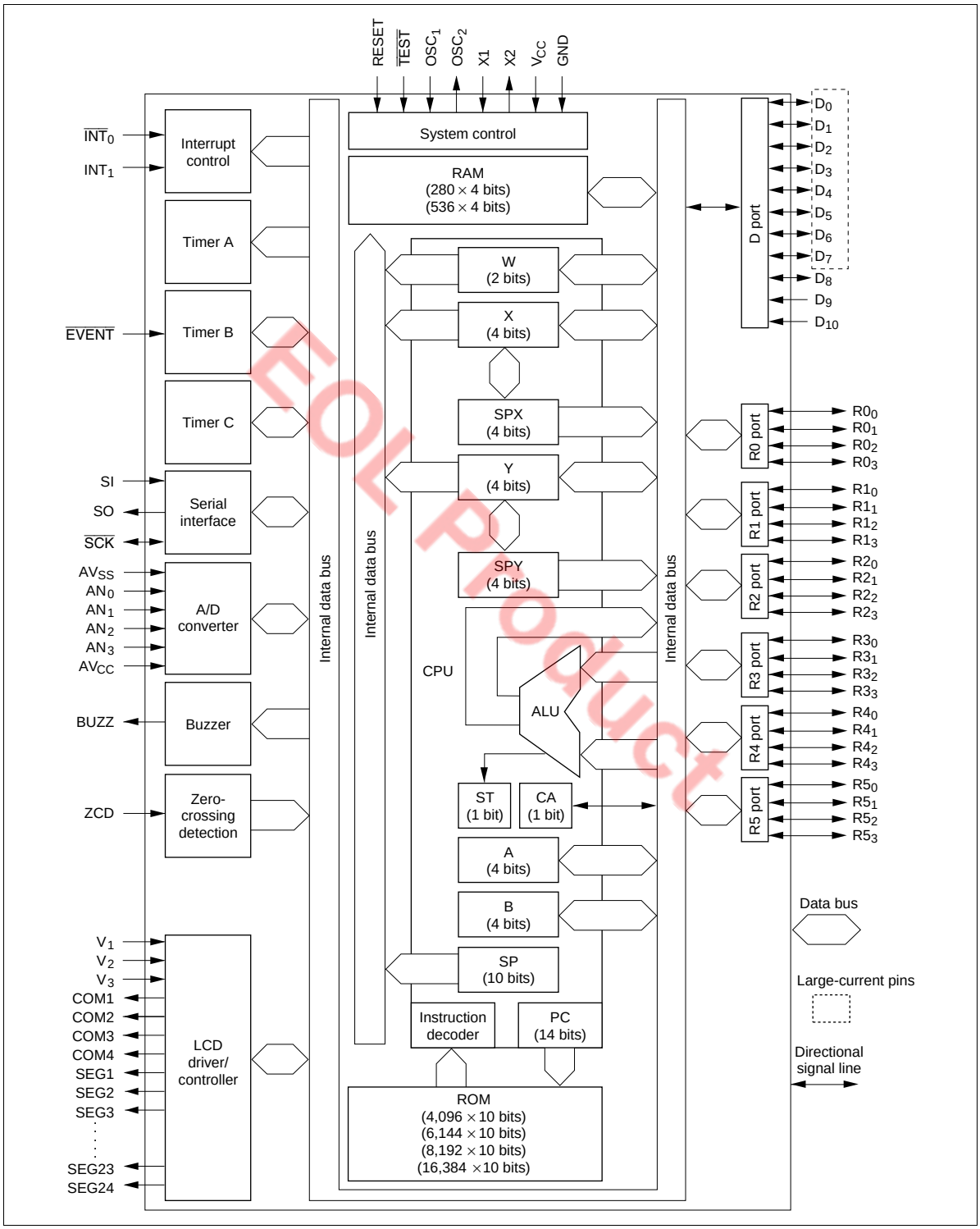


Pin Description

Item	Symbol	Pin Number DP-64S DC-64S	FP-64B	FP-64A	I/O	Function
Power supply	V_{CC}	64	58	56		Applies power voltage
	GND	16	10	8		Connected to ground
Test	$\overline{TEST}$	10	4	2	I	Used for factory testing only; connect this pin to V_{CC}
Reset	RESET	13	7	5	I	Resets the MCU
Oscillator	OSC_1	11	5	3	I	Input/output pins for the internal oscillator circuit; connect them to a crystal, ceramic, or external oscillator circuit
	OSC_2	12	6	4	O	
	X1	14	8	6	I	Used for a 32.768-kHz crystal for clock purposes; if not used, fix X1 to V_{CC} and leave X2 open
	X2	15	9	7	O	
Port	D_0–D_8	17–25	11–19	9–17	I/O	Input/output ports addressed by individual bits; pins D_0–D_7 are high-current pins that can each supply up to 15 mA
	D_9, D_{10}	26, 27	20, 21	18, 19	I	Input ports addressable by individual bits
	$R0_0$–$R5_3$	28–51	22–45	20–43	I/O	Input/output ports addressable in 4-bit units
Interrupt	$\overline{INT_0}$, INT_1	26, 27	20, 21	18, 19	I	Input pins for external interrupts
Serial interface	$\overline{SCK}$	32	26	24	I/O	Serial interface clock input/output pin
	SI	33	27	25	I	Serial interface receive data input pin
	SO	34	28	26	O	Serial interface transmit data output pin
Buzzer	BUZZ	35	29	27	O	Buzzer signal output pin
LCD	V_1, V_2, V_3	1–3	59–61	57–59		Power pins for LCD driver; can be left open in operation because they are connected by internal voltage division resistors (except for HD404324U, HD404326U, HD404328U and HD4074329U) Voltage conditions are: $V_{CC} \geq V_1 \geq V_2 \geq V_3 \geq GND$
	COM1–COM4	60–63	54–57	52–55	O	Common signal pins for LCD
	SEG1–SEG24	36–59	30–53	28–51	O	Segment signal pins for LCD

Item	Symbol	Pin Number DP-64S DC-64S	FP-64B	FP-64A	I/O	Function
A/D converter	AV_{CC}	4	62	60		Power pin for A/D converter; connect it to the same potential as V_{CC}, as physically close as possible to the power source
	AV_{SS}	9	3	1		Ground for AV_{CC}; connect it to the same potential as GND, as physically close as possible to the power source
	AN_0–AN_3	5–8	63, 64, 1, 2	61–64	I	Analog input pins for 4-channel A/D converter
Zero-crossing detection	ZCD	25	19	17	I	Zero-crossing detection input pin
Counter	$\overline{EVENT}$	25	19	17	I	Event count input pin

Block Diagram



Memory Map

ROM Memory Map

The ROM memory map is shown in figure 1 and described below.

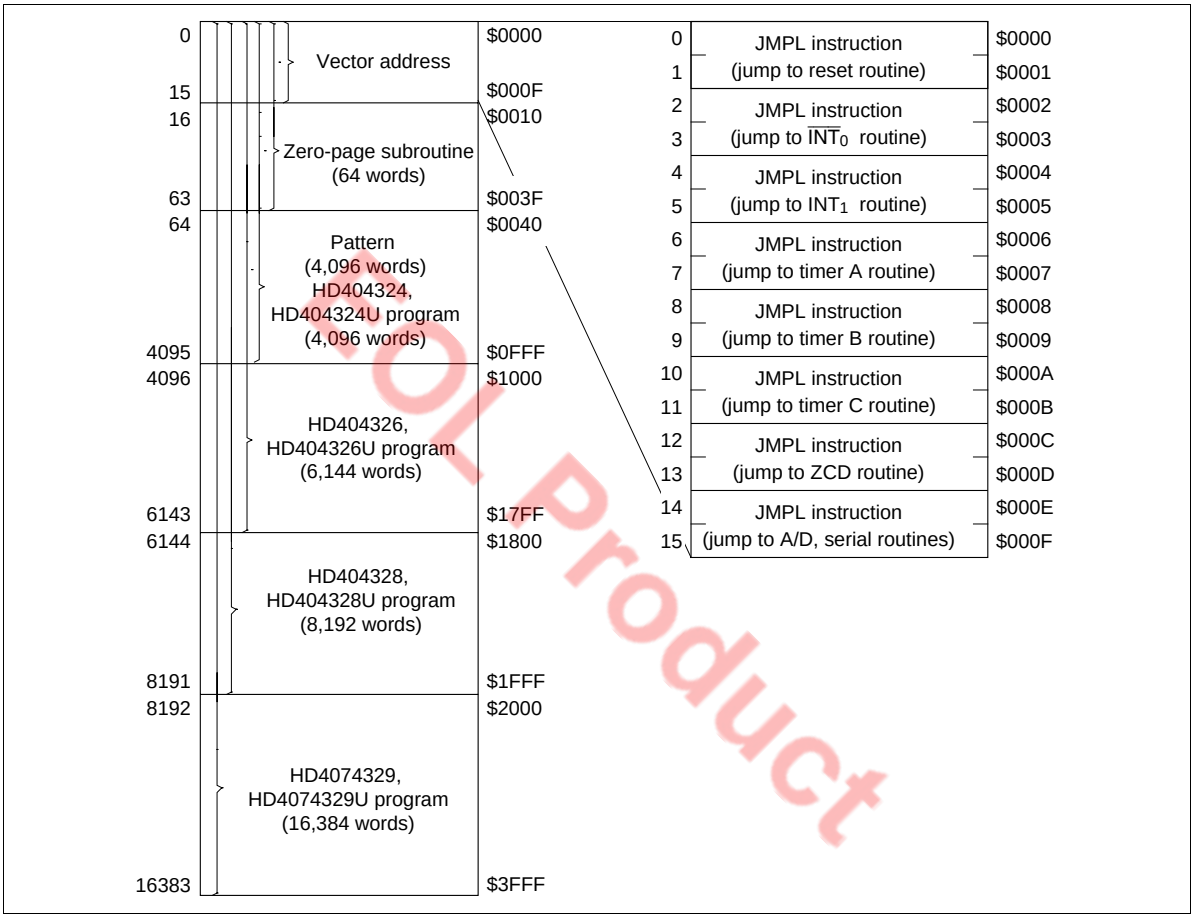


Figure 1 ROM Memory Map

Vector Address Area ($0000–$000F): Reserved for JMPL instructions that branch to the start addresses of the reset and interrupt routines. After MCU reset or an interrupt, program execution continues from the vector address.

Zero-Page Subroutine Area ($0000–$003F): Reserved for subroutines. The program branches to a subroutine in this area in response to the CAL instruction.

Pattern Area ($0000–$0FFF): Contains ROM data that can be referenced with the P instruction.

Program Area (HD404324, HD404324U: $0000-$0FFF; HD404326, HD404326U: $0000-$17FF; HD404328, HD404328U: $0000–$1FFF; HD4074329, HD4074329U: $0000–$3FFF): Used for program coding.

RAM Memory Map

The MPU contains a 280-digit × 4-bit (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U) or 536-digit × 4-bit (HD4074329, HD4074329U) RAM area consisting of a data area and a stack area. In addition, interrupt control bits and special registers are mapped onto the same RAM memory space outside this area. The RAM memory map is shown in figure 2 and described below.

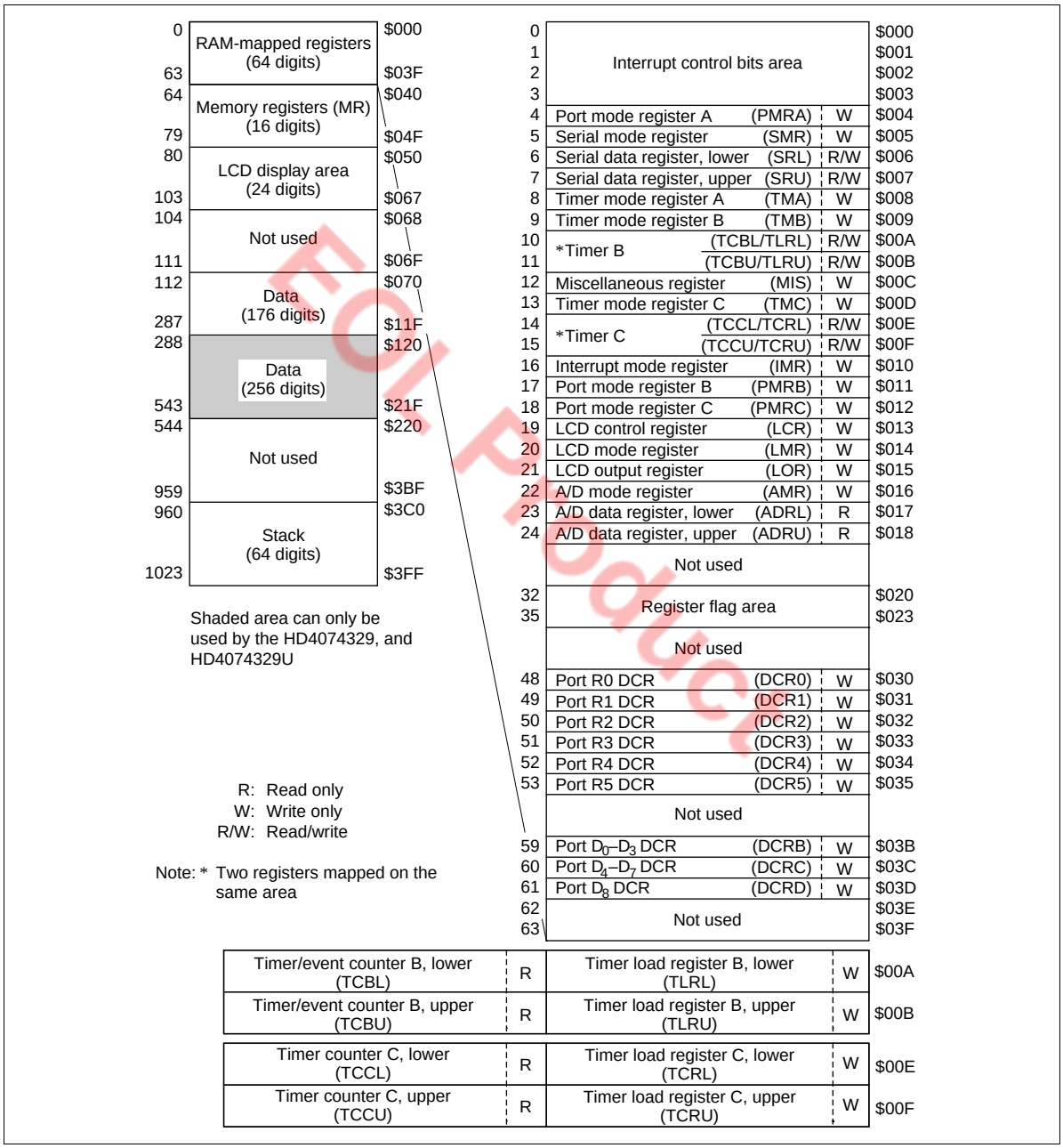


Figure 2 RAM Memory Map

Interrupt Control Bits Area and Register Flag Area ($000–$003, $020–$023): Used for interrupt control bits and the bit register (figure 3). This area can be accessed only by RAM bit manipulation instructions. In addition, note that the interrupt request flag cannot be set by software, the RSP bit is used only to reset the stack ppointer, and the WDON flag can be set only by the SEM and SEMD instructions.

Special Function Registers Area ($004–$01F, $024–$03F): Used as mode registers for external interrupts, serial interface, and timer/counters, and as data registers and as data control registers for I/O ports. As shown in figure 2, these registers can be classified into three types: write-only, read-only, and read/write. The SEM, SEMD, REM, and REMD instructions can be used for the LCD control register (LCR), but RAM bit manipulation instructions cannot be used for other registers.

LCD Data Area ($050–$067): Used for storing LCD data which is automatically output to LCD segments as display data. Data 1 lights the corresponding LCD segment; data 0 extinguishes it.

Data Area (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: $040–$04F and $070–$11F, HD4074329, HD4074329U: $040–$04F and $070–$21F): The memory registers (MR), which consist of 16 digits ($040–$04F), can be accessed by the LAMR and XMRA instructions. Its structure is shown in figure 4.

Stack Area ($3C0–$3FF): Used for saving the contents of the program counter (PC), status flag (ST), and carry flag (CA) at subroutine calls (CAL, CALL) and interrupts. This area can be used as a 16-level nesting subroutine stack in which one level requires four digits. The data to be saved and the save conditions are shown in figure 4.

The program counter is restored by either the RTN or RTNI instruction, but the status and carry flags can only be restored by the RTNI instruction. Any unused space in this area is used for data storage.

	Bit 3	Bit 2	Bit 1	Bit 0	
0	IM0 (IM of $\overline{INT_0}$)	IF0 (IF of $\overline{INT_0}$)	RSP (Reset SP bit)	IE (Interrupt enable flag)	$000
1	IMTA (IM of timer A)	IFTA (IF of timer A)	IM1 (IM of INT_1)	IF1 (IF of INT_1)	$001
2	IMTC (IM of timer C)	IFTC (IF of timer C)	IMTB (IM of timer B)	IFTB (IF of timer B)	$002
3	IMAD (IM of A/D)	IFAD (IF of A/D)	IMZC (IM of ZCD)	IFZC (IF of ZCD)	$003
32	DTON (Direct transfer on flag)	ADSF (A/D start flag)	WDON (Watchdog on flag)	LSON (Low speed on flag)	$020
33	Not used				$021
34					$022
35	IMS (IM of serial interface)	IFS (IF of serial interface)			$023

IF: Interrupt request flag
IM: Interrupt mask
IE: Interrupt enable flag
SP: Stack pointer

Note: Bits in the interrupt control bits area and register flag area are set by the SEM or SEMD instruction, reset by the REM or REMD instruction, and tested by the TM or TMD instruction. Other instructions have no effect.
However, note the following usage limitations of RAM bit manipulation instructions.

	SEM/SEMD	REM/REMD	TM/TMD
IF	Not executed	Allowed	Allowed
RSP	Not executed	Allowed	Inhibited
WDON	Allowed	Not executed	Inhibited
DTON	Not executed in active mode	Allowed	Allowed
	Used in subactive mode		

Note: WDON is reset by MCU reset.
DTON is always reset in active mode.
If the TM or TMD instruction is executed for the inhibited bits or non-existing bits, the value in ST becomes invalid.

Figure 3 Configuration of Interrupt Control Bits and Register Flag Areas

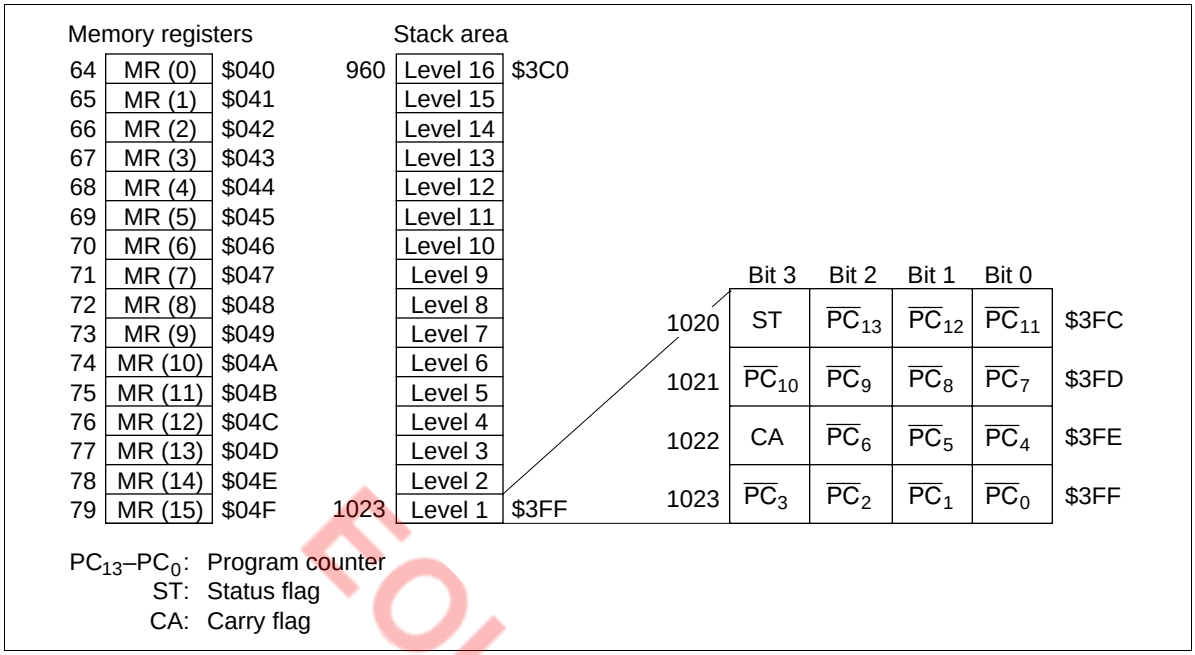


Figure 4 Configuration of Memory Registers and Stack Area, and Stack Position

Functional Description

Registers and Flags

The MCU has nine registers and two flags for CPU operations. They are shown in figure 5 and described below.

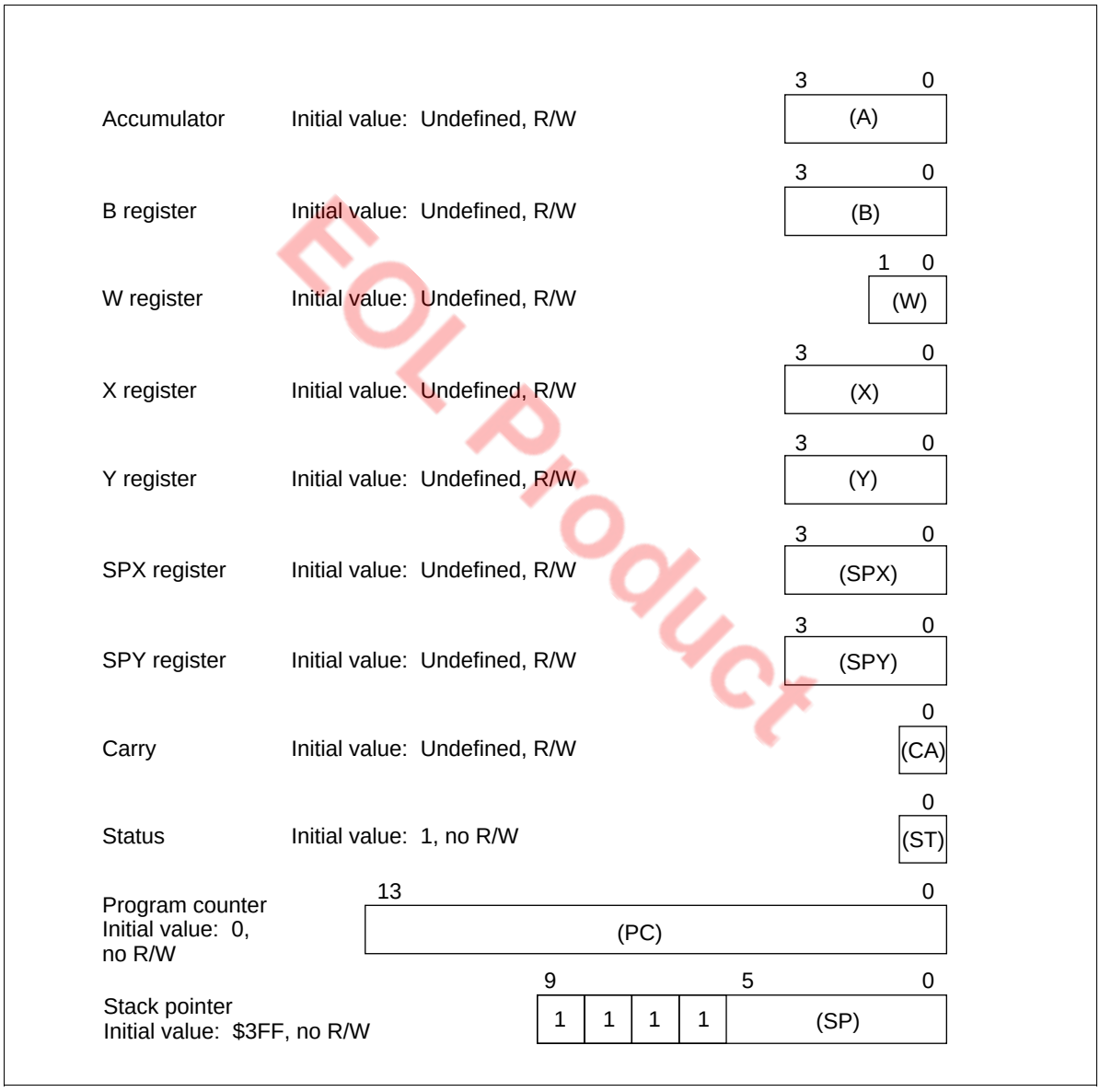


Figure 5 Registers and Flags

Accumulator (A), B Register (B): Four-bit registers used to hold results from the arithmetic logic unit (ALU) and transfer data between memory, I/O, and other registers.

W Register (W), X Register (X), Y Register (Y): Two-bit (W) and four-bit (X and Y) registers used for indirect RAM addressing. The Y register is also used for D-port addressing.

SPX Register (SPX), SPY Register (SPY): Four-bit registers used to supplement the X and Y registers.

Carry Flag (CA): One-bit flag that stores any ALU overflow generated by an arithmetic operation. CA is affected by the SEC, REC, ROTL, and ROTR instructions. A carry is pushed onto the stack during an interrupt and popped from the stack by the RTNI instruction—but not by the RTN instruction.

Status Flag (ST): One-bit flag that latches any overflow generated by an arithmetic or compare instruction, not-zero decision from the ALU, or result of a bit test. ST is used as a branch condition of the BR, BRL, CAL, and CALL instructions. The contents of ST remain unchanged until the next arithmetic, compare, or bit test instruction is executed, but become 1 after the BR, BRL, CAL, or CALL instruction is read, regardless of whether the instruction is executed or skipped. The contents of ST are pushed onto the stack during an interrupt and popped from the stack by the RTNI instruction—but not by the RTN instruction.

Program Counter (PC): A 14-bit counter that points to the ROM address of the instruction being executed.

Stack Pointer (SP): Ten-bit pointer that contains the address of the stack area to be used next. The SP is initialized to $3FF by MCU reset, is decremented by 4 when data is pushed onto the stack, and is incremented by 4 when data is popped from the stack. Since the top four bits of the SP are fixed at 1111, a stack of up to 16 levels can be used.

The SP can be initialized to $3FF in another way: by resetting the RSP bit with the REM or REMD instruction.

Reset

The MCU is reset by inputting a high-level voltage to the RESET pin. At power-on or when stop mode is cancelled, RESET must be high for at least one t_{RC} to enable the oscillator to stabilize. During operation, RESET must be high for at least two instruction cycles.

Initial values after MCU reset are shown in table 1.

Table 1 Initial Values After MCU Reset

Item		Abbr.	Initial Value	Contents
Program counter		(PC)	$0000	Indicates program execution point from start address of ROM area
Status flag		(ST)	1	Enables conditional branching
Stack pointer		(SP)	$3FF	Stack level 0
Interrupt flags/mask	Interrupt enable flag	(IE)	0	Inhibits all interrupts
	Interrupt request flag	(IF)	0	Indicates there is no interrupt request
	Interrupt mask	(IM)	1	Prevents (masks) interrupt requests
I/O	Port data register	(PDR)	All bits 1	Enables output at level 1
	Data control register	(DCR)	All bits 0	Turns output buffer off (to high impedance)
	Port mode register A	(PMRA)	0000	Refer to description of port mode register A
	Port mode register B	(PMRB)	- - 00	Refer to description of port mode register B
	Port mode register C	(PMRC)	0000	Refer to description of port mode register C
	Interrupt mode register	(IMR)	0000	Refer to description of interrupt mode register
Timer/ counters, serial interface	Timer mode register A	(TMA)	0000	Refer to description of timer mode register A
	Timer mode register B	(TMB)	0000	Refer to description of timer mode register B
	Timer mode register C	(TMC)	0000	Refer to description of timer mode register C
	Serial mode register	(SMR)	0000	Refer to description of serial mode register
	Prescaler S		$000	—
	Prescaler W		$00	—
	Timer counter A	(TCA)	$00	—
	Timer counter B	(TCB)	$00	—

Item		Abbr.	Initial Value	Contents
Timer/ counters, serial interface	Timer counter C	(TCC)	$00	—
	Timer load register B	(TLR)	$00	—
	Timer load register C	(TCR)	$00	—
	Octal counter		000	—
A/D	A/D mode register	(AMR)	00-0	Refer to description of A/D mode register
LCD	LCD control register	(LCR)	000	Refer to description of LCD control register
	LCD mode register	(LMR)	0000	Refer to description of LCD duty cycle/clock control register
	LCD output register	(LOR)	0000	Refer to description of LCD output register
Bit register	Low speed on flag	(LSON)	0	Refer to description of low-power dissipation modes
	Watchdog timer on flag	(WDON)	0	Refer to description of timer C
	A/D start flag	(ADSF)	0	Refer to description of A/D converter
	Direct transfer on flag	(DTON)	0	Refer to description of low-power dissipation modes
Miscellaneous register		(MIS)	0000	Refer to description of miscellaneous register

Note: The statuses of other registers and flags after MCU reset are as follows:

Item	Abbr.	Status After Cancellation of Stop Mode by MCU Reset	Status After Cancellation of all Other Types of Modes by MCU Reset
Carry flag	(CA)	Pre-MCU-reset values are not guaranteed: values must be initialized by program	Pre-MCU-reset values are not guaranteed: values must be initialized by program
Accumulator	(A)		
B register	(B)		
W register	(W)		
X/SPX register	(X/SPX)		
Y/SPY register	(Y/SPY)		
Serial data register	(SR)		
A/D data register	(ADRL, ADRU)		
RAM		Pre-MCU-reset (pre-STOP-instruction) values are retained	

Interrupts

The MCU has eight interrupt sources: two external signals ($\overline{INT_0}$ and INT_1), three timer/counters (timer A, timer B, and timer C), serial interface, zero-crossing detection, and A/D converter.

An interrupt request flag (IF), interrupt mask (IM), and vector address are provided for each interrupt source, and an interrupt enable flag (IE) controls the entire interrupt process.

Vector addresses are shared by serial interface and A/D converter interrupt causes, so software must first check which type of request has occurred.

Interrupt Control Bits and Interrupt Servicing: Locations $000–$003 and $020–$023 in RAM are reserved for the interrupt control bits which can be accessed by RAM bit manipulation instructions.

The interrupt request flag (IF) cannot be set by software. MCU reset initializes the interrupt enable flag (IE) and the IF to 0 and the interrupt mask (IM) to 1.

A block diagram of the interrupt control circuit is shown in figure 6, interrupt priorities and vector addresses are listed in table 2, and interrupt processing conditions for the eight interrupt sources are listed in table 3.

An interrupt request occurs when the IF is set to 1 and the IM is set to 0. If the IE is 1 at that point, the interrupt is processed. Priority control logic generates the vector address assigned to that interrupt source.

The interrupt processing sequence is shown in figure 7 and an interrupt processing flowchart is shown in figure 8. After an interrupt is acknowledged, the previous instruction is completed in the first cycle. The IE is reset in the second cycle, the carry flag, status flag, and program counter values are pushed onto the stack during the second and third cycles, and the program jumps to the vector address to execute the instruction in the third cycle.

Program the JMPL instruction at each vector address, to branch the program to the start address of the interrupt program, and reset the IF by a software instruction within the interrupt program.

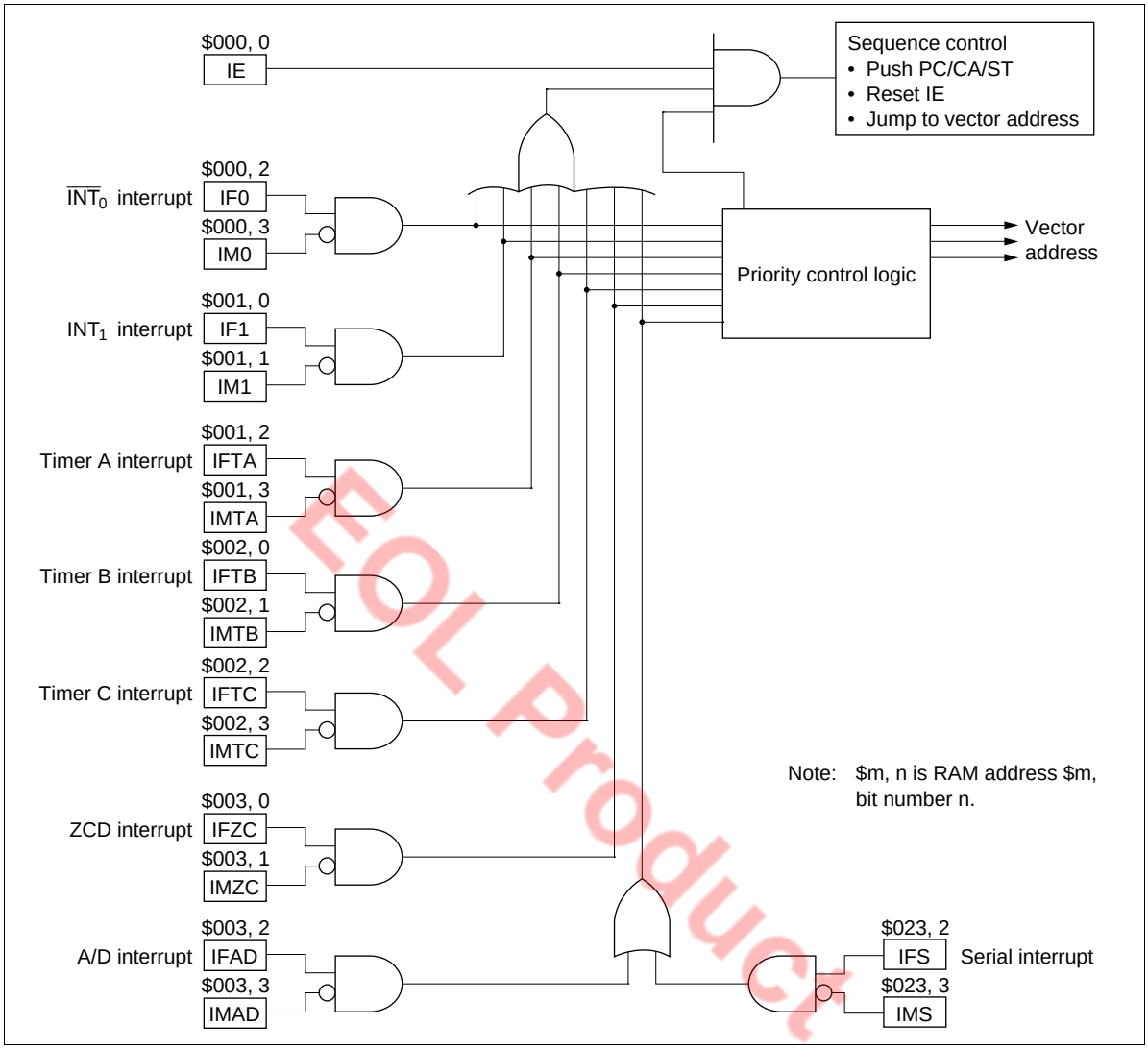


Figure 6 Block Diagram of Interrupt Control Circuit

Table 2 Vector Addresses and Interrupt Priorities

Reset/Interrupt	Priority	Vector Address
RESET	—	$0000
$\overline{INT_0}$	1	$0002
INT_1	2	$0004
Timer A	3	$0006
Timer B	4	$0008
Timer C	5	$000A
ZCD	6	$000C
A/D, Serial	7	$000E

Table 3 Interrupt Processing and Activation Conditions

	Interrupt Cause						
Interrupt Control Bit	$\overline{INT_0}$	INT_1	Timer A	Timer B	Timer C	ZCD	A/D, Serial
IE	1	1	1	1	1	1	1
IF0 · $\overline{IM0}$	1	0	0	0	0	0	0
IF1 · $\overline{IM1}$	*	1	0	0	0	0	0
IFTA · $\overline{IMTA}$	*	*	1	0	0	0	0
IFTB · $\overline{IMTB}$	*	*	*	1	0	0	0
IFTC · $\overline{IMTC}$	*	*	*	*	1	0	0
IFZC · $\overline{IMZC}$	*	*	*	*	*	1	0
IFAD · $\overline{IMAD}$ + IFS · $\overline{IMS}$	*	*	*	*	*	*	1

Note: Bits marked * can be either 0 or 1. Their values have no effect on operation.

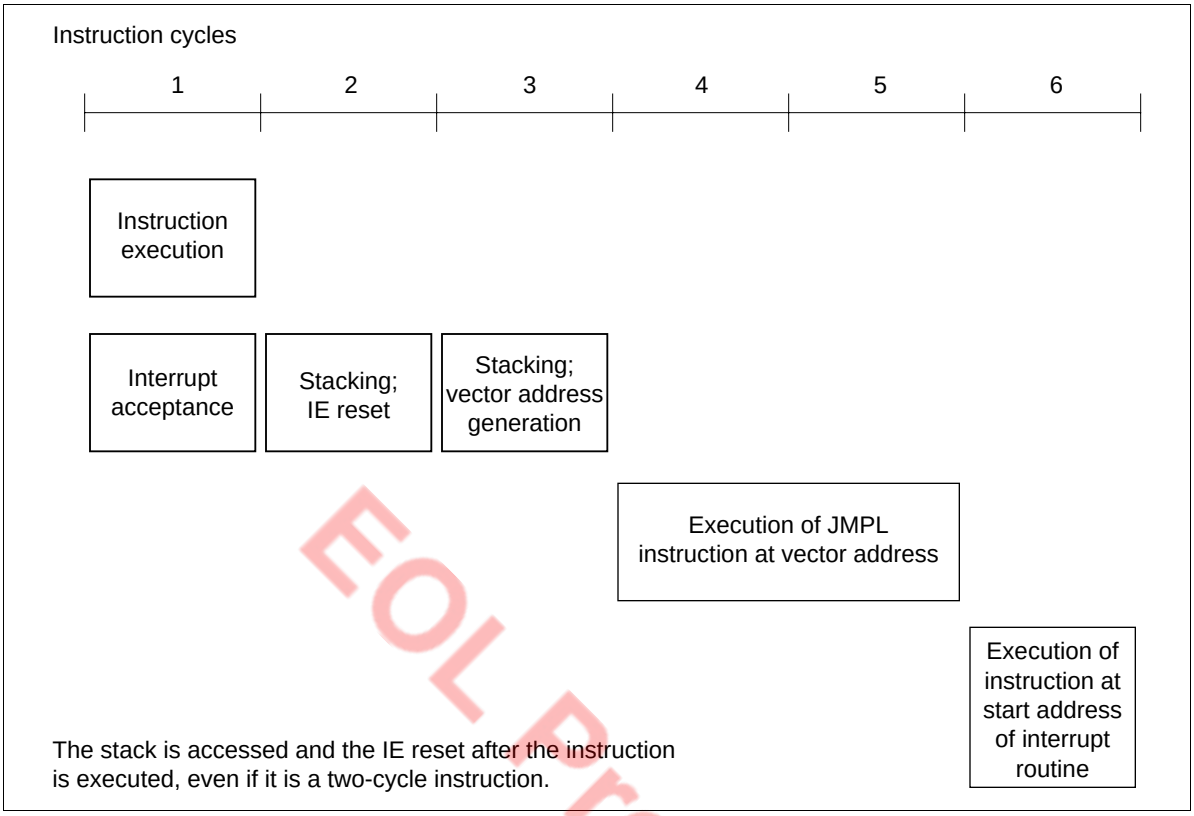


Figure 7 Interrupt Processing Sequence

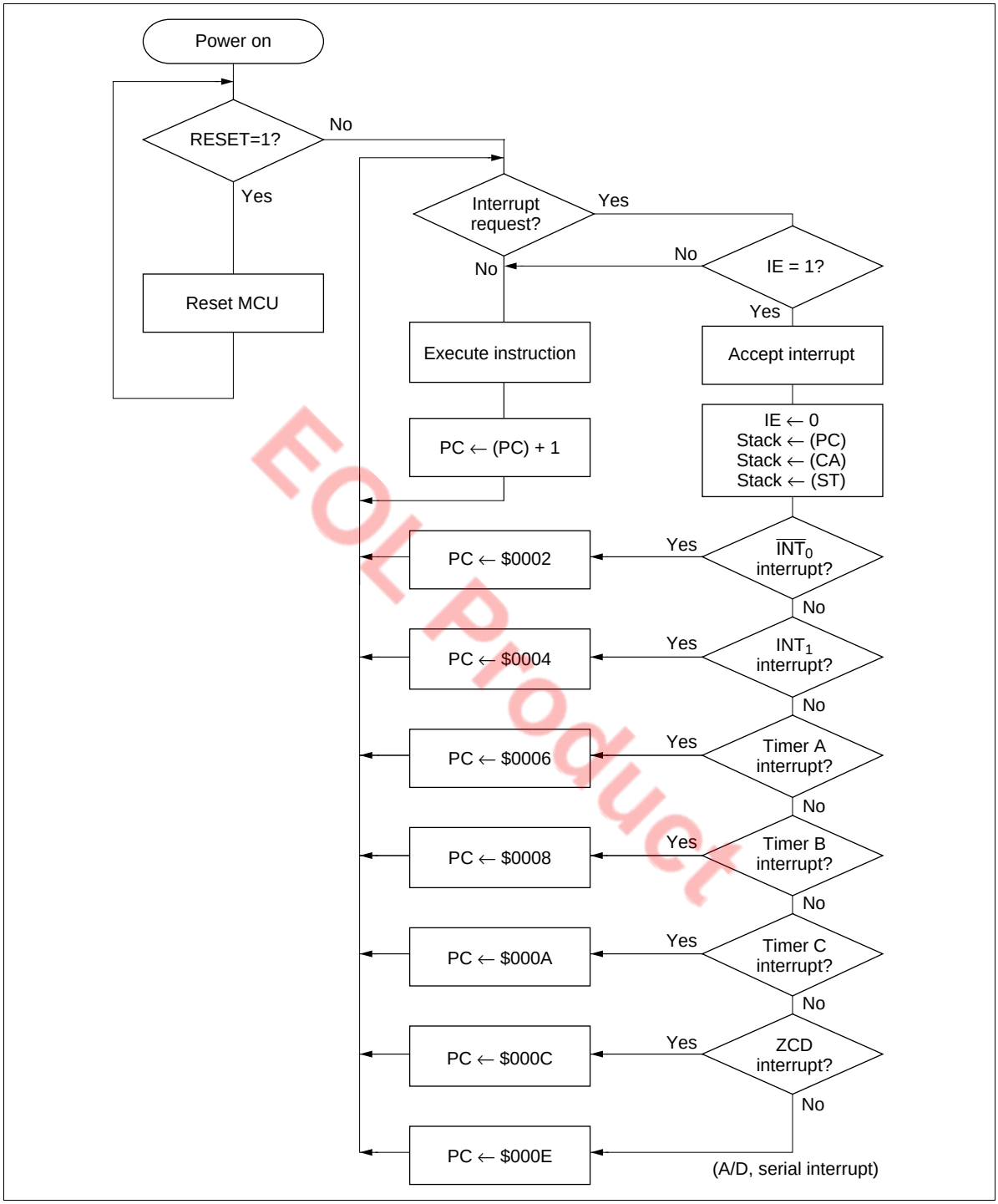


Figure 8 Interrupt Processing Flowchart

Interrupt Enable Flag (IE: $000, Bit 0): Controls the entire interrupt process. It is reset by the interrupt processing and set by the RTNI instruction, as shown in table 4.

Table 4 Interrupt Enable Flag

IE	Interrupt Enabled/Disabled
0	Disabled
1	Enabled

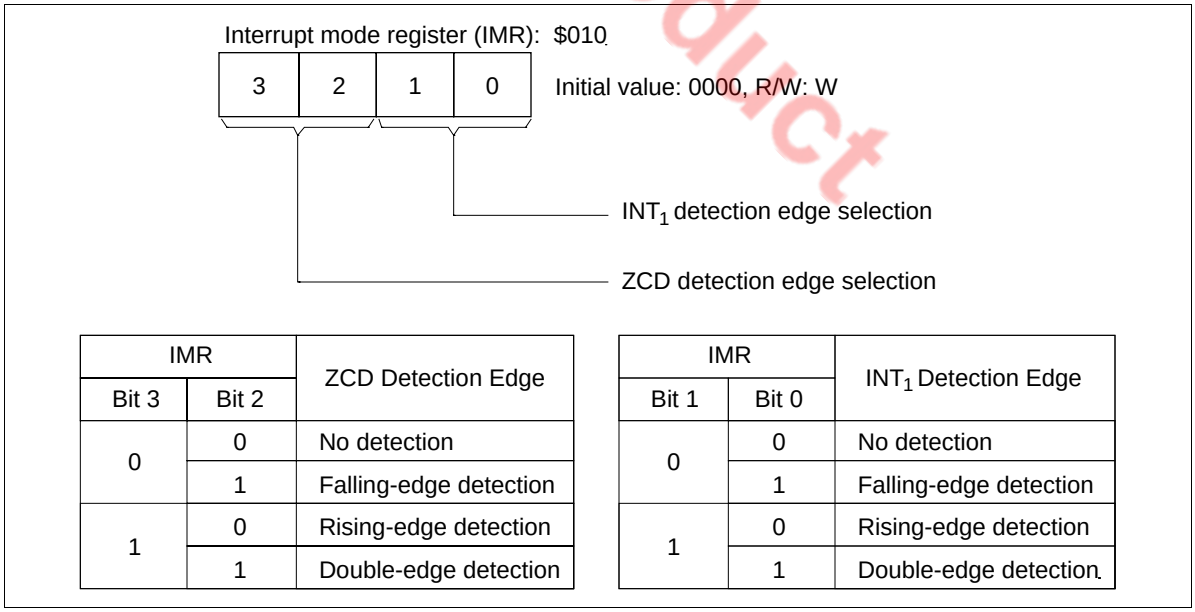
External Interrupts ($\overline{INT}_0$, INT_1): Specified by port mode register A (PMRA: $004).

External Interrupt Request Flags (IF0: $000, Bit 2; IF1: $001, Bit 0): Set at the rising or falling edges of the $\overline{INT}_0$ and INT_1 inputs, as shown in table 5.

Table 5 External Interrupt Request Flags

IF0, IF1	Interrupt Request
0	No
1	Yes

IF0 is set at the falling edge of signals input to $\overline{INT}_0$, and IF1 is set at the rising and falling edges of signals input to INT_1. The INT_1 interrupt edge is selected by the interrupt mode register (IMR: $010), as shown in figure 9.



IMR		ZCD Detection Edge
Bit 3	Bit 2	
0	0	No detection
	1	Falling-edge detection
1	0	Rising-edge detection
	1	Double-edge detection

IMR		INT_1 Detection Edge
Bit 1	Bit 0	
0	0	No detection
	1	Falling-edge detection
1	0	Rising-edge detection
	1	Double-edge detection

Figure 9 Interrupt Mode Register

External Interrupt Masks (IM0: $000, Bit 3; IM1: $001, Bit 1): Prevent (mask) interrupt requests caused by the corresponding external interrupt request flags, as shown in table 6.

Table 6 External Interrupt Masks

IM0, IM1	Interrupt Request
0	Enabled
1	Disabled (Masked)

Timer A Interrupt Request Flag (IFTA: $001, Bit 2): Set by overflow output from timer A, as shown in table 7.

Table 7 Timer A Interrupt Request Flag

IFTA	Interrupt Request
0	No
1	Yes

Timer A Interrupt Mask (IMTA: $001, Bit 3): Prevents (masks) an interrupt request caused by the timer A interrupt request flag, as shown in table 8.

Table 8 Timer A Interrupt Mask

IMTA	Interrupt Request
0	Enabled
1	Disabled (Masked)

Timer B Interrupt Request Flag (IFTB: $002, Bit 0): Set by overflow output from timer B, as shown in table 9.

Table 9 Timer B Interrupt Request Flag

IFTB	Interrupt Request
0	No
1	Yes

Timer B Interrupt Mask (IMTB: $002, Bit 1): Prevents (masks) an interrupt request caused by the timer B interrupt request flag, as shown in table 10.

Table 10 Timer B Interrupt Mask

IMTB	Interrupt Request
0	Enabled
1	Disabled (Masked)

Timer C Interrupt Request Flag (IFTC: $002, Bit 2): Set by overflow output from timer C, as shown in table 11.

Table 11 Timer C Interrupt Request Flag

IFTC	Interrupt Request
0	No
1	Yes

Timer C Interrupt Mask (IMTC: $002, Bit 3): Prevents (masks) an interrupt request caused by the timer C interrupt request flag, as shown in table 12.

Table 12 Timer C Interrupt Mask

IMTC	Interrupt Request
0	Enabled
1	Disabled (Masked)

Zero-Crossing Interrupt Request Flag (IFZC: $003, Bit 0): Set by a zero crossing of an AC input signal, as shown in table 13. The interrupt edge is selected by the interrupt mode register (IMR: $010), as shown in figure 9.

Table 13 Zero-Crossing Interrupt Request Flag

IFZC	Interrupt Request
0	No
1	Yes

Zero-Crossing Interrupt Mask (IMZC: $003, Bit 1): Prevents (masks) an interrupt request caused by the zero-crossing interrupt request flag, as shown in table 14.

Table 14 Zero-Crossing Interrupt Mask

IMZC	Interrupt Request
0	Enabled
1	Disabled (Masked)

A/D Interrupt Request Flag (IFAD: $003, Bit 2): Set at the completion of A/D conversion, as shown in table 15.

Table 15 A/D Interrupt Request Flag

IFAD	Interrupt Request
0	No
1	Yes

A/D Interrupt Mask (IMAD: $003, Bit 3): Prevents (masks) an interrupt request caused by the A/D interrupt request flag, as shown in table 16.

Table 16 A/D Interrupt Mask

IMAD	Interrupt Request
0	Enabled
1	Disabled (Masked)

Serial Interrupt Request Flag (IFS: $023, Bit 2): Set when the octal counter counts the eighth transmit clock signal or when data transfer is discontinued by resetting the octal counter (table 17).

Table 17 Serial Interrupt Request Flag

IFS	Interrupt Request
0	No
1	Yes

Serial Interrupt Mask (IMS: $023, Bit 3): Prevents (masks) an interrupt request caused by the serial interrupt request flag, as shown in table 18.

Table 18 Serial Interrupt Mask

IMS	Interrupt Request
0	Enabled
1	Disabled (Masked)

Operating Modes

The MCU has five operating modes that are specified by how the clock is used. The functions available in each mode are listed in table 19, and operations are shown in table 20. Transitions between operating modes are shown in figure 10.

Table 19 Functions Available in Each Operating Mode

		Mode Name				
		Active	**Standby**	**Stop**	**Watch**	**Subactive**[*4]
Activation method		RESET cancellation, interrupt request	SBY instruction	TMA3 = 0 STOP instruction	TMA3 = 1 STOP instruction	$\overline{INT_0}$ or timer A interrupt request from watch mode
Status	System oscillator	OP	OP	Stopped	Stopped	Stopped
	Subsystem oscillator	OP	OP	*[1] OP	OP	OP
	Instruction execution ($ø_{CPU}$)	OP	Stopped	Stopped	Stopped	OP
	Interrupt function interrupt ($ø_{PER}$)	OP	OP	Stopped	Stopped	*[5]OP
	Clock function interrupt ($ø_{CLK}$)	OP	OP	Stopped	*[2] OP	*[2]OP
	RAM	OP	Retained	Retained	Retained	OP
	Registers/flags	OP	Retained	Reset*[6]	Retained	Retained/ operating
	I/O	OP	Retained	Reset*[3]	Retained	OP
Cancellation method		RESET input, STOP/SBY instruction	RESET input interrupt request	RESET input	RESET input, $\overline{INT_0}$ or timer A interrupt request	RESET input, STOP/SBY instruction

Notes: OP: indicates in operation

1. To reduce current dissipation, stop all oscillation in external circuits.
2. Refer to the Interrupt Frame section for details.
3. Output pins are at high impedance.
4. Subactive mode is an optional function; specify it on the function option list.
5. The A/D converter does not operate.
6. Port mode register B retains the contents it had in active mode.

		System Clock ($ø_{CPU}$)	
		Operating	**Stopped**
Non-Time-Base Peripheral Function Clock ($ø_{PER}$)	**Operating**	Active mode	Standby mode
		Subactive mode	
	Stopped	—	Watch mode (TMA3 = 1)
			Stop mode (TMA3 = 0)

Table 20 Operations in Low-Power Dissipation Modes

Function	Stop Mode	Watch Mode	Standby Mode	Subactive Mode*[3]
CPU	Reset	Retained	Retained	OP
RAM	Retained	Retained	Retained	OP
Timer A	Reset	OP	OP	OP
Timer B	Reset	Stopped	OP	OP
Timer C	Reset	Stopped	OP	OP
Serial interface	Reset	Stopped*[3]	OP	OP
LCD	Reset	OP	OP	OP
I/O	Reset*[1]	Retained	Retained	OP
A/D	Reset	Stopped	OP	Stopped
Zero-crossing detection	Stopped*[4]	Stopped*[4]	OP	OP

Notes: OP: indicates in operation

1. Output pins are at high impedance.
2. Subactive mode is an optional function specified on the function option list.
3. Transmission/reception is activated if a clock is input in external clock mode. (However interrupts stop.)
4. The bias circuits still operate when the D_8/ZCD/$\overline{EVENT}$ pin is set to ZCD.

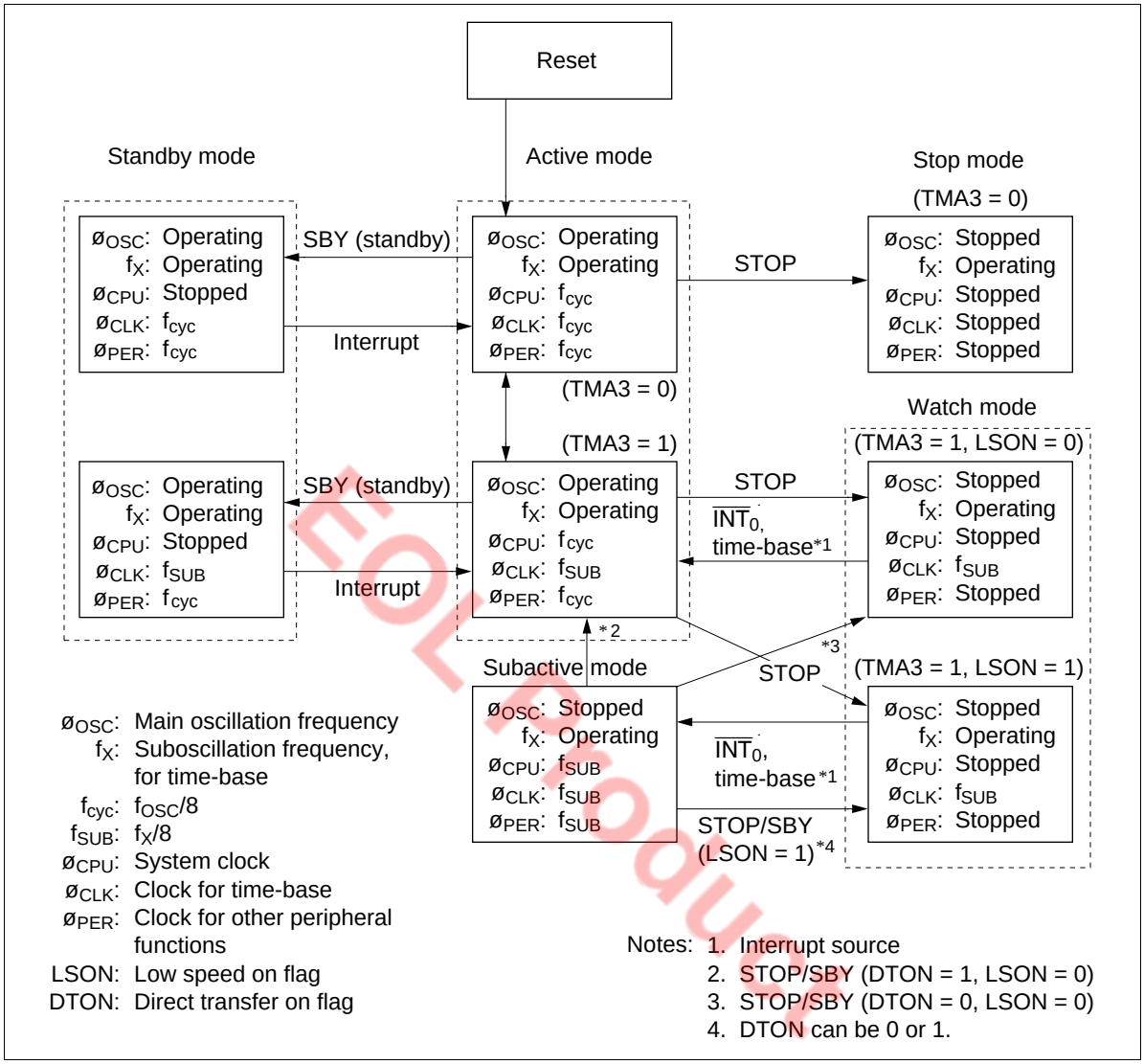


Figure 10 MCU Status Transitions

Active Mode: The MCU operates according to the clock generated by the system oscillators OSC_1 and OSC_2.

Standby Mode: The MCU enters standby mode when the SBY instruction is executed from active mode. In this mode, the oscillators, interrupts, timer/counters, and serial interface continue to operate, but all instruction execution-related clocks stop. The stopping of these clocks stops the CPU, retaining all RAM and register contents and maintaining the current I/O pin status.

The standby mode is terminated by a RESET input or an interrupt request. If it is terminated by RESET input, the MCU is reset as well. After an interrupt request, the MCU enters active mode and resumes, executing the next instruction after the SBY instruction. If the interrupt enable flag is 1, that interrupt is then processed; if it is 0, the interrupt request is left pending and normal instruction execution continues. A flowchart of operation in standby mode is shown in figure 11.

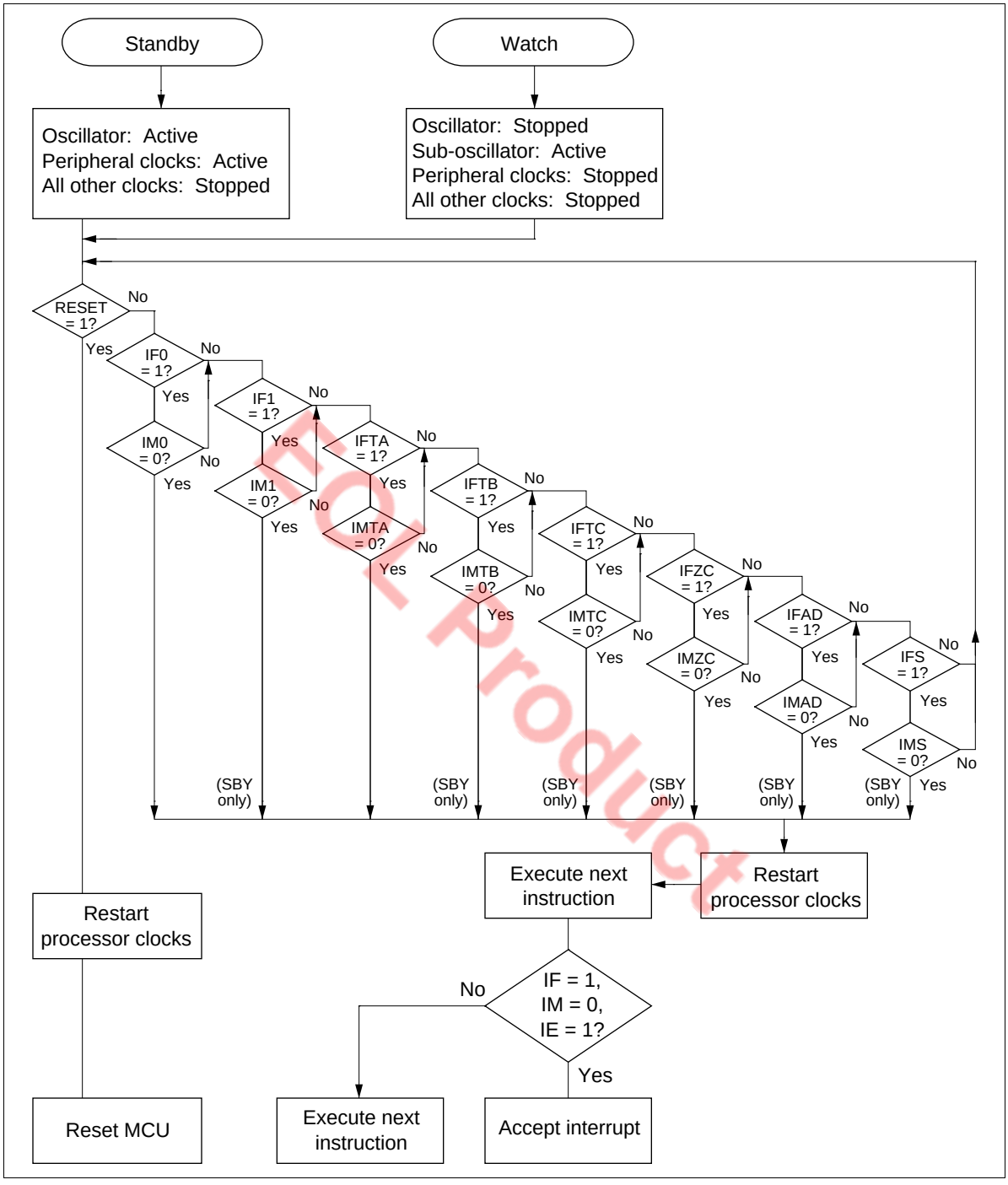


Figure 11 MCU Operation Flowchart

Stop Mode: The MCU enters stop mode if the STOP instruction is executed in active mode when TMA3 = 0. In this mode, the system oscillator stops, which stops all MCU functions as well.

The stop mode is terminated by a RESET input as shown in figure 12. RESET must be high for at least one t_{RC} to stabilize oscillation (refer to the AC Characteristics section). When the MCU restarts after stop mode is cancelled, all RAM contents are retained, but the accuracy of the contents of the accumulator, B register, W register, X/SPX register, Y/SPY register, carry flag, and serial data register cannot be guaranteed.

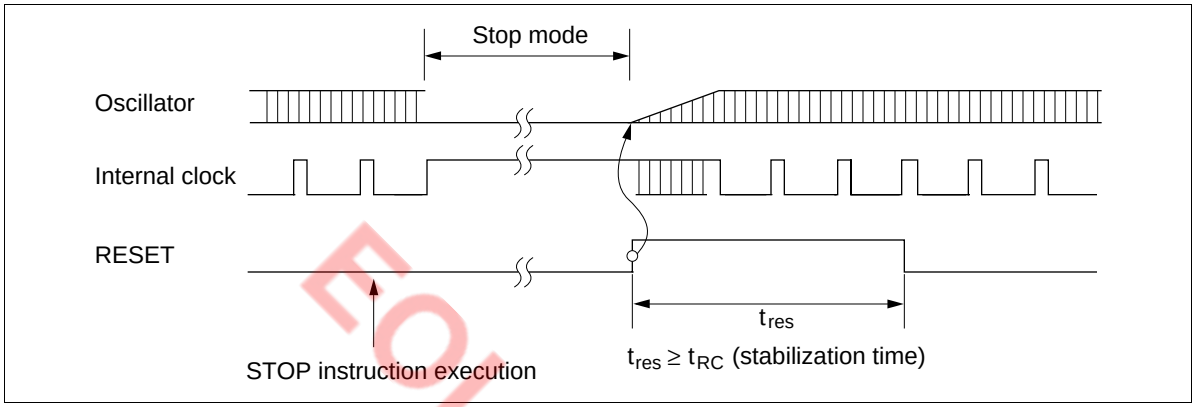


Figure 12 Timing of Stop Mode Cancellation

Watch Mode: The MCU enters watch mode if the STOP instruction is executed in active mode when TMA3 = 1, or if the STOP or SBY instruction is executed in subactive mode.

The watch mode is terminated by a RESET input or a timer-A/$\overline{INT_0}$ interrupt request. For details of RESET input, refer to the Stop Mode section. When terminated by a timer-A/$\overline{INT_0}$ interrupt request, the MCU enters active mode if LSON is 0, or subactive mode if LSON is 1. After an interrupt request is generated, the time required to enter active mode is t_{RC} for a timer A interrupt, and T_X (where $T + t_{RC} < T_X < 2T + t_{RC}$) for an $\overline{INT_0}$ interrupt, as shown in figures 13 and 14.

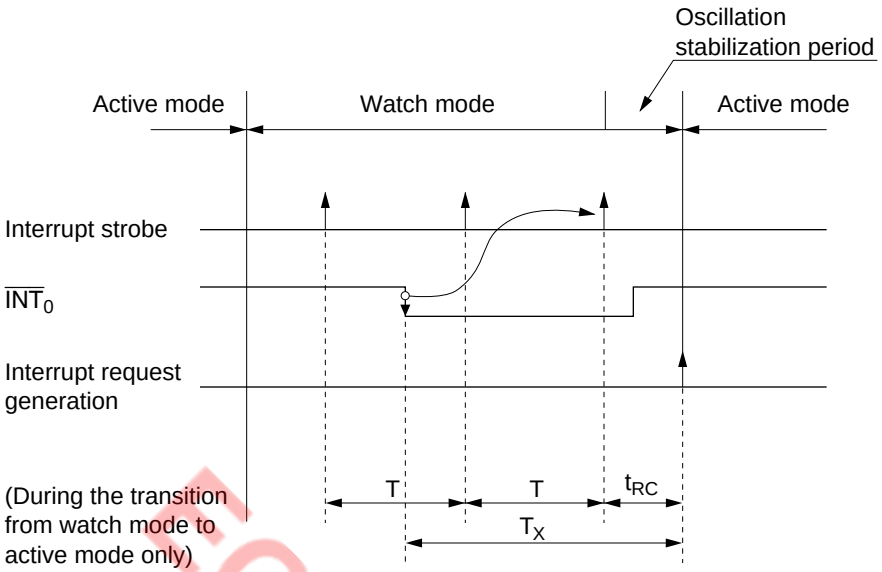


Figure 13 Interrupt Frame

Miscellaneous register (MIS): $00C

3	2	1	0

Initial value: 0000,
R/W: W

t_{RC} selection

$R1_2$/SO PMOS off

Setting for switching the system oscillator's frequency

MIS		T *1	t_{RC} *1
Bit 1	Bit 0		
0	0	0.24414 ms	0.12207 ms
			0.24414 *2 ms
0	1	15.625 ms	7.8125 ms
1	0	125 ms	62.5 ms
1	1	Not used	

T: Interrupt frame length
t_{RC}: Oscillation stabilization period

Notes: 1. The value of t_{RC} applies only when using a 32.768-kHz crystal oscillator.
2. Only direct transfer.

Figure 14 Miscellaneous Register

Operation during mode transition is the same as that at standby mode cancellation (figure 11).

Subactive Mode: The CPU operates with a clock generated by the X1 and X2 oscillation circuits. Functions that can operate in subactive mode are listed in table 20. When the STOP or SBY instruction is executed in subactive mode, the MCU enters either watch or active mode, depending on the statuses of LSON and DTON. The DTON flag can only be set in subactive mode; it is automatically reset after a transition to active mode.

The subactive mode is an optional function that the user must specify on the function option list.

Interrupt Frame: In watch and subactive modes, timer A and $\overline{INT}_0$ interrupts are generated in synchronism with the interrupt frame. Three interrupt frame lengths (T) can be selected by the settings of the miscellaneous register, as shown in figure 14.

The time from an interrupt strobe to interrupt request generation is the oscillation stabilization period (t_{RC}), as shown in figure 13.

The interrupt request is generated synchronously with the interrupt strobe timing except during transition to active mode. The falling edge of the $\overline{INT}_0$ signal is input asynchronously with the interrupt frame timing, but it is regarded as input synchronously with the second interrupt strobe clock after the falling edge. An overflow and interrupt request in timer A is generated synchronously with the interrupt strobe timing.

Operation during the transition from watch mode to active mode is the same as that at standby mode cancellation (figure 11).

Direct Transfer: By controlling the DTON flag, the MCU will be placed directly from subactive to active mode. The detailed procedure is as follows:

- Set the DTON flag in subactive mode while LSON = 0 and DTON = 1.
- Execute the STOP or SBY instruction.
- After the oscillation stabilization time (a fixed value), the MCU will move automatically from subactive to active mode (see figure 15).

Note that DTON ($020, bit 3) is valid only in subactive mode. When the MCU is in active mode, this flag is always at reset.

The transition time (t_D) from subactive to active mode is $t_{RC} < t_D < T + t_{RC}$.

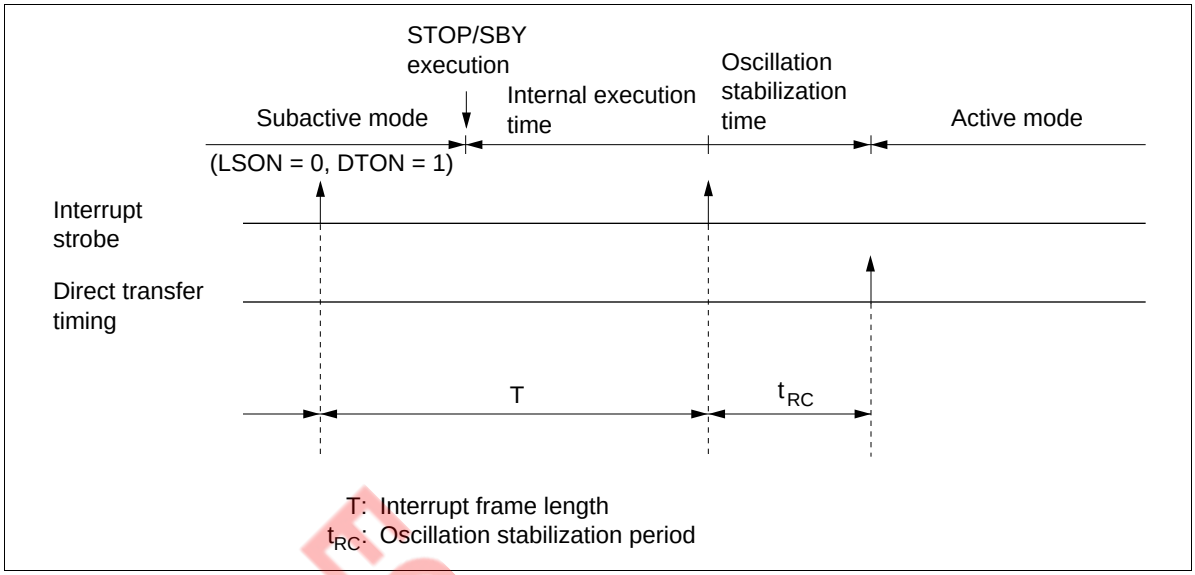


Figure 15 Direct Transfer Timing

MCU Operation Sequence: The MCU operates in the sequence shown in figures 16 to 18. It is reset by an asynchronous RESET input, regardless of its state.

The low-power mode operation sequence is shown in figure 18. With the IE flag cleared and an interrupt flag set together with its interrupt mask cleared, if a STOP/SBY instruction is executed, the instruction is cancelled (regarded as an NOP) and the following instruction is executed. Before executing a STOP/SBY instruction, make sure all interrupt flags are cleared or all interrupts are masked.

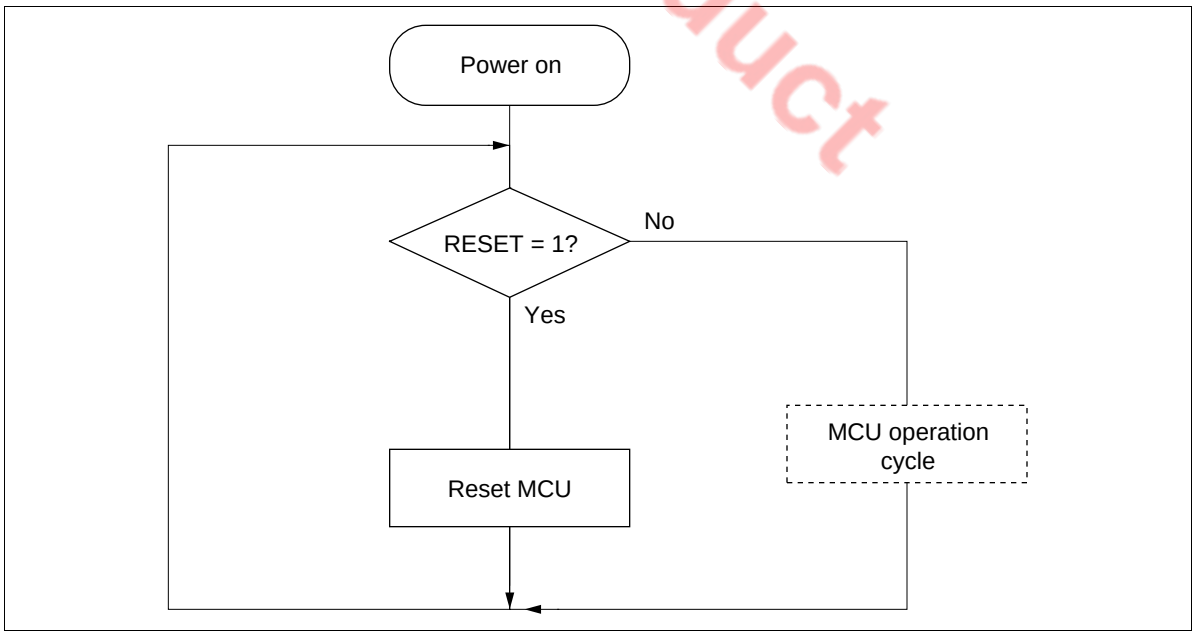


Figure 16 MCU Operating Sequence (Power On)

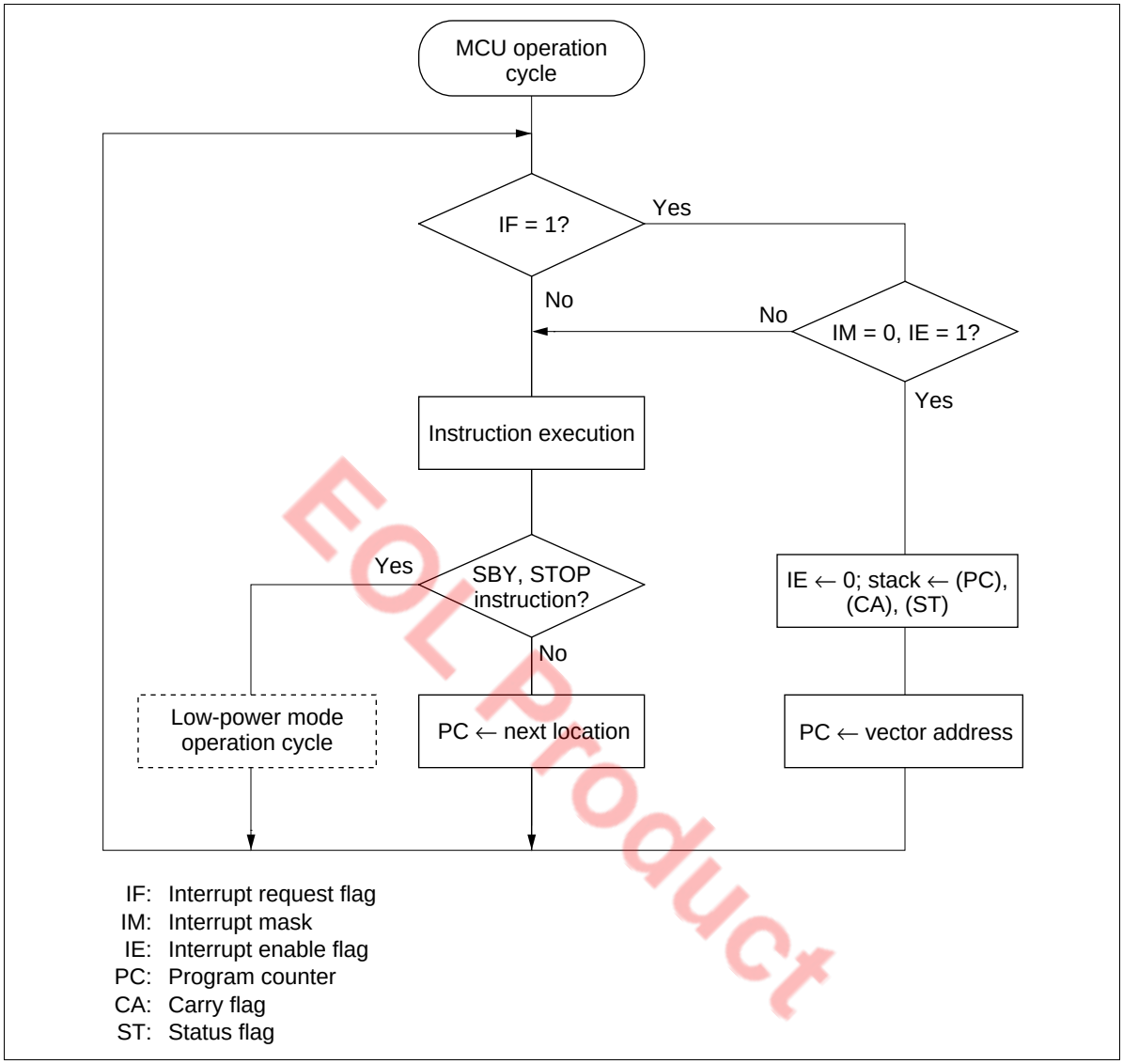


Figure 17 MCU Operating Sequence (MCU Operation Cycle)

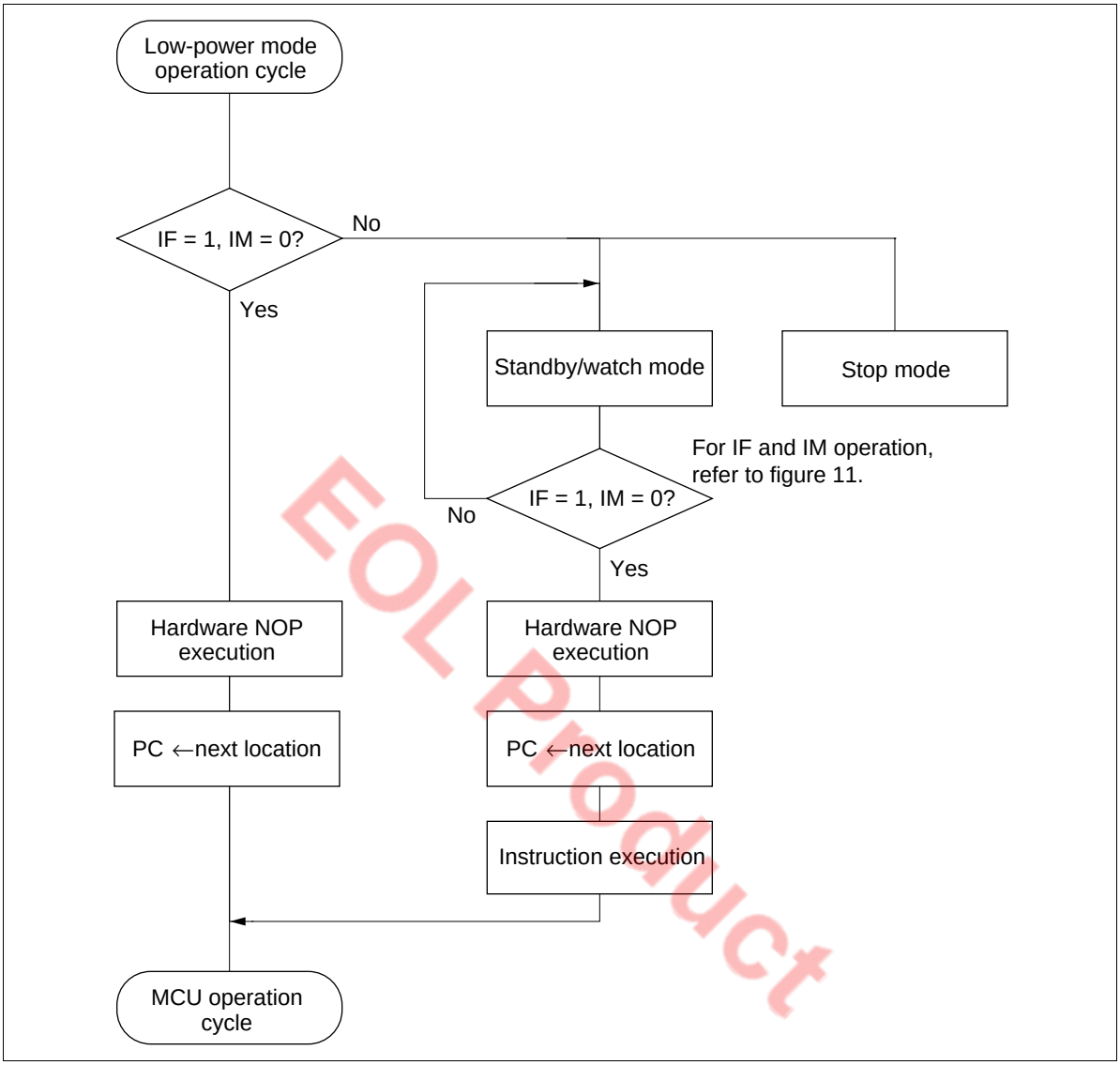


Figure 18 MCU Operating Sequence (Low-Power Mode Operation)

Limitation on Use

- In subactive mode, the timer A interrupt request or the external interrupt request ($\overline{INT_0}$) occurs in synchronism with the interrupt strobe. If the STOP or SBY instruction is executed at the same time with the interrupt strobe, these interrupt requests will be cancelled and its corresponding interrupt request flags (IFTA, IF0) will be not set.

  In subactive mode, do not use the STOP or SBY instruction at the time of the interrupt strobe.

- When the MCU is in watch mode or subactive mode, if the high level period before the falling edge of $\overline{INT_0}$ is shorter than the interrupt frame, $\overline{INT_0}$ is not detected. Also, if the low level period after the falling edge of $\overline{INT_0}$ is shorter than the interrupt frame, $\overline{INT_0}$ is not detected.

  Edge detection is shown in figure 19. The level of the $\overline{INT_0}$ signal is sampled by a sampling clock. When this sampled value changes to low from high, a falling edge is detected.

  In figure 20, the level of the $\overline{INT_0}$ signal is sampled by an interrupt frame. In (a) the sampled value is low at point A, and also low at point B. Therefore, a falling edge is not detected. In (b), the sampled value is high at point A, and also high at point B. A falling edge is not detected in this case either.

  When the MCU is in watch mode or subactive mode, keep the high level and low level period of $\overline{INT_0}$ longer than interrupt frame.

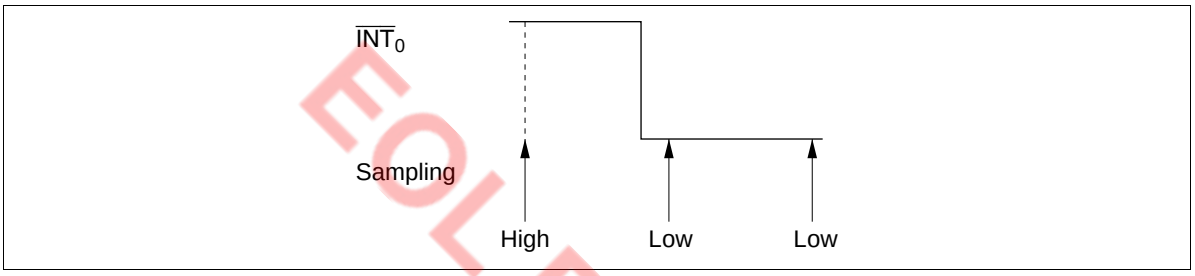


Figure 19 Edge Detection

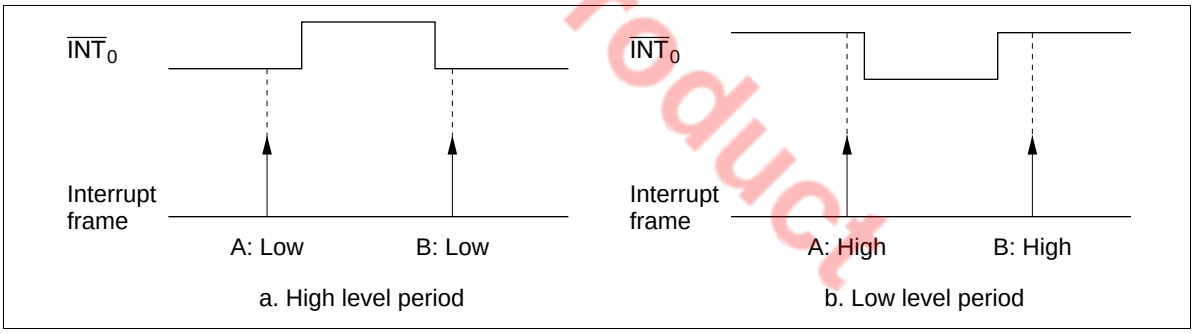
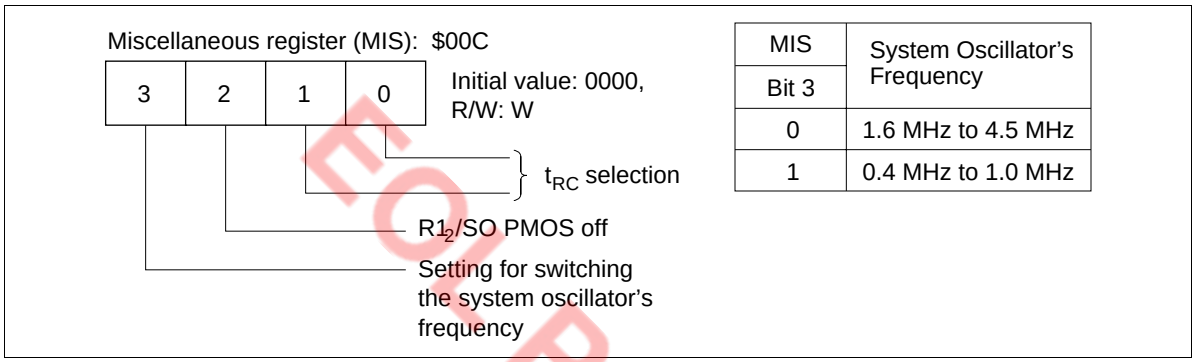


Figure 20 Sampling Example

Internal Oscillator Circuit

A block diagram of the internal oscillator circuit is shown in figure 22. As shown in table 21, crystal and ceramic oscillators can be connected to OSC_1 and OSC_2, and a 32.768-kHz oscillator can be connected to X1 and X2. The system oscillator can also be operated by an external clock. Bit 3 of the miscellaneous register (MIS: $00C) must be set according to the frequency of the oscillator connected to OSC_1 and OSC_2.

Note: If the MIS register setting does not match the oscillator frequency, subsystems using 32-kHz oscillation will malfunction. Set the system oscillator frequency to anything outside the range of 1.0 MHz to 1.6 MHz when using 32-kHz oscillation.



MIS Bit 3	System Oscillator's Frequency
0	1.6 MHz to 4.5 MHz
1	0.4 MHz to 1.0 MHz

Figure 21 Miscellaneous Register

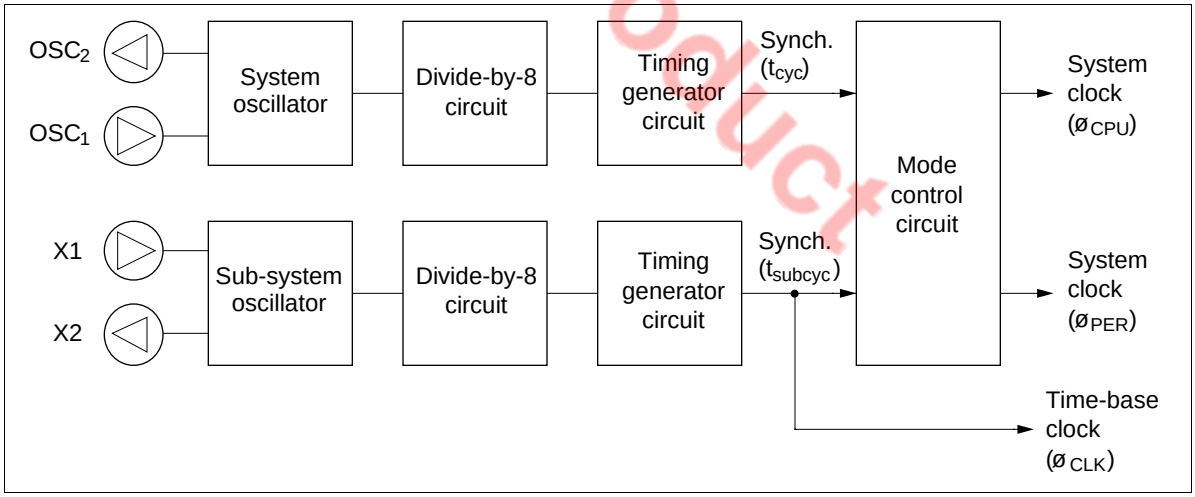
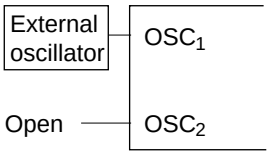
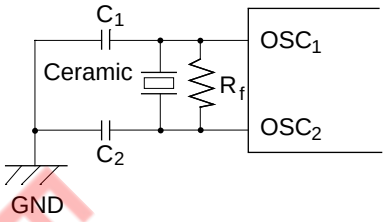
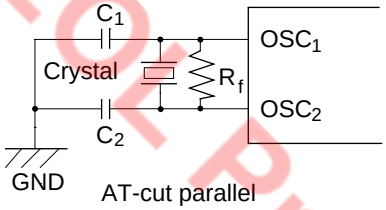
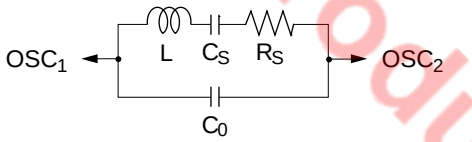
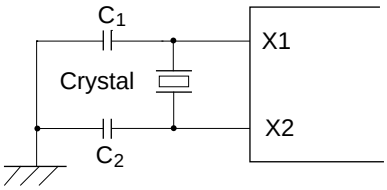
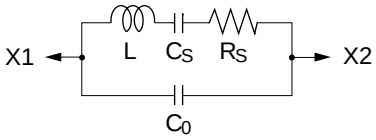


Figure 22 Internal Oscillator Circuit

Table 21 Oscillator Circuit Examples

	Circuit Configuration	Circuit Constants
External Clock Operation (OSC_1, OSC_2)		
Ceramic Oscillator (OSC_1, OSC_2)		Ceramic: CSA4.00MG (Murata) R_f = 1 MΩ ±20% $C_1 = C_2$ = 30 pF ±20%
Crystal Oscillator (OSC_1, OSC_2)	 AT-cut parallel resonance crystal 	R_f: 1 MΩ ±20% $C_1 = C_2$ = 10 pF ±10% Crystal: Equivalent to circuit shown at bottom left C_0 = 7 pF, max. R_S = 100 Ω , max. f = 1.0 MHz to 4.5 MHz
Crystal Oscillator (X1, X2)	 	$C_1 = C_2$ = 15 pF ±5% Crystal: 32.768 kHz, MX38T (Nippon Denpa) C_0 = 1.5 pF, typ. R_S = 14 kΩ , typ.

Notes:
1. Circuit constants differ with different types of crystal and ceramic oscillators, and with the stray capacitance of the board, so consult the manufacturer of the oscillator to determine the circuit parameters.
2. The wiring between the OSC_1 and OSC_2 pins (X1 and X2 pins) and the other elements should be as short as possible, and must not cross other wiring. Refer to figure 23.
3. If not using a 32.768-kHz crystal oscillator, fix the X1 pin to V_{CC} and leave the X2 pin open.

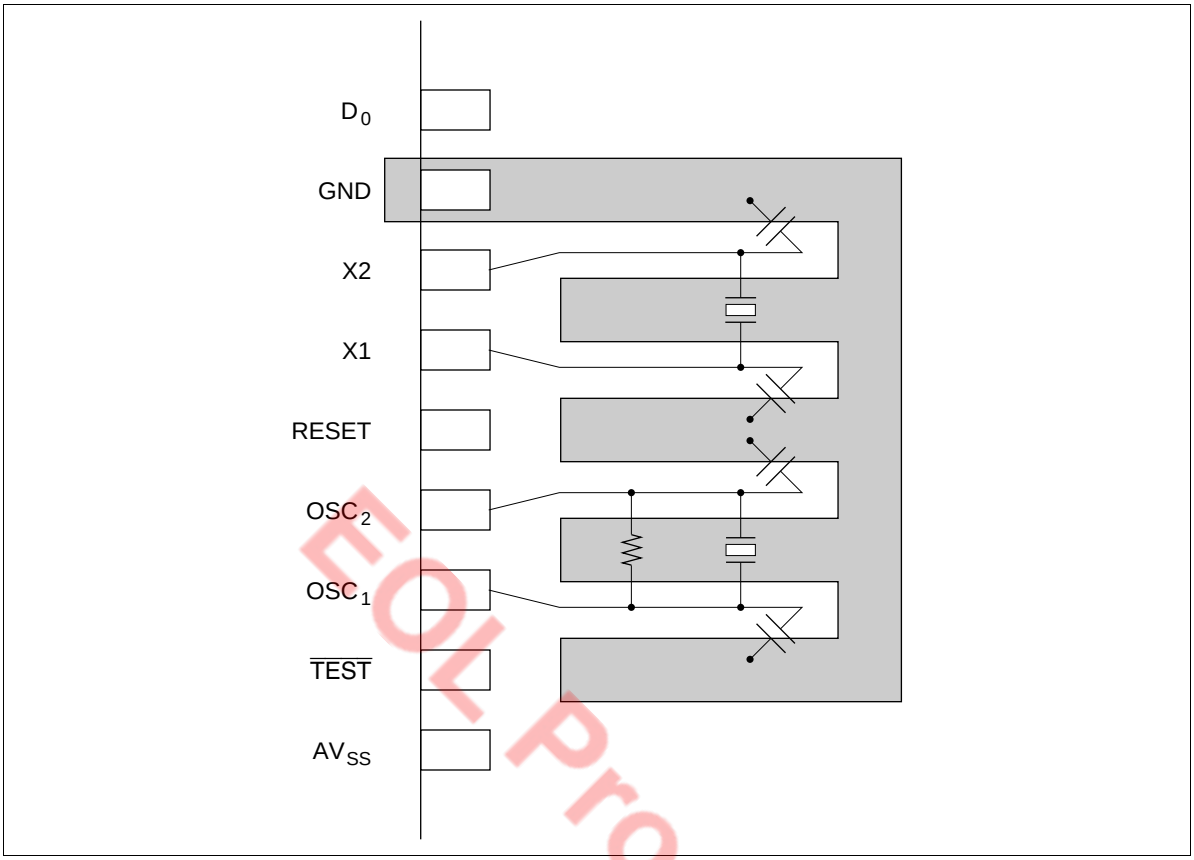


Figure 23 Typical Layout of Crystal and Ceramic Oscillators

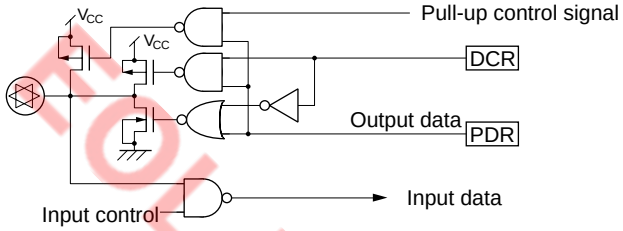
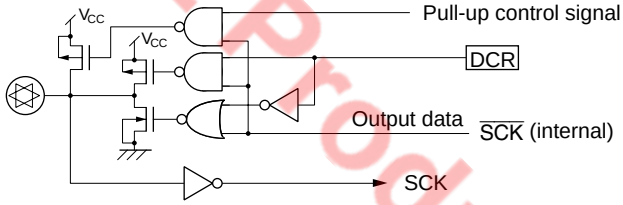
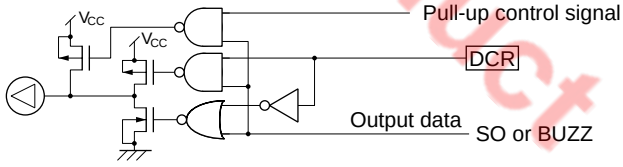
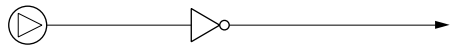
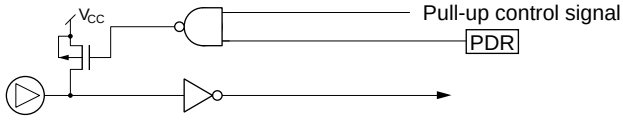
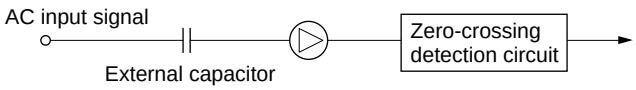
Input/Output

The MCU has 2 input pins and 33 input/output pins, 8 of the input/output pins being large-current pins (15 mA, max.). A program-controlled pull-up MOS transistor is provided for each input/output pin.

The output buffer is turned on and off by the data control register (DCR) during input through an input/output pin.

I/O pin circuit types are shown in table 22.

Table 22 Circuit Configurations of I/O Pins

I/O Pin Type	Circuit	Applicable Pins
Common I/O Pin (with pull-up MOS transistor)		D_0–D_8 $R0_0$–$R0_3$ $R1_0$–$R1_3$ $R2_0$–$R2_3$ $R3_0$–$R3_3$ $R4_0$–$R4_3$ $R5_0$–$R5_3$
		$\overline{SCK}$
Output Pin (with pull-up MOS transistor)		SO BUZZ
Input Pin		$\overline{INT_0}$ INT_1
		SI $\overline{EVENT}$
		D_9 D_{10}
		ZCD

Note: For details of the $R1_2$ /SO pin, refer to note 2 of table 23.

D Port (D_0–D_{10}): Consist of 9 input/output pins and 2 input pins. Pins D_0–D_7 are high-current I/O pins, D_8 is an ordinary input/output pin, and D_9 and D_{10} are input-only pins. These pins are set by the SED and SEDD instructions, reset by the RED and REDD instructions, and tested by the TD and TDD instructions.

The operating modes of D_8–D_{10} are set by bits 2 and 3 of port mode register A (PMRA) and bits 0 and 1 of port mode register B (PMRB), as shown in figure 24. The on/off status of the output buffer is controlled by D port data control registers (DCRB, DCRC, and DCRD) that are mapped to memory addresses.

R Ports: Accessed in 4-bit units. Data is input to these ports by the LAR and LBR instructions and output from them by the LRA and LRB instructions. The on/off status of the output buffers of the R ports are controlled by R port data control registers (DCR0–DCR5) that are mapped to memory addresses.

Pins $R1_0$–$R1_3$ are multiplexed with pins $\overline{SCK}$, SI, SO, and BUZZ, respectively. The operating modes of these pins are controlled by bit 3 of the serial mode register (SMR), bits 1 and 0 of port mode register A (PMRA), and bit 2 of port mode register C (PMRC), as shown in figure 24.

Ports R2–R5 are multiplexed with SEG1–SEG16. The functions of these pins must be specified by the LCD output register (LOR: $015).

Serial mode register (SMR): $005

3	2	1	0

Initial value: 0000, R/W: W

$R1_0$ /$\overline{SCK}$ pin mode selection

SMR Bit 3	Port Selection
0	$R1_0$
1	$\overline{SCK}$

Port mode register A (PMRA): $004

3	2	1	0

Initial value: 0000, R/W: W

$R1_2$ /SO pin mode selection
$R1_1$ /SI pin mode selection
D_9 /$\overline{INT_0}$ pin mode selection
D_{10}/INT_1 pin mode selection

PMRA Bit 3	Port Selection	PMRA Bit 2	Port Selection	PMRA Bit 1	Port Selection	PMRA Bit 0	Port Selection
0	D_{10}	0	D_9	0	$R1_1$	0	$R1_2$
1	INT_1	1	$\overline{INT_0}$	1	SI	1	SO

Port mode register B (PMRB): $011

3	2	1	0

Initial value: 0000, R/W: W

D_8 /ZCD/$\overline{EVENT}$ pin mode selection

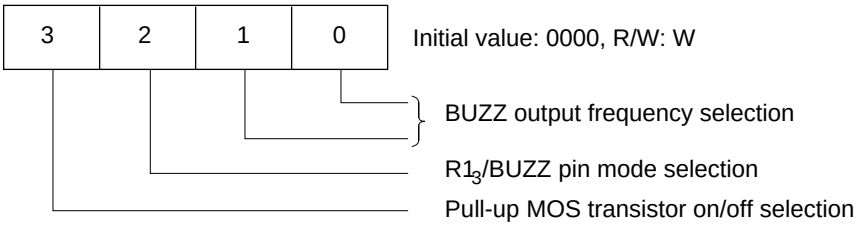
Not used

PMRB Bit 1	PMRB Bit 0	Port Selection
0	0	ZCD (low sensitivity)
	1	ZCD (high sensitivity)*
1	0	D_8
	1	$\overline{EVENT}$

Note: * Becomes low sensitivity in subactive mode.

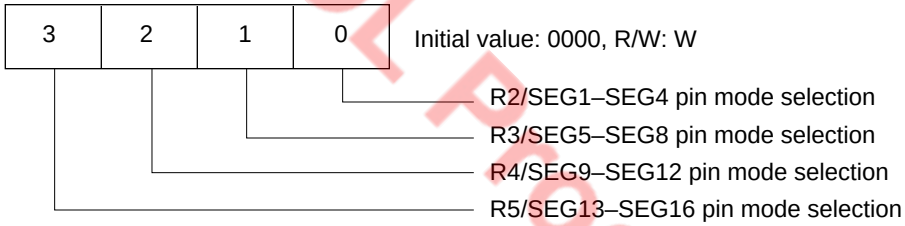
Figure 24 I/O Switching Mode Registers

Port mode register C (PMRC): $012



PMRC Bit 3	Pull-Up MOS On/Off Selection	PMRC Bit 3	Port Selection
0	Off	0	$R1_3$
1	On	1	BUZZ

LCD output register (LOR): $015



LOR Bit 3	Port Selection	LOR Bit 2	Port Selection	LOR Bit 1	Port Selection	LOR Bit 0	Port Selection
0	R5	0	R4	0	R3	0	R2
1	SEG13–SEG16	1	SEG9–SEG12	1	SEG5–SEG8	1	SEG1–SEG4

Figure 24 I/O Switching Mode Registers (cont)

Pull-Up MOS Transistor Control: A program-controlled pull-up MOS transistor is provided for each input/output pin. The on/off status of all these transistors is controlled by bit 3 of port mode register C (PMRC), and the on/off status of an individual transistor can also be controlled by the port data register of the corresponding pin—enabling on/off control of that pin alone.

The on/off status of each transistor and the peripheral function mode of each pin can be set independently.

The configuration of the I/O buffer is shown in figure 25, and the configurations of various program-controlled I/O circuits are given in table 23.

How to Deal with Unused I/O Pins: I/O pins that are not needed by the user system (floating) must be connected to V_{CC} to prevent LSI malfunctions due to noise. These pins must either be pulled up to V_{CC} by their pull-up MOS transistors or by resistors of about 100 kΩ.

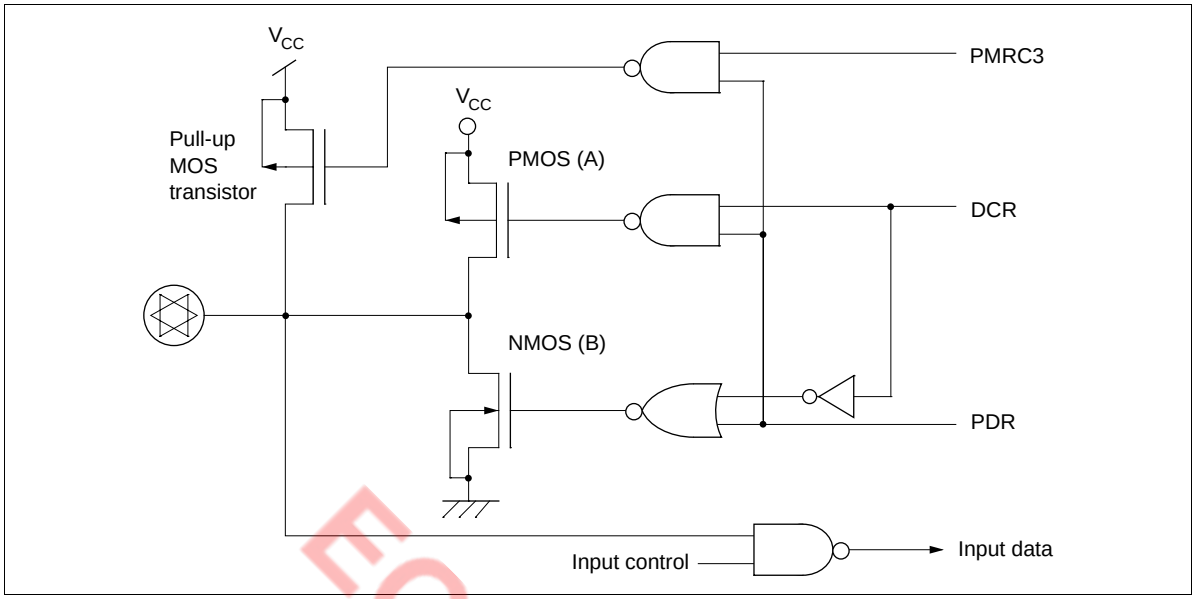


Figure 25 I/O Buffer Configuration

Table 23 Programmable I/O Circuits

PMRC, Bit 3		0				1			
DCR		0		1		0		1	
PDR		0	1	0	1	0	1	0	1
CMOS Buffer	PMOS (A)	Off	Off	Off	On	Off	Off	Off	On
	NMOS (B)	Off	Off	On	Off	Off	Off	On	Off
Pull-Up MOS Transistor		Off	Off	Off	Off	Off	On	Off	On

Notes: 1. Various I/O methods can be selected by different combinations of settings of the above mode registers (PMRC3, DCR, PDR).

2. The PMOS (A) transistor of the $R1_2$/SO pin can be turned off by setting bit 2 of the miscellaneous register (MIS) to 1.

MIS Bit 2	$R1_2$/SO Pin PMOS (A)
0	On
1	Off

3. The relationships between DCRs and pins are as shown on the right.

DCR	Bit 3	Bit 2	Bit 1	Bit 0
DCR0	$R0_3$	$R0_2$	$R0_1$	$R0_0$
DCR1	$R1_3$	$R1_2$	$R1_1$	$R1_0$
DCR2	$R2_3$	$R2_2$	$R2_1$	$R2_0$
DCR3	$R3_3$	$R3_2$	$R3_1$	$R3_0$
DCR4	$R4_3$	$R4_2$	$R4_1$	$R4_0$
DCR5	$R5_3$	$R5_2$	$R5_1$	$R5_0$
DCRB	D_3	D_2	D_1	D_0
DCRC	D_7	D_6	D_5	D_4
DCRD	—	—	—	D_8

Timers

The MCU has two prescalers (S and W) and three timer/counters (A, B, and C).

Prescaler S: Eleven-bit counter that inputs a system clock signal. After being initialized to $000 by MCU reset, prescaler S divides the system clock. Prescaler S keeps counting, except in watch and stop modes, and at MCU reset. Of the prescaler S outputs, timer A input clock, timer B input clock, timer C input clock, and serial interface transmit clock are selected by timer mode register A (TMA), timer mode register B (TMB), timer mode register C (TMC), and the serial mode register (SMR).

Prescaler W: Five-bit counter that inputs the X1 input clock signal divided by eight. Prescaler W output can be selected as a timer A input clock by timer mode register A (TMA).

Timer A: Eight-bit timer that can be used as a clock time-base (figure 26). It is initialized to $00 and incremented at each input clock. If an input clock is applied to timer A after it has reached $FF, an overflow that sets the timer A interrupt request flag (IFTA: $001, bit 2) is generated, and timer A restarts from $00.

Timer A is used to generate regular interrupts (every 256 clocks) for measuring times between events. It can also be used as a clock time-base when bit 3 of timer mode register A (TMA) is set to 1. The timer is driven by the 32-kHz oscillator clock frequency divided by prescaler W, and the clock input to timer A is controlled by TMA. In this case, prescaler W and timer A can be initialized to $00 by software.

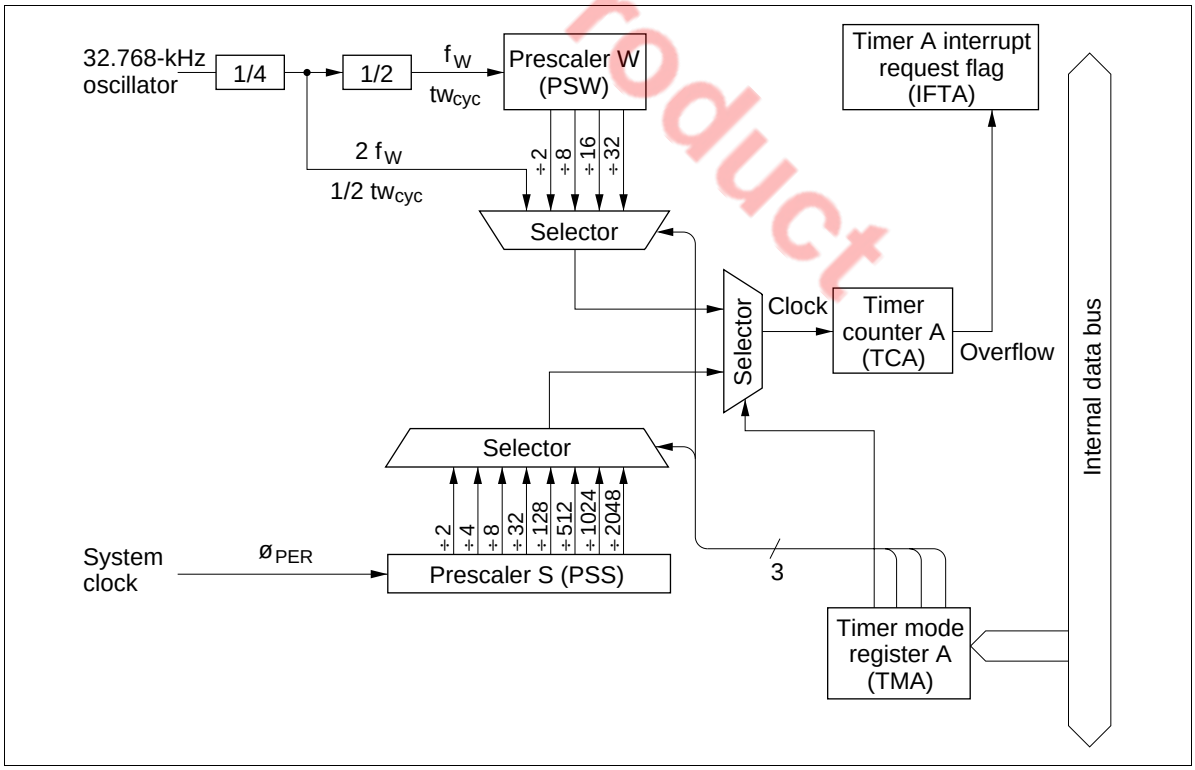


Figure 26 Timer A Block Diagram

Timer B (TCBL and TLRL: $00A, TCBU and TLRU: $00B): Eight-bit write-only timer load register (TLRL and TLRU) and read-only timer counter (TCBL and TCBU) located at the same addresses. The eight-bit configuration consists of lower and upper digits located at sequential addresses. A block diagram of timer B is shown in figure 27.

Timer counter B is initialized by writing to timer load register B (TLR). In this case, the lower nibble must be written to first. The contents of TLR are loaded into the timer counter at the same time the upper nibble is written to, initializing the timer counter. TLR is initialized to $00 by MCU reset.

The count of timer B is obtained by reading timer counter B. In this case, the upper digit must be read first; the count is latched when the upper nibble is read. An auto-reload function, input clock source, and prescaler division ratio of timer B depend on the state of timer mode register B (TMB). When an external event input is used as the input clock source of TMB, the D_8/ZCD/$\overline{\text{EVENT}}$ pin must be set to function as the ZCD or $\overline{\text{EVENT}}$ pin by setting port mode register B (PMRB: $011).

Timer B is initialized to the value set in TMB by software, and is then incremented by one by each clock input. If an input is applied to timer B after it has reached $FF, an overflow is generated. In this case, if the auto-reload function is enabled, timer B is initialized to its initial value; if auto-reload is disabled, the timer is initialized to $00. The overflow sets the timer B interrupt request flag (IFTB: $002, bit 0).

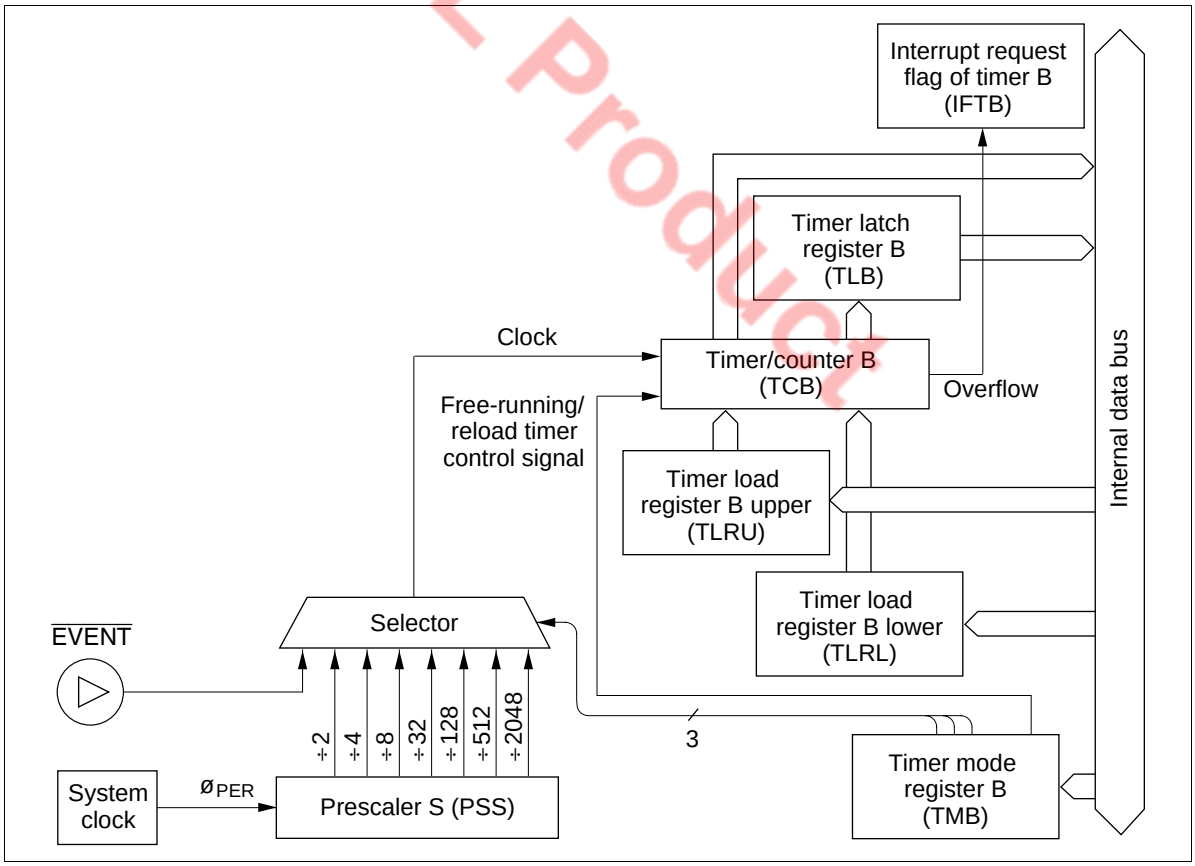


Figure 27 Timer B Free-Running and Reload Operation Block Diagram

Timer C (TCCL and TCRL: $00A, TCCU and TCRU: $00B): Eight-bit write-only timer load register (TCRL and TCRU) and read-only timer counter (TCCL and TCCU) located at the same addresses. The eight-bit configuration consists of lower and upper digits located at sequential addresses. The operation of timer C is basically the same as that of timer B. A block diagram of timer C is shown in figure 28.

The auto-reload function and prescaler division ratio of timer C depend on the state of timer mode register C (TMC). Timer C is initialized to the value set in TMC by software, then is incremented by one at each clock input. If an input is applied to timer C after it has reached $FF, an overflow is generated. In this case, if the auto-reload function is enabled, timer C is initialized to its initial value; if auto-reload is disabled, the timer is initialized to $00. The overflow sets the timer C interrupt request flag (IFTC: $002, bit 2).

Timer C also functions as a watchdog timer. If a program routine runs out of control and an overflow is generated while the watchdog on (WDON) flag is set, the MCU is reset. This error can be detected by having the program control timer C reset before timer C reaches $FF.

The WDON can only have 1 written to it; it is cleared to 0 only by MCU reset.

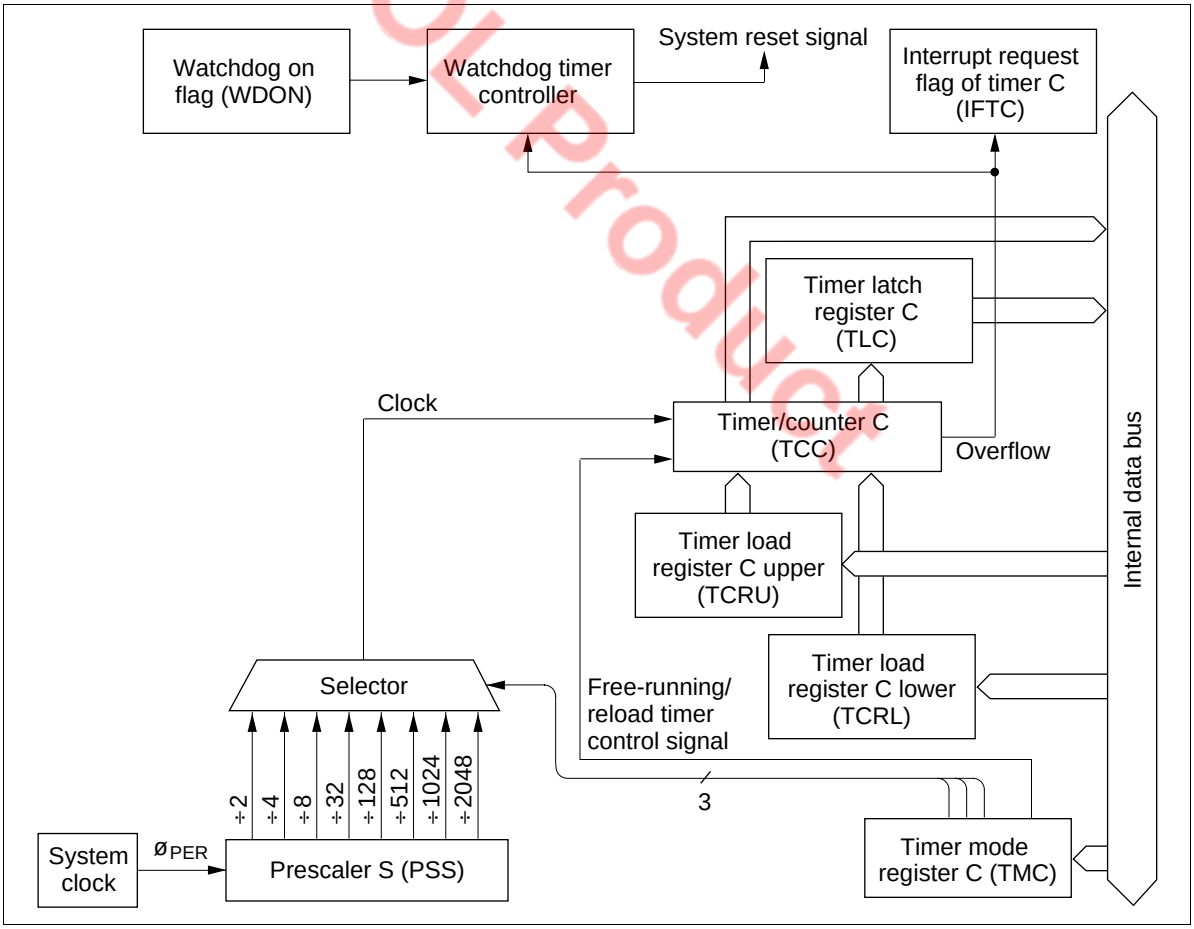


Figure 28 Timer C Block Diagram

Timer Mode Register A (TMA: $008): Four-bit write-only register that controls timer A as shown in table 24.

Table 24 Timer Mode Register A

TMA					
Bit 3	**Bit 2**	**Bit 1**	**Bit 0**	**Source Prescaler, Input Clock Period, Operating Mode**	
0	0	0	0	PSS, 2048 t_{cyc}	Timer A mode
			1	PSS, 1024 t_{cyc}	
		1	0	PSS, 512 t_{cyc}	
			1	PSS, 128 t_{cyc}	
	1	0	0	PSS, 32 t_{cyc}	
			1	PSS, 8 t_{cyc}	
		1	0	PSS, 4 t_{cyc}	
			1	PSS, 2 t_{cyc}	
1	0	0	0	PSW, 32 t_{subcyc}	Time-base mode
			1	PSW, 16 t_{subcyc}	
		1	0	PSW, 8 t_{subcyc}	
			1	PSW, 2 t_{subcyc}	
	1	0	0	PSW, 1/2 t_{subcyc}	
			1	Do not use	
		1	0	PSW, TCA reset	
			1		

Notes:
1. t_{subcyc} = 244.14 µs (when 32.768-kHz crystal oscillator is used)
2. t_{cyc} = 1.9074 µs (when 4.1943-MHz crystal oscillator is used)
3. Timer counter overflow output period (seconds) = input clock period (seconds) × 256.
4. If PSW or TCA reset is selected while the LCD is operating, LCD operation halts (power switch goes off and all SEG and COM pins are grounded).
   When an LCD is connected for display, the PSW and TCA reset periods must be set in the program to the minimum.
5. The division ratio must not be modified during time-base mode operation, otherwise an overflow cycle error will occur.

Timer Mode Register B (TMB: $009): Four-bit write-only register that selects the auto-reload function, input clock source, and the prescaler division ratio as shown in table 25. It is initialized to $0 by MCU reset.

Writing to this register is valid from the second instruction execution cycle. Timer B initialization set by writing to TMB must be done after a mode change becomes valid.

Table 25 Timer Mode Register B

TMB Bit 3	Auto Reload Function
0	Disabled
1	Enabled

TMB Bit 2	Bit 1	Bit 0	Input Clock Period/ Input Clock Source
0	0	0	2048 t_{cyc}
		1	512 t_{cyc}
	1	0	128 t_{cyc}
		1	32 t_{cyc}
1	0	0	8 t_{cyc}
		1	4 t_{cyc}
	1	0	2 t_{cyc}
		1	ZCD/$\overline{\text{EVENT}}$ (external event input)

Timer Mode Register C (TMC: $00D): Four-bit write-only register that selects the auto-reload function and prescaler division ratio as shown in table 26. It is initialized to $0 by MCU reset.

Writing to this register is valid from the second instruction execution cycle. Timer C initialization set by writing to TMC must be done after a mode change becomes valid.

Table 26 Timer Mode Register C

TMC Bit 3	Auto Reload Function
0	Disabled
1	Enabled

TMC			
Bit 2	**Bit 1**	**Bit 0**	**Input Clock Period**
0	0	0	2048 t_{cyc}
		1	1024 t_{cyc}
	1	0	512 t_{cyc}
		1	128 t_{cyc}
1	0	0	32 t_{cyc}
		1	8 t_{cyc}
	1	0	4 t_{cyc}
		1	2 t_{cyc}

Pulse Output

The MCU has a built-in pulse output function called BUZZ. The pulse frequency can be selected from the prescaler S's outputs, and the output frequency depends on the state of port mode register C (PMRC: $012), as shown in table 27. The duty cycle of the pulse output is fixed at 50%. When the pulse output function is used, the $R1_3$/BUZZ pin must be specified as BUZZ by PMRC.

Table 27 Port Mode Register C

PMRC		
Bit 1	**Bit 0**	**Prescaler Division Ratio**
0	0	÷ 1024
	1	÷ 512
1	0	÷ 256
	1	÷ 128

Serial Interface

The MCU has a clock-synchronous serial interface which transmits and receives 8-bit data.

The serial interface consists of a serial data register (SR), serial mode register (SMR), port mode register A (PMRA), octal counter, and selector, as shown in figure 29. The $R1_0/\overline{SCK}$ pin and the transmit clock are controlled by writing data to the SMR. The transmit clock shifts the contents of the SR, which can be read and written to by software, before transmission starts between two MCUs.

The serial interface is activated by the STS instruction. The octal counter is reset to 000 by this instruction, it starts counting at the falling edge of the transmit clock ($\overline{SCK}$), and it increments at the rising edge of the clock. A serial interrupt request flag is set when the eighth transmit clock signal is input (the serial interface is reset) or when serial transmission is discontinued (the octal counter is reset).

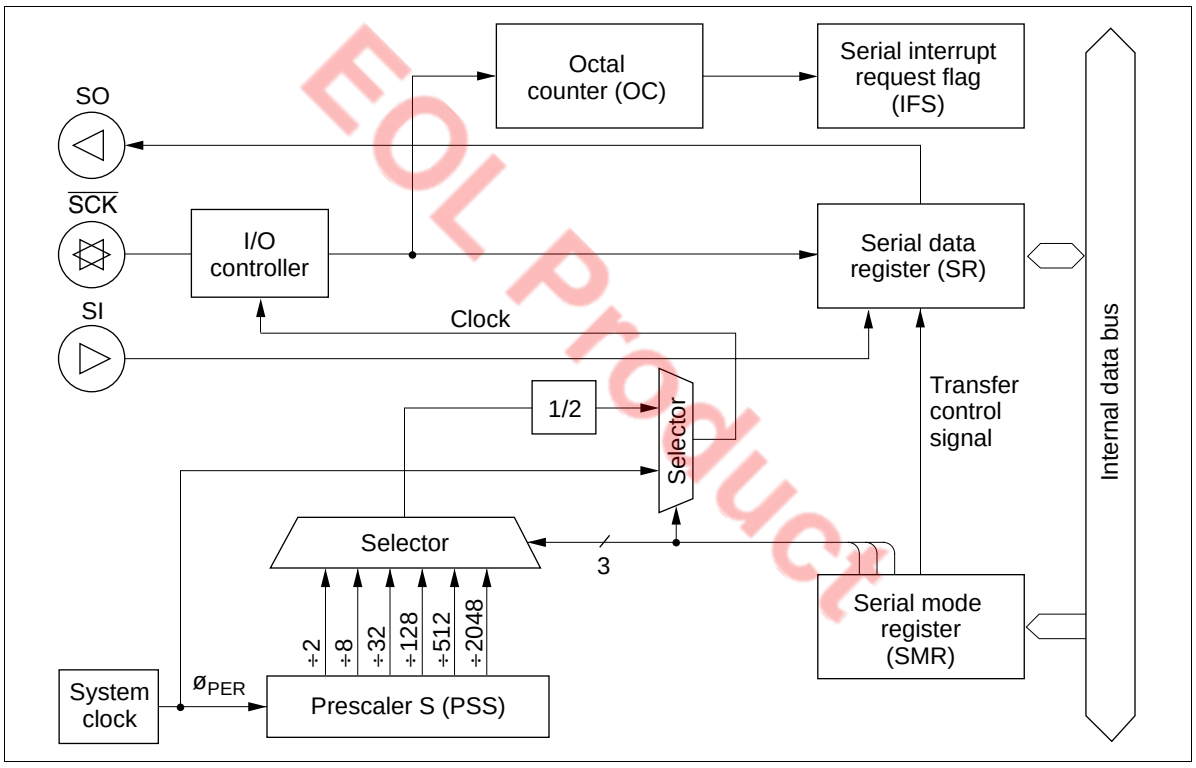


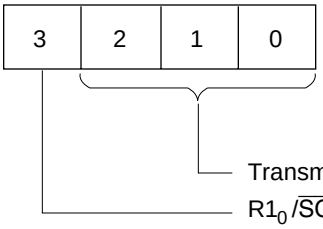
Figure 29 Serial Interface Block Diagram

Serial Mode Register (SMR: $005): Four-bit write-only register that controls the $R1_0/\overline{SCK}$ pin, transmit clock, and prescaler division ratio as shown in figure 30. Writing to this register initializes the serial interface.

A write signal input to the serial mode register discontinues the input of the transmit clock to the serial data register and octal counter. Therefore, if a write is performed during data transmission, the octal counter is reset to 000 to stop transmission, and, at the same time, the serial interrupt request flag is set.

Write operations are valid from the second instruction execution cycle, so the STS instruction must be executed after at least two cycles have been executed. The serial mode register is initialized to $0 by MCU reset.

Serial mode register (SMR): $005



SMR Bit 3	R1$_0$/SCK Pin
0	R1$_0$ port input or output pin
1	SCK input or output pin

SMR Bit 2	SMR Bit 1	SMR Bit 0	R1$_0$/SCK Pin	Clock Source	Prescaler Division Ratio	Transmit Clock Period
0	0	0	SCK output	Prescaler	÷ 2048	4096 t_{cyc}
		1	SCK output	Prescaler	÷ 512	1024 t_{cyc}
	1	0	SCK output	Prescaler	÷ 128	256 t_{cyc}
		1	SCK output	Prescaler	÷ 32	64 t_{cyc}
1	0	0	SCK output	Prescaler	÷ 8	16 t_{cyc}
		1	SCK output	Prescaler	÷ 2	4 t_{cyc}
	1	0	SCK output	System clock	—	1 t_{cyc}
		1	SCK input	External clock	—	—

Note: t_{cyc} = 1.9074 µs (with 4.1943-MHz crystal oscillator used at 1/8 division ratio)

Figure 30 Serial Mode Register

Serial Data Register (SRL: $006, SRU: $007): Eight-bit read/write register separated into upper and lower digits located at sequential addresses. Data in this register is output from the SO pin, LSB first, in synchronism with the falling edge of the transmit clock; and data is input, LSB first, through the SI pin at the rising edge of the transmit clock. Input/output timing is shown in figure 31.

Data cannot be read or written during serial data transmission. If a read/write occurs during transmission, the accuracy of the resultant data cannot be guaranteed.

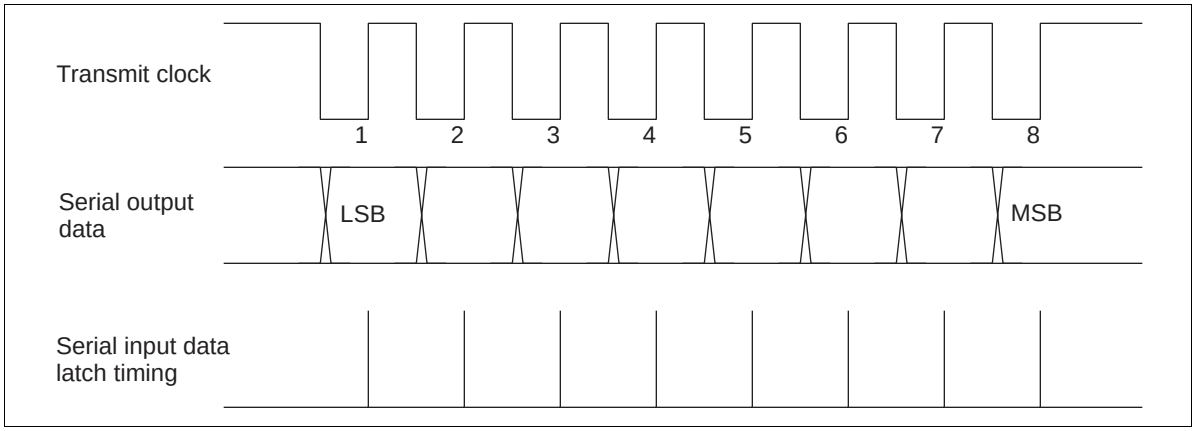


Figure 31 Timing of Serial Interface Output

Selecting and Changing Operating Mode: Table 28 lists the serial interface's operating modes. To select an operating mode, use one of these combinations of PMR and SMR settings; to change the operating mode, always initialize the serial interface internally by writing data to the SMR.

Table 28 Serial Interface Operating Modes

SMR	PMRA		
Bit 3	**Bit 1**	**Bit 0**	**Operating Mode**
1	0	0	Continuous clock output mode
		1	Transmit mode
	1	0	Receive mode
		1	Transmit/receive mode

Serial Interface Operation: Three operating modes are provided for the serial interface; transitions between them are shown in figure 32.

In STS wait state, the serial interface is initialized and the transmit clock is ignored. If the STS instruction is then executed, the serial interface enters transmit clock wait state.

In transmit clock wait state, input of the transmit clock increments the octal clock, shifts the serial clock register, and activates serial transmission. However, note that if clock output mode is selected, the transmit clock is continuously output but data is not transmitted.

During transfer state, the input of eight clocks or the execution of the STS instruction sets the octal counter to 000, and the serial interface enters transmit clock wait state. If the state changes from transmit to another state, the serial interrupt request flag is set by the octal counter reaching 000.

In this state, if the internal clock has been selected, the transmit clock is output in answer to the execution of the STS instruction, but serial transmission is inhibited after the eighth clock is output.

If port mode register A (PMRA) is written to in transmit clock wait state or transfer state, the serial mode register (SMR) must be written to, to initialize the serial interface. The serial interface then enters STS wait state.

If the serial interface shifts from transfer state to another state, the octal counter returns to 000, setting the serial interrupt request flag.

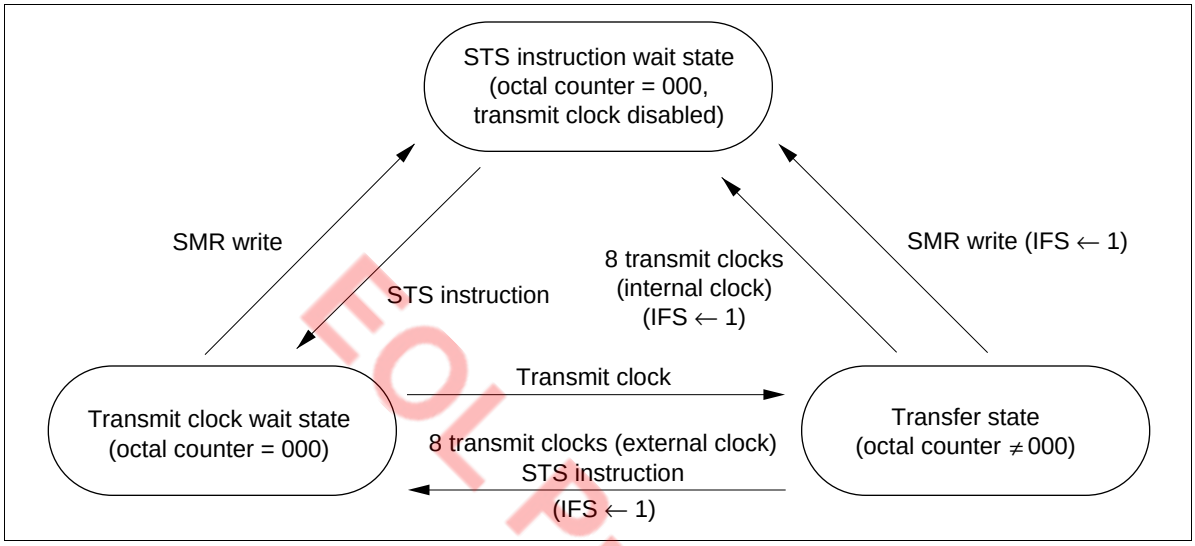


Figure 32 Serial Interface Mode Transitions

Transmit Clock Error Detection: The serial interface will malfunction if a spurious pulse caused by external noise conflicts with a normal transmit clock during transmission. A transmit clock error of this type can be detected as shown in figure 33.

If more than eight transmit clocks are input in transmit clock wait state, the serial interface's state changes to transfer, transmit clock wait, then back to transfer.

If the serial interface is set to STS wait state by writing data to the SMR after the serial interrupt request flag has been reset, the flag is reset again.

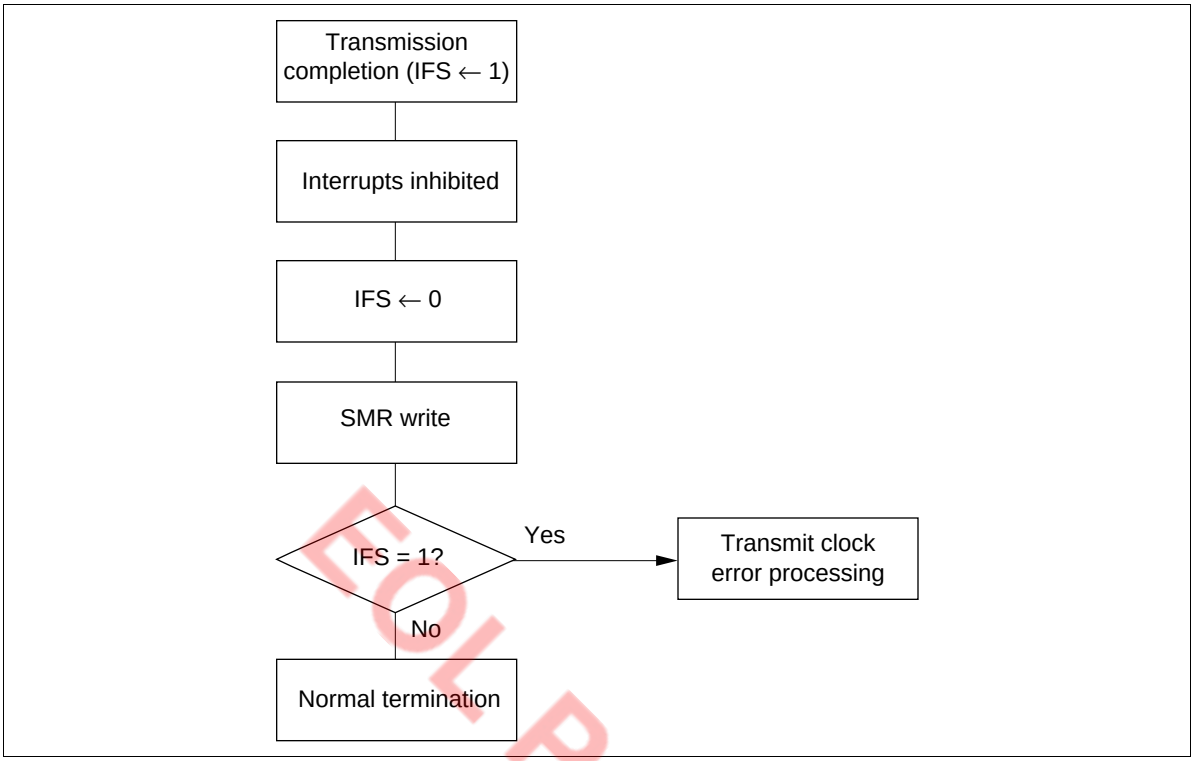


Figure 33 Transmit Clock Error Detection

Note on Use: The serial interrupt request flag might not be set if the status is changed from transfer by the execution of an SMR write or STS instruction during the first period that the transmit clock is low. To prevent this, program a check that the SCK pin is at 1 (by executing an input instruction for the R1 port) before the execution of an SMR write or STS instruction, to ensure that the serial interrupt request flag is set.

A/D Converter

The MCU has a built-in A/D converter that uses a sequential comparison method with a resistor ladder. It can measure four analog inputs with an eight-bit resolution. As shown in the block diagram of figure 34, the A/D converter has a four-bit A/D mode register, a one-bit A/D start flag, and a four-bit plus four-bit A/D data register.

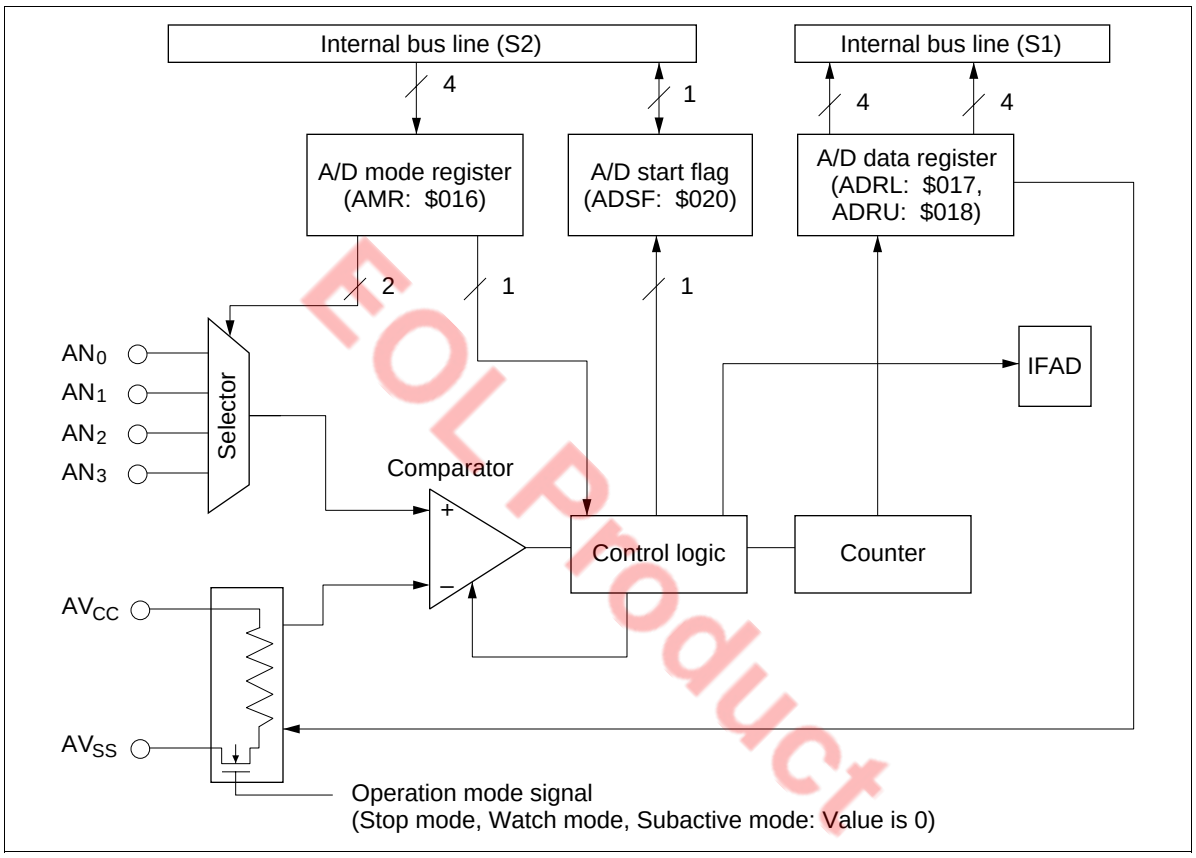


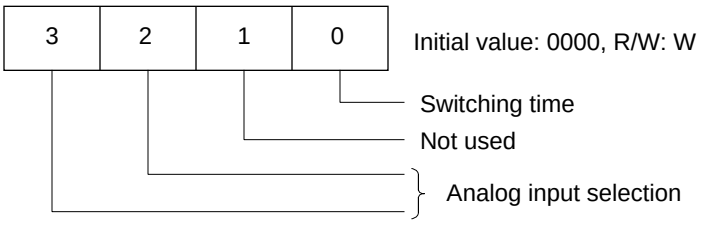
Figure 34 A/D Converter Block Diagram

A/D Mode Register (AMR: $016): Four-bit write-only register which selects the A/D conversion period and indicates analog input pin information. Bit 0 of the AMR selects the A/D conversion period, and bits 2 and 3 select a channel, as shown in figure 35.

A/D Start Flag (ADSF: $020, Bit 2): One-bit flag that initiates A/D conversion when 1 is written to it. At the completion of A/D conversion, the converted data is stored in the A/D data register and the ADSF is cleared. Refer to figure 35.

Note: Use the SEM and SEMD instructions to write data to the ADSF, but make sure that the ADSF is not written to during A/D conversion.

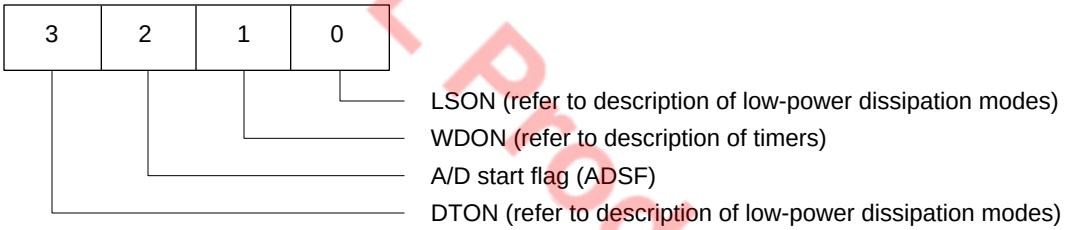
A/D mode register (AMR): $016



AMR Bit 0	Switching Time
0	34 t_{cyc}
1	67 t_{cyc}

AMR Bit 3	AMR Bit 2	Analog Input Selection
0	0	AN_0
	1	AN_1
1	0	AN_2
	1	AN_3

Special flag bits: $020



Bit 2	A/D Start Flag (ADSF)
1	A/D conversion started
0	A/D conversion completed

Figure 35 A/D Registers

A/D Data Register (ADRL: $017, ADRU: $018): Eight-bit read-only register that is not cleared by a reset. Note that data read from this register during A/D conversion cannot be guaranteed. After the completion of A/D conversion, the resultant eight-bit data is held in this register, as shown in figure 36, until the start of the next conversion.

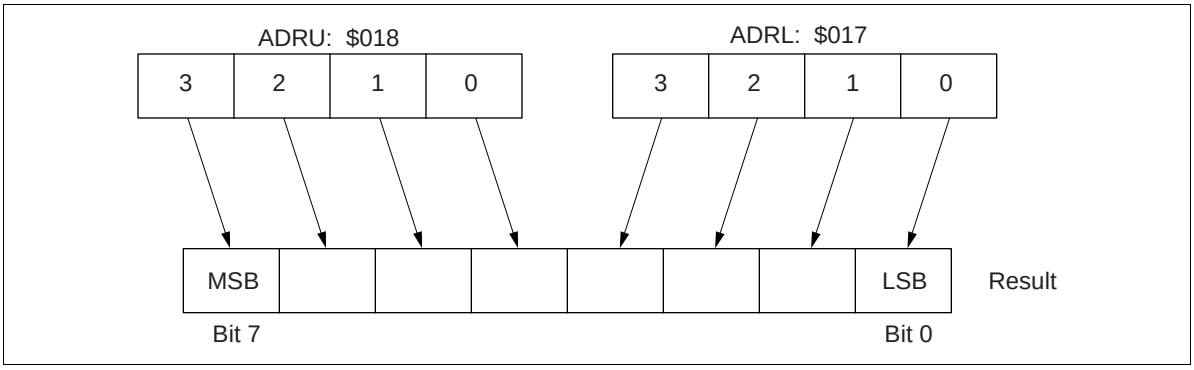


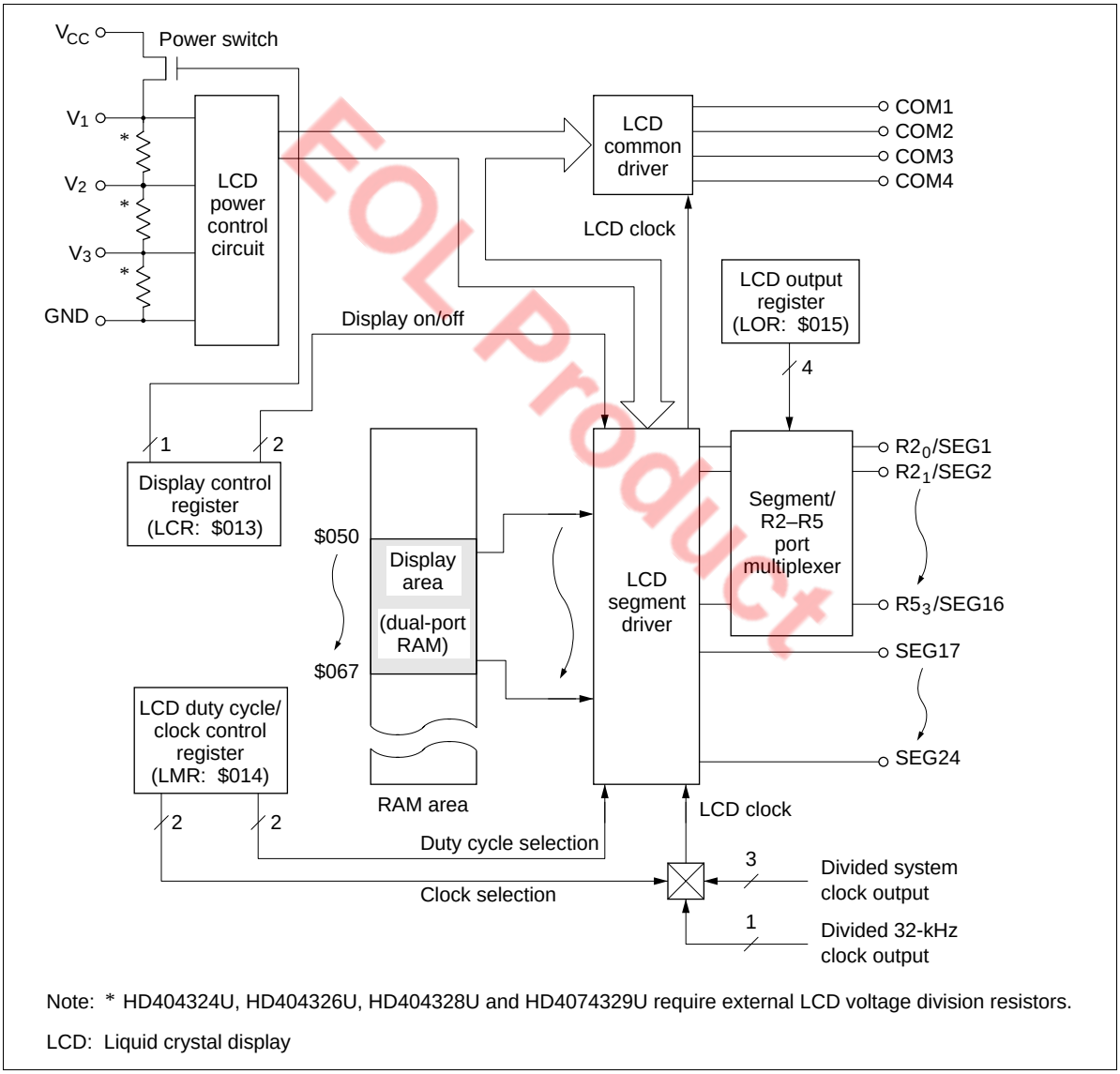
Figure 36 A/D Data Registers

Note on Use: The contents of the A/D data register are not guaranteed during A/D conversion. To ensure that the A/D converter operates stably, do not execute port output instructions during A/D conversion.

LCD Controller/Driver

The MCU has an LCD controller and driver which drive four common signal pins and 24 segment pins. The controller consists of a RAM area in which display data is stored, a display control register (LCR), and a duty cycle/clock control register (LMR), as shown in figures 37 and 38.

Four duty cycles and the LCD clock are program-controllable, and a built-in dual-port RAM ensures that display data can be automatically transmitted to the segment signal pins without program intervention. If a 32-kHz oscillation clock is selected as the LCD clock source, the LCD can be used even in watch mode, in which the system clock stops.



Note: * HD404324U, HD404326U, HD404328U and HD4074329U require external LCD voltage division resistors.

LCD: Liquid crystal display

Figure 37 Block Diagram of LCD Controller/Driver

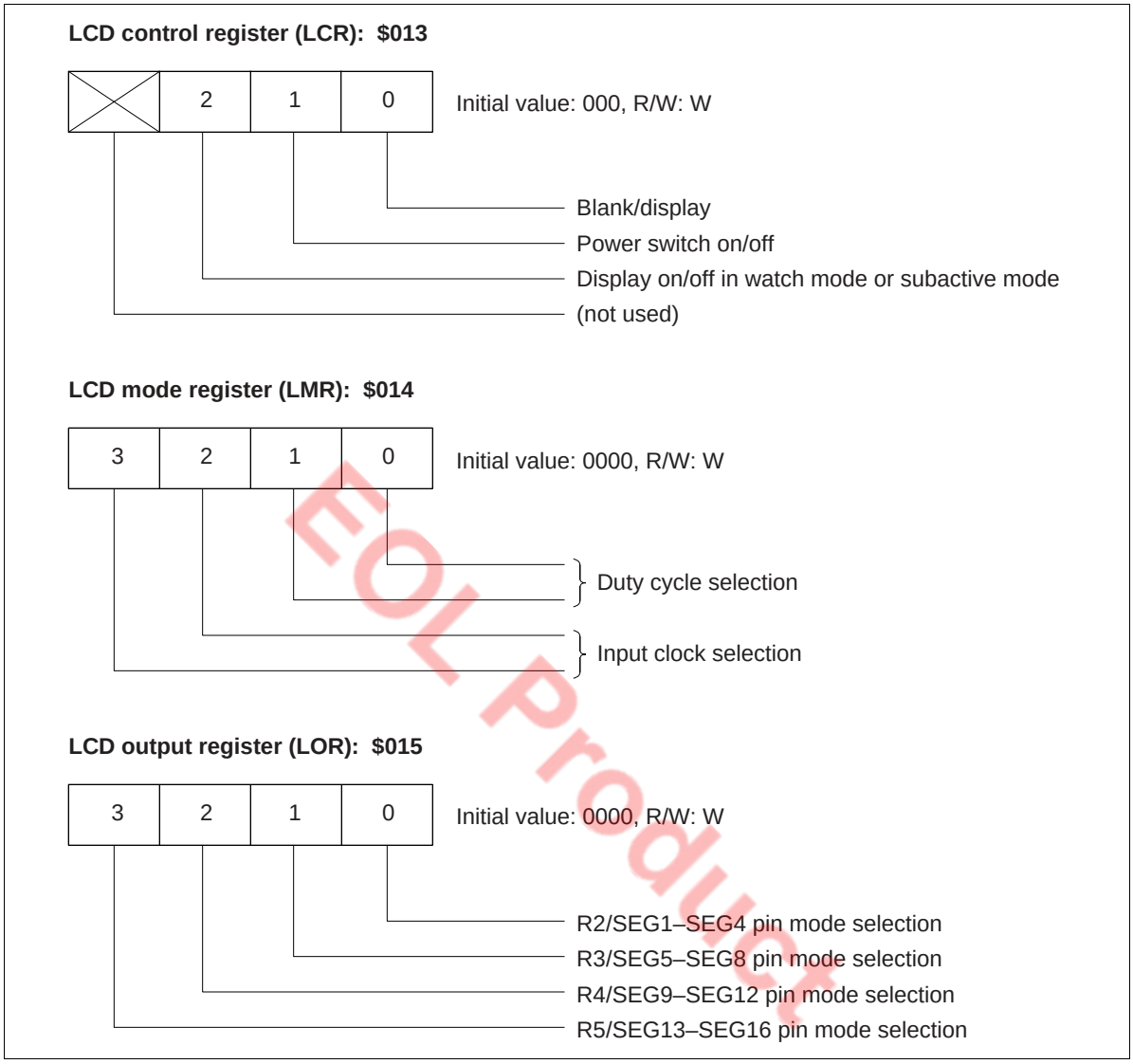


Figure 38 LCD Registers

LCD Data Area and Segment Data ($050–$067): As shown in figure 39, each bit of the storage area corresponds to one of four duty cycles. If data is written to an area corresponding to a certain duty cycle, it is automatically output to the corresponding segments as display data.

	Bit 3	Bit 2	Bit 1	Bit 0	
80	SEG1	SEG1	SEG1	SEG1	$050
81	SEG2	SEG2	SEG2	SEG2	$051
82	SEG3	SEG3	SEG3	SEG3	$052
83	SEG4	SEG4	SEG4	SEG4	$053
84	SEG5	SEG5	SEG5	SEG5	$054
85	SEG6	SEG6	SEG6	SEG6	$055
86	SEG7	SEG7	SEG7	SEG7	$056
87	SEG8	SEG8	SEG8	SEG8	$057
88	SEG9	SEG9	SEG9	SEG9	$058
89	SEG10	SEG10	SEG10	SEG10	$059
90	SEG11	SEG11	SEG11	SEG11	$05A
91	SEG12	SEG12	SEG12	SEG12	$05B
	COM4	COM3	COM2	COM1	

	Bit 3	Bit 2	Bit 1	Bit 0	
92	SEG13	SEG13	SEG13	SEG13	$05C
93	SEG14	SEG14	SEG14	SEG14	$05D
94	SEG15	SEG15	SEG15	SEG15	$05E
95	SEG16	SEG16	SEG16	SEG16	$05F
96	SEG17	SEG17	SEG17	SEG17	$060
97	SEG18	SEG18	SEG18	SEG18	$061
98	SEG19	SEG19	SEG19	SEG19	$062
99	SEG20	SEG20	SEG20	SEG20	$063
100	SEG21	SEG21	SEG21	SEG21	$064
101	SEG22	SEG22	SEG22	SEG22	$065
102	SEG23	SEG23	SEG23	SEG23	$066
103	SEG24	SEG24	SEG24	SEG24	$067
	COM4	COM3	COM2	COM1	

Figure 39 Configuration of LCD RAM Area (for Dual-Port RAM)

LCD Control Register (LCR: $013): Three-bit write-only register which controls LCD blanking, the turning on and off of the liquid-crystal display's power supply division resistor, and display in watch and subactive modes, as shown in table 29.

- Blank/display
  Blank: Segment signals are turned off, regardless of LCD RAM data setting.
  Display: LCD RAM data is output as segment signals.

- Power switch on/off
  Off: The power switch is off.
  On: The power switch is on and V_1 is V_{CC}.

- Watch/subactive mode display
  Off: In watch and subactive modes, all common and segment pins are grounded and the liquid-crystal power switch is turned off.
  On: In watch and subactive modes, LCD RAM data is output as segment signals.

Table 29 LCD Control Register

LCR Bit 2	Display in Watch Mode or Subactive Mode	LCR Bit 1	Power Switch On/Off	LCR Bit 0	Blank/Display
0	Off	0	Off	0	Blank
1	On	1	On	1	Display

Note: When using an LCD in watch mode or subactive mode, use the divided output of a 32-kHz oscillator as the LCD clock and set bit 2 of the LCR to 1. If using the divided output of the system clock as the LCD clock, always set bit 2 of the LCR to 0.

LCD Duty Cycle/Clock Control Register (LMR: $014): Four-bit write-only register which selects the display duty cycle and LCD clock source, as shown in table 30. The dependence of frame frequency on duty cycle is shown in table 31.

Table 30 LCD Duty Cycle/Clock Control Register

LMR Bit 3	Bit 2	Bit 1	Bit 0	Duty Selection/Input Clock Selection
—	—	0	0	1/4 duty cycle
			1	1/3 duty cycle
		1	0	1/2 duty cycle
			1	Static
0	0	—	—	CL0 (32.768/64 kHz when using a 32.768-kHz oscillator)
	1			CL1 (f_{cyc}/256)
1	0			CL2 (f_{cyc}/2048)
	1			CL3 (refer to table 31)

Note: f_{cyc} is the divided system clock output.

Table 31 LCD Frame Periods for Different Duty Cycles

Static Duty Cycle

	LMR							
	Bit 3	Bit 2	Bit 3	Bit 2	Bit 3	Bit 2	Bit 3	Bit 2
	0	0	0	1	1	0	1	1
Instruction Cycle Time	CL0		CL1		CL2		CL3*	
2 µs	512 Hz		1953 Hz		244 Hz		122 Hz/64 Hz	

1/2 Duty Cycle

	LMR							
	Bit 3	Bit 2	Bit 3	Bit 2	Bit 3	Bit 2	Bit 3	Bit 2
	0	0	0	1	1	0	1	1
Instruction Cycle Time	CL0		CL1		CL2		CL3*	
2 µs	256 Hz		976.5 Hz		122 Hz		61 Hz/32 Hz	

1/3 Duty Cycle

	LMR							
	Bit 3	Bit 2	Bit 3	Bit 2	Bit 3	Bit 2	Bit 3	Bit 2
	0	0	0	1	1	0	1	1
Instruction Cycle Time	CL0		CL1		CL2		CL3*	
2 µs	170.6 Hz		651 Hz		81.3 Hz		40.6 Hz/21.3 Hz	

1/4 Duty Cycle

	LMR							
	Bit 3	Bit 2	Bit 3	Bit 2	Bit 3	Bit 2	Bit 3	Bit 2
	0	0	0	1	1	0	1	1
Instruction Cycle Time	CL0		CL1		CL2		CL3*	
2 µs	128 Hz		488.2 Hz		61 Hz		30.5 Hz/16 Hz	

Note: * The division ratio depends on the value of bit 3 of timer mode register A (TMA); the first value is for TMA3 = 0 and the second is for TMA3 = 1.

When TMA3 = 0, CL3 = f_{cyc}/4096

When TMA3 = 1, CL3 = 32.768 kHz/512.

LCD Output Register (LOR: $015): Write-only register used to specify that ports R2–R5 act as pins SEG1–SEG16, as shown in table 32.

Table 32 LCD Output Register

LOR Bit 3	Port Selection	LOR Bit2	Port Selection	LOR Bit 1	Port Selection	LOR Bit 0	Port Selection
0	R5	0	R4	0	R3	0	R2
1	SEG16–SEG13	1	SEG12–SEG9	1	SEG8–SEG5	1	SEG4–SEG1

Large Liquid-Crystal Panel Drive and V_{LCD}: To drive a large-capacity LCD, decrease the resistance of the built-in division resistors by attaching external resistors in parallel, as shown in figure 40.

Since HD404328U and HD4074329U do not have built-in division resistors, they require external LCD voltage division resistors for voltage adjustment.

The size of these resistors cannot be simply calculated from the LCD load capacitance because the matrix configuration of the LCD complicates the paths of charge/discharge currents flowing through the capacitors—and the resistance will also vary with lighting conditions. This size must be determined by trial-and-error, taking into account the power dissipation of the device using the LCD, but a resistance of 1 kΩ to 10 kΩ would usually be suitable. (Another effective method is to attach capacitors of 0.1 µF to 0.3 µF.)

Always turn off the power switch (set bit 1 of the LCR to 0) before changing the liquid-crystal drive voltage (V_{LCD}).

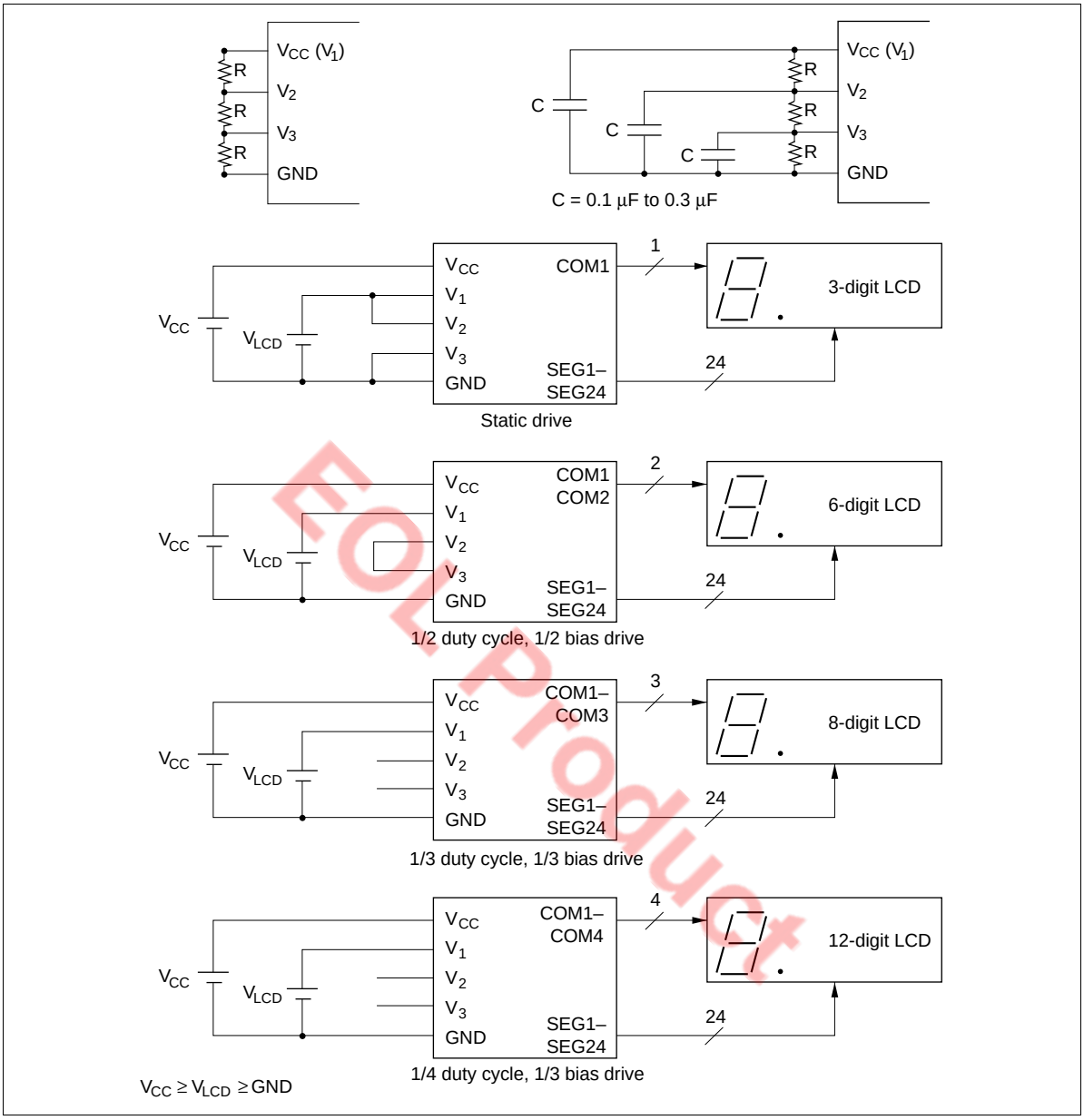


Figure 40 LCD Connection Examples

Zero-Crossing Detection Circuit

The MCU has a zero-crossing detection circuit that generates a digital signal in synchronism with an AC signal input to the ZCD pin through an external capacitor. A block diagram of the zero-crossing detection circuit is shown in figure 41.

The zero-crossing detection circuit has two modes (low sensitivity mode and high sensitivity mode) which are set by port mode register B (PMRB: $011) as shown in table 33.

A digital signal generated by the zero-crossing detection circuit sets the zero-crossing interrupt request flag (IFZC). The interrupt edge is selected by the interrupt mode register (IMR: $010). This signal can be made as the input clock of timer B by setting the input clock source of timer mode register B (TMB: $009) for external event input.

Note: After MCU reset, the D_8/ZCD/$\overline{EVENT}$ pin is set to ZCD. With this setting, a supply current (bias current) always flows because a bias circuit within the zero-crossing circuit is still operating. This current flows in all MCU operation modes, but it is particularly critical in stop mode because the MCU is more affected by bias current since the other circuits of the LSI are not dissipating much current. If the zero-crossing detection function is not being used, use port mode register B to set this pin to D_8 or $\overline{EVENT}$. This prevents the bias current from flowing.

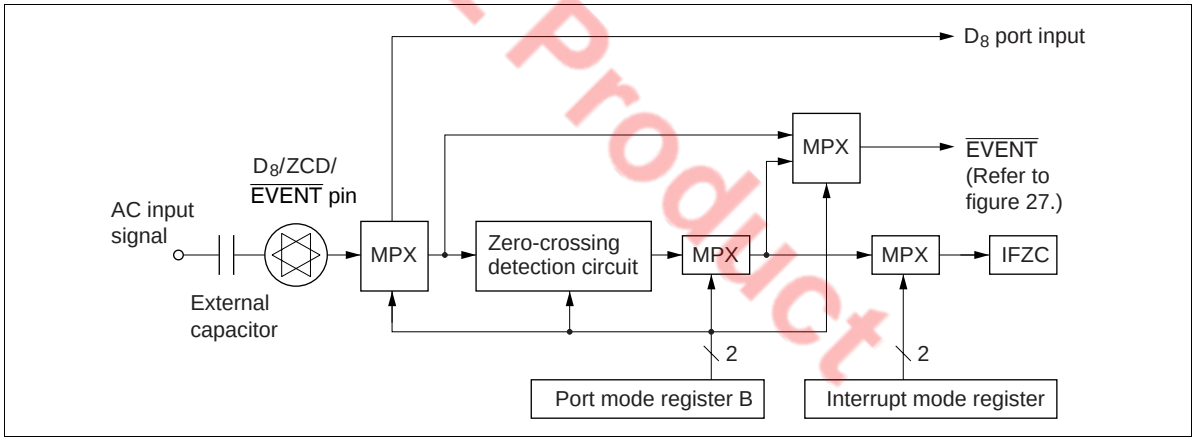


Figure 41 Block Diagram of Zero-Crossing Detection Circuit

Table 33 Port Mode Register B

PMRB		
1	**0**	**Port Selection**
0	0	ZCD (low sensitivity mode)
	1	ZCD (high sensitivity mode)*
1	0	D_8
	1	$\overline{EVENT}$

Note: * Becomes low sensitivity in subactive mode.

Table 34 Registers in Special Register Area

Name	Address	R/W	Bit	Description
PMRA	$004	W	0	$R1_2$/S0 pin mode selection
			1	$R1_1$/SI pin mode selection
			2	$D_9/\overline{INT_0}$ pin mode selection
			3	D_{10}/INT_1 pin mode selection
SMR	$005	W	2–0	Serial transmit clock speed selection
			3	$R1_0/\overline{SCK}$ pin mode selection
SRL	$006	R/W	3–0	Serial interface data register, lower 4 bits
SRU	$007	R/W	3–0	Serial interface data register, upper 4 bits
TMA	$008	W	2–0	Input clock selection (timer A)
			3	Timer-A/time-base mode selection
TMB	$009	W	2–0	Input clock selection (timer B)
			3	Auto-reload function selection
TCBL/TLRL	$00A	R/W	3–0	Timer counter/timer load register (timer B), lower 4 bits
TCBU/TLRU	$00B	R/W	3–0	Timer counter/timer load register (timer B), upper 4 bits
MIS	$00C	W	1, 0	Interrupt frame period selection
			2	$R1_2$/SO PMOS off
			3	Changeover to setting by system oscillator frequency
TMC	$00D	W	2–0	Input clock selection (timer C)
			3	Auto-reload function selection
TCCL/TCRL	$00E	R/W	3–0	Timer counter/timer load register (timer C), lower 4 bits
TCCU/TCRU	$00F	R/W	3–0	Timer counter/timer load register (timer C), upper 4 bits
IMR	$010	W	1, 0	INT_1 detection edge selection
			3, 2	Zero-crossing detection edge selection
PMRB	$011	W	1, 0	D_8/ZCD/$\overline{EVENT}$ pin mode selection
			3, 2	Do not use
PMRC	$012	W	1, 0	Buzzer frequency selection
			2	$R1_3$/ BUZZ pin mode selection
			3	Pull-up MOS transistor on/off selection
LCR	$013	W	0	LCD display selection
			1	LCD power switch on/off selection
			2	LCD display selection during watch mode
			3	Do not use
LMR	$014	W	1, 0	LCD duty cycle selection
			3, 2	LCD input clock selection

Name	Address	R/W	Bit	Description
LOR	$015	W	0	R2/SEG1–SEG4 pin mode selection
			1	R3/SEG5–SEG8 pin mode selection
			2	R4/SEG9–SEG12 pin mode selection
			3	R5/SEG13–SEG16 pin mode selection
AMR	$016	W	0	Conversion timing selection (A/D)
			1	Do not use
			3, 2	Analog input selection (A/D)
ADRL	$017	R	3–0	A/D data register, lower 4 bits
ADRU	$018	R	3–0	A/D data register, upper 4 bits
DCR0	$030	W	3–0	Data control register for port R0
DCR1	$031	W	3–0	Data control register for port R1
DCR2	$032	W	3–0	Data control register for port R2
DCR3	$033	W	3–0	Data control register for port R3
DCR4	$034	W	3–0	Data control register for port R4
DCR5	$035	W	3–0	Data control register for port R5
DCRB	$03B	W	3–0	Data control register for port D_0–D_3
DCRC	$03C	W	3–0	Data control register for port D_4–D_7
DCRD	$03D	W	0	Data control register for port D_8
			3–1	Do not use

PROM Mode Description

Programming the Built-In ROM

The MCU's built-in ROM is programmed in PROM mode in which the pins are arranged as shown in figure 42. PROM mode is set by pulling $\overline{TEST}$, $\overline{M}_0$, and $\overline{M}_1$ low, and RESET high as shown in figure 43. In PROM mode, the MCU does not operate, but it can be programmed in the same way as any other commercial 27256-type EPROM using a standard PROM programmer and a 64-to-28–pin socket adapter. Recommended PROM programmers and socket adapters are listed in table 35.

Since an HMCS400-series instruction is ten bits long, the HMCS400-series MCU has a built-in conversion circuit to enable use of a general-purpose PROM programmer. This circuit splits each instruction into a lower five bits and an upper five bits that are read from or written to consecutive addresses. This means that if, for example, 16 kwords of built-in PROM are to be programmed by a general-purpose PROM programmer, a 32-kbyte address space ($0000–$7FFF) must be specified.

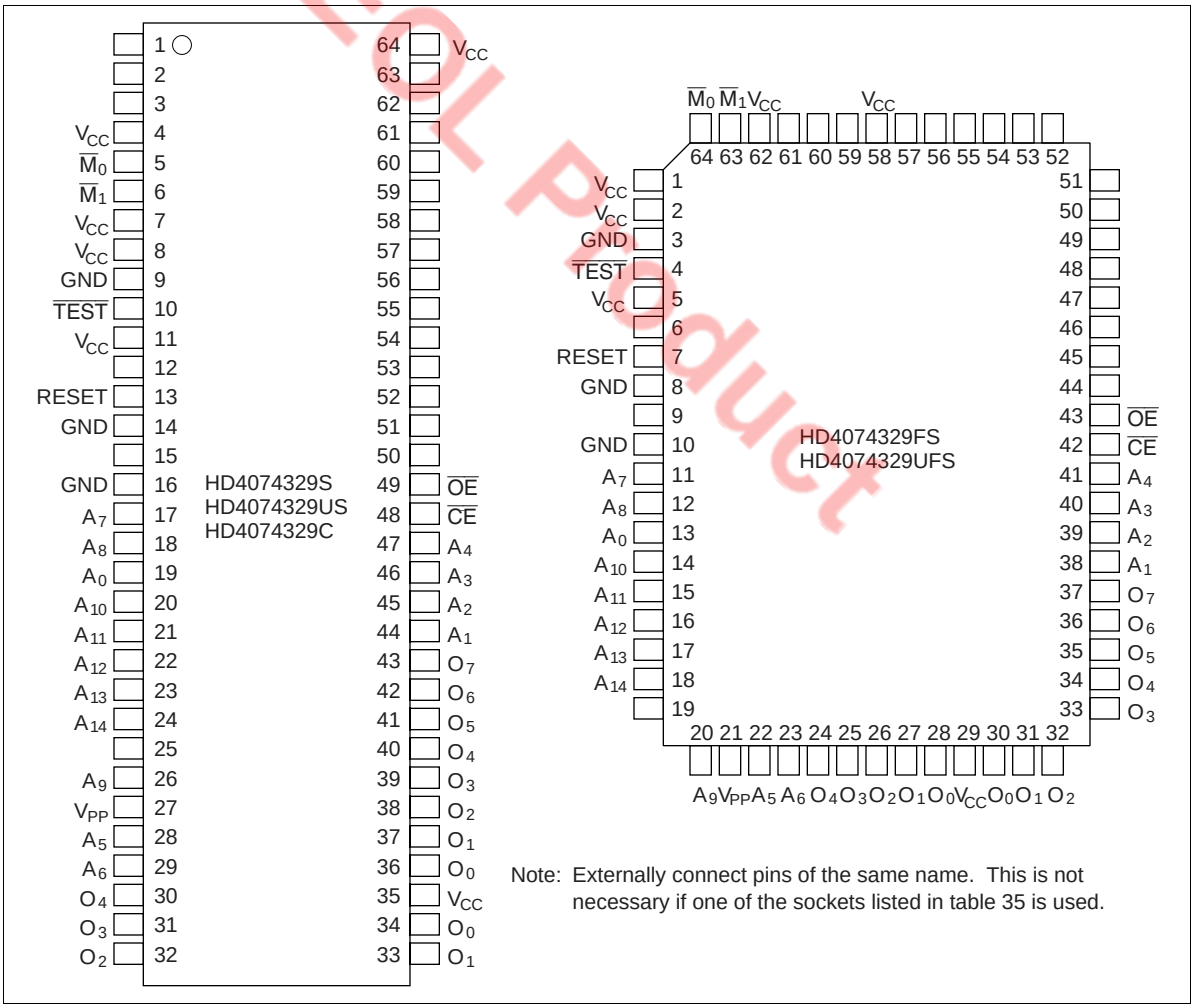


Figure 42 Pin Arrangement in PROM Mode

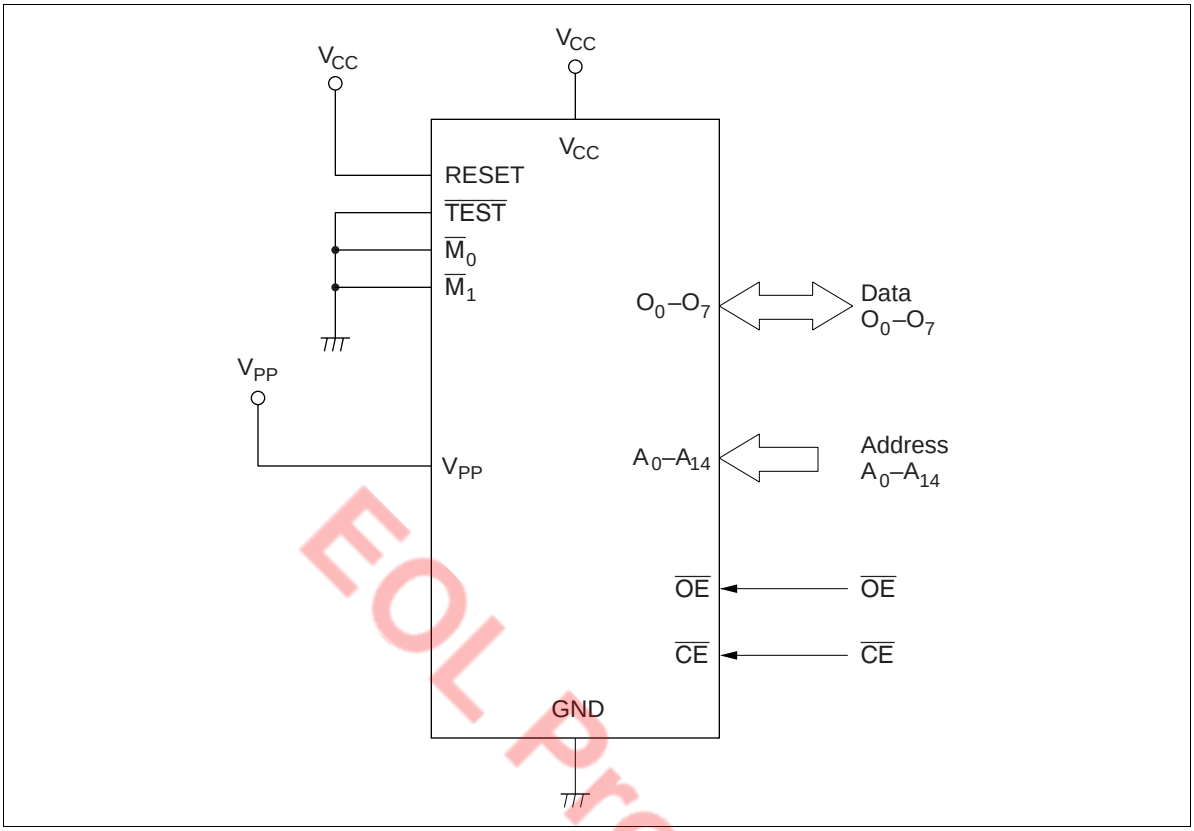


Figure 43 PROM Mode Connections

Table 35 Recommended PROM Programmers and Socket Adapters

PROM Programmer		Socket Adapter		
Manufacturer	**Model Name**	**Package**	**Model Name**	**Manufacturer**
DATA I/O Corp.	29B	DP-64S DC-64S	HS432ESS01H	Hitachi
		FP-64B	HS432ESF01H	Hitachi
AVAL Data Corp.	PKW-1000	DP-64S DC-64S	HS432ESS01H	Hitachi
		FP-64B	HS432ESF01H	Hitachi

Warnings

1. Always specify addresses $0000 to $7FFF when programming with a PROM programmer. If address $8000 or higher is accessed, the PROM may not be programmed or verified correctly. Set all data in unused addresses to $FF.

   Note that the plastic-package version cannot be erased and reprogrammed, but the ceramic window-package version can be reprogrammed after being exposed to ultraviolet light.

2. Make sure that the PROM programmer, socket adapter, and LSI are aligned correctly (their pin 1 positions match), otherwise overcurrents may damage the LSI. Before starting programming, make sure that the LSI is firmly fixed in the socket adapter and the socket adapter is firmly fixed in the programmer.

3. PROM programmers have two voltages (V_{PP}): 12.5 V and 21 V. Remember that ZTAT™ devices require a V_{PP} of 12.5 V—the 21-V setting will damage them. 12.5 V is the Intel 27256 setting.

Programming and Verification: The built-in PROM of the MCU can be programmed at high speed without risk of voltage stress or damage to data reliability.

Programming and verification modes are selected as shown in table 36.

For details of PROM programming, refer to the Notes on PROM Programming section.

Table 36 PROM Mode Selection

	Pin			
Mode	**$\overline{CE}$**	**$\overline{OE}$**	**V_{PP}**	**O_0–O_7**
Programming	Low	High	V_{PP}	Data input
Verification	High	Low	V_{PP}	Data output
Programming inhibited	High	High	V_{PP}	High impedence

Erasure (Window Package)

Data in the PROM is erased by exposing the LSI to ultraviolet light of a wavelength of 2537 Å for an integrated dose of at least 15 W.s/cm^2. These conditions can be satisfied by placing the LSI about 2 cm to 3 cm away from an ultraviolet lamp with a rating of 12,000 µW/cm^2 for about 20 minutes. After erasure, all PROM bits are set to 1.

For details of packages with windows, refer to the Notes on Window Packages section.

Addressing Modes

RAM Addressing Modes

The MCU has three RAM addressing modes, as shown in figure 44 and described below.

Register Indirect Addressing Mode: The contents of the W, X, and Y registers (10 bits in total) are used as a RAM address.

Direct Addressing Mode: A direct addressing instruction consists of two words. The first word contains the opcode, and the contents of the second word (10 bits) are used as a RAM address.

Memory Register Addressing Mode: The memory registers (MR), which consist of 16 digits from $040–$04F, are accessed with the LAMR and XMRA instructions.

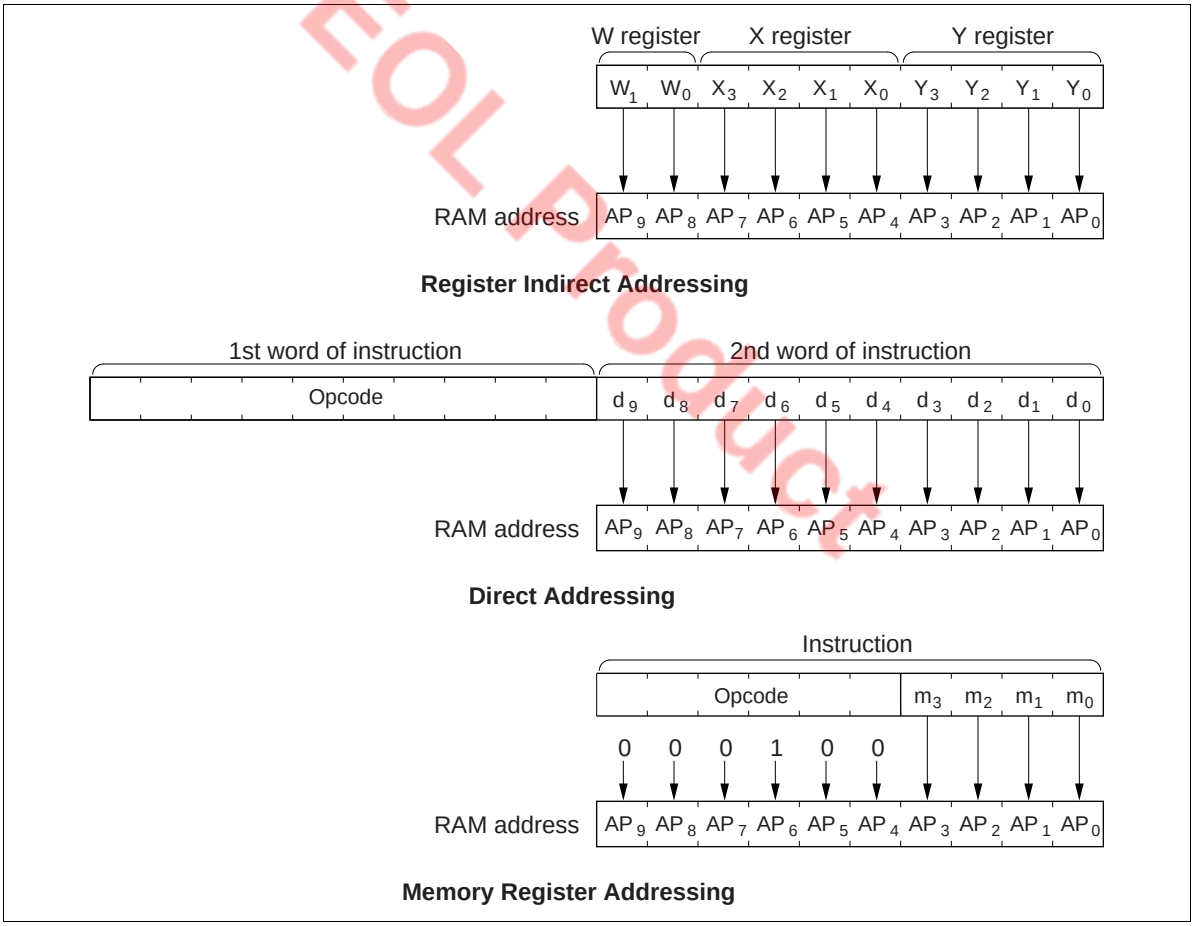


Figure 44 RAM Addressing Modes

ROM Addressing Modes and the P Instruction

The MCU has four ROM addressing modes, as shown in figure 45 and described below.

Direct Addressing Mode: A program can branch to any address in the ROM memory space by executing the JMPL, BRL, or CALL instruction. Each of these instructions replaces the 14 program counter bits (PC_{13}–PC_0) with 14-bit immediate data.

Current Page Addressing Mode: The MCU has 64 pages of ROM with 256 words per page. A program can branch to any address in the current page by executing the BR instruction. This instruction replaces the eight low-order bits of the program counter (PC_7–PC_0) with eight-bit immediate data. If the BR instruction is on a page boundary (address 256n + 255), executing that instruction transfers the PC contents to the next physical page, as shown in figure 47. This means that the execution of the BR instruction on a page boundary will make the program branch to the next page.

Note that the HMCS400-Series cross macroassembler has an automatic paging feature for ROM pages.

Zero-Page Addressing Mode: A program can branch to the zero-page subroutine area located at $000–$003F by executing the CAL instruction. When the CAL instruction is executed, 6 bits of immediate data are placed in the six low-order bits of the program counter (PC_5–PC_0), and 0s are placed in the eight high-order bits (PC_{13}–PC_6).

Table Data Addressing Mode: A program can branch to an address determined by the contents of four-bit immediate data, the accumulator, and the B register by executing the TBR instruction.

P Instruction: ROM data addressed in table data addressing mode can be referenced with the P instruction as shown in figure 46. If bit 8 of the ROM data is 1, eight bits of ROM data are written to the accumulator and the B register. If bit 9 is 1, eight bits of ROM data are written to the R0 and R1 port output registers. If both bits 8 and 9 are 1, ROM data is written to the accumulator and the B register, and also to the R0 and R1 port output registers at the same time.

The P instruction has no effect on the program counter.

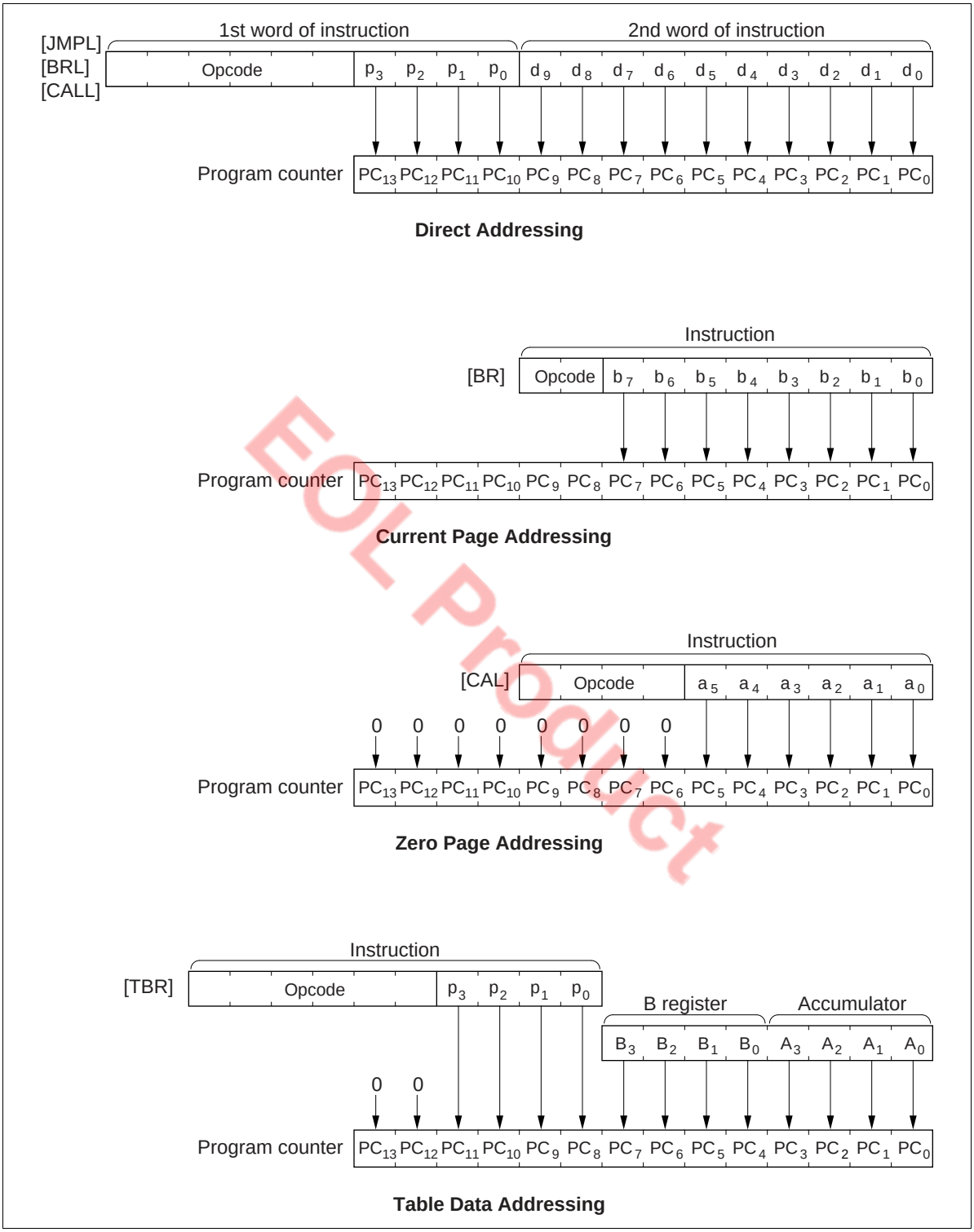


Figure 45 ROM Addressing Modes

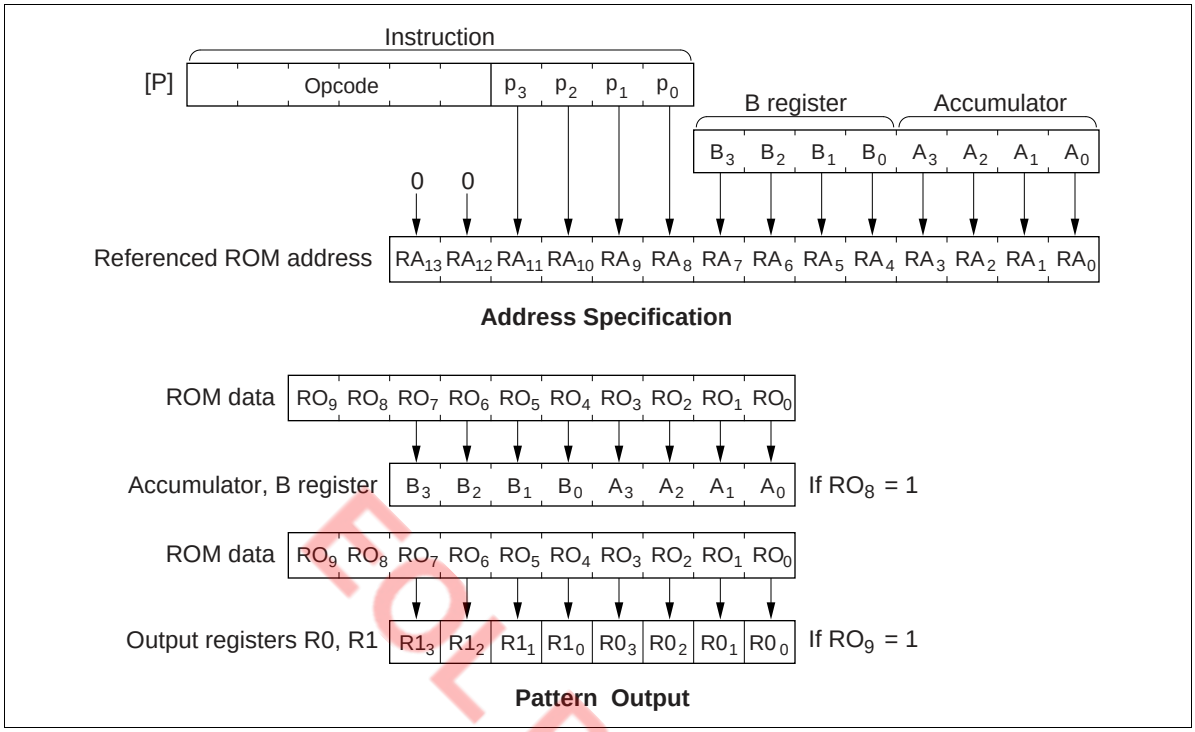


Figure 46 P Instruction

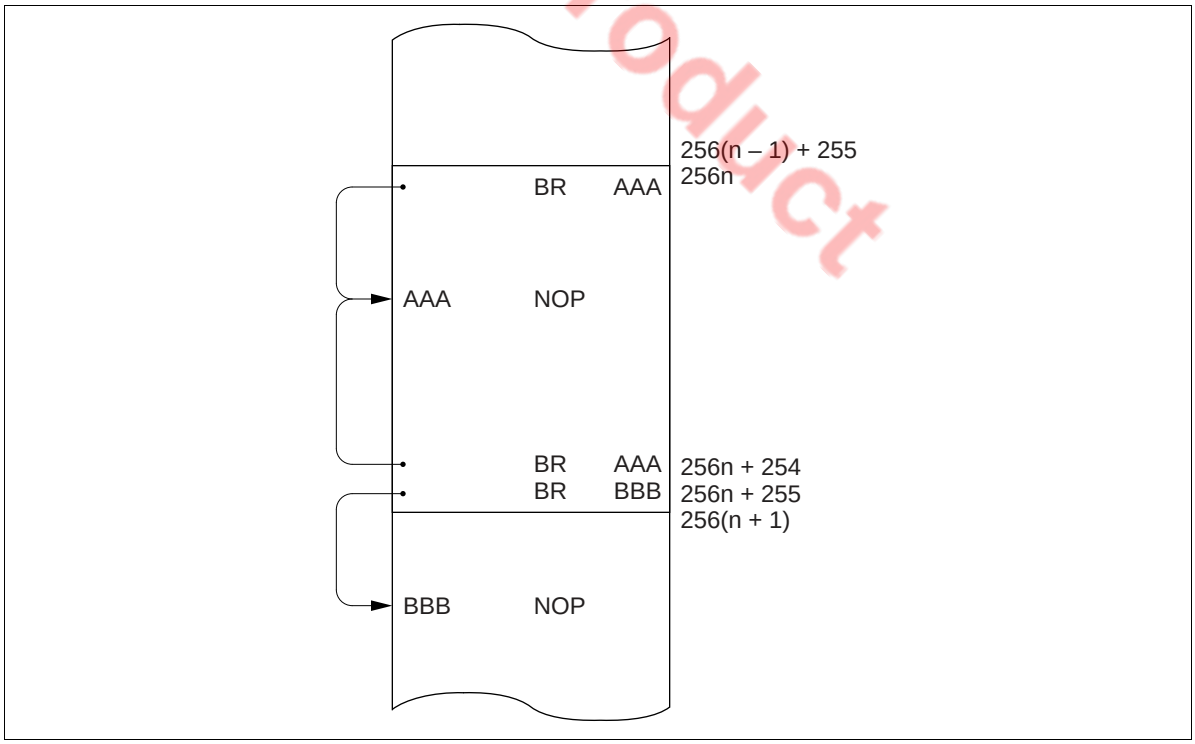


Figure 47 Branching when Branch Destination is on a Page Boundary

Absolute Maximum Ratings

Item	Symbol	Value	Unit	Notes
Power voltage	V_{CC}	–0.3 to +7.0	V	
Programming voltage	V_{PP}	–0.3 to +14.0	V	1
Pin voltage	V_T	–0.3 to V_{CC} + 0.3	V	
Total permissible input current	$\sum I_o$	100	mA	2
Total permissible output current	$-\sum I_o$	50	mA	3
Maximum input current	I_o	4	mA	4, 5
		30	mA	4, 6
Maximum output current	$-I_o$	4	mA	7, 8
Operating temperature	T_{opr}	–20 to +75	°C	
Storage temperature	T_{stg}	–55 to +125	°C	

Notes: Permanent damage may occur if these absolute maximum ratings are exceeded. Normal operation must be under the conditions stated in the Electrical Characteristics table. If these conditions are exceeded, the LSI may malfunction or its reliability may be affected.

1. D_{10} (V_{PP}) of the HD4074329 and HD4074329U.
2. The total permissible input current is the total of input currents simultaneously flowing in from all the I/O pins to ground.
3. The total permissible output current is the total of output currents simultaneously flowing out from V_{CC} to all I/O pins.
4. The maximum input current is the maximum current flowing from any I/O pin to ground.
5. Applies to D_8, R0–R5.
6. Applies to D_0–D_7.
7. The maximum output current is the maximum current flowing from V_{CC} to any I/O pin.
8. Applies to D_0–D_8, R0–R5.

Electrical Characteristics

DC Characteristics (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, GND = 0.0 V, T_a = –20°Cto+75°C; unless otherwise specified)

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Notes
Input high voltage	V_{IH}	RESET, $\overline{SCK}$, $\overline{INT_0}$, INT_1, SI,$\overline{EVENT}$	0.8V_{CC}	—	V_{CC} + 0.3	V	HD404324, HD404324U: HD404326, HD404326U: HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	
			0.9V_{CC}	—	V_{CC} + 0.3	V		
		OSC_1	V_{CC} – 0.5	—	V_{CC} + 0.3	V	HD404324, HD404324U: HD404326, HD404326U: HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	
			V_{CC} – 0.3	—	V_{CC} + 0.3	V		
Input low voltage	V_{IL}	RESET, $\overline{SCK}$, $\overline{INT_0}$, INT_1,$\overline{EVENT}$, SI	–0.3	—	0.2V_{CC}	V	HD404324, HD404324U: HD404326, HD404326U: HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	
			–0.3	—	0.1V_{CC}	V		

DC Characteristics (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, GND = 0.0 V, T_a = –20°Cto+75°C; unless otherwise specified) (cont)

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Notes
Input low voltage	V_{IL}	OSC_1	–0.3	—	0.5	V	HD404324, HD404324U: HD404326, HD404326U: HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	
			–0.3	—	0.3	V		
Output high voltage	V_{OH}	$\overline{SCK}$, SO, BUZZ	V_{CC} – 1.0	—	—	V	$–I_{OH}$ = 0.5 mA	
Output low voltage	V_{OL}	$\overline{SCK}$, SO, BUZZ	—	—	0.4	V	I_{OL} = 0.4 mA	
I/O leakage current	$\|I_{IL}\|$	RESET, $\overline{SCK}$, $\overline{INT_0}$, INT_1, SI, SO, OSC_1, BUZZ	—	—	1.0	µA	V_{in} = 0 to V_{CC}	1
Current dissipation in active mode	I_{CC}	V_{CC}	—	3	6	mA	V_{CC} = 5.0 V, f_{OSC} = 4 MHz	2
Current dissipation in standby mode	I_{SBY}	V_{CC}	—	0.6	1.5	mA	V_{CC} = 3.0 V, LCD on	3
Current dissipation in subactive mode	I_{SUB}	V_{CC}	—	50	70	µA	HD404324, HD404326, HD404328: V_{CC} = 3.0 V, LCD on	
			—	40	60	µA	HD404324U, HD404326U, HD404328U: V_{CC} = 3.0 V, LCD on	
			—	70	150	µA	HD4074329: V_{CC} = 3.0 V, LCD on	
			—	60	140	µA	HD4074329U: V_{CC} = 3.0 V, LCD on	
Current dissipation in watch mode(1)	I_{WTC1}	V_{CC}	—	4	15	µA	V_{CC} = 3.0 V, LCD off	4

DC Characteristics (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, GND = 0.0 V, T_a = –20°C to +75°C; unless otherwise specified) (cont)

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Notes
Current dissipation in watch mode(2)	I_{WTC2}	V_{CC}	—	15	35	µA	HD404324, HD404326, HD404328, HD4074329: V_{CC} = 3.0 V, LCD on	4
			—	5	25	µA	HD404324U, HD404326U, HD404328U, HD4074329U: V_{CC} = 3.0 V, LCD on	4
Current dissipation in stop mode	I_{STOP}	V_{CC}	—	1	10	µA	V_{CC} = 3.0 V, X1 = V_{CC}	4
Stop mode retain voltage	V_{STOP}	V_{CC}	2	—	—	V	No 32-kHz oscillator	5

Notes: 1. Output buffer current is excluded.

2. I_{CC1} is the source current when no I/O current is flowing while the MCU is in reset state.
   Test conditions: MCU: Reset
   Pins: RESET, $\overline{TEST}$, D_0–D_7, D_9, D_{10}, R0–R5 at V_{CC}
   D_8 open

3. I_{SBY} is the source current when no I/O current is flowing while the MCU timer is in operation.
   Test conditions: MCU: I/O reset
   Serial interface stopped
   Standby mode
   Pins: RESET at GND
   $\overline{TEST}$, D_0–D_7, D_9, D_{10}, R0–R5 at V_{CC}
   D_8 open

4. D_{10} is connected to V_{CC} in the HD4074329 and HD4074329U.

5. RAM data retention.

I/O Characteristics for Standard Pins (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, GND = 0.0 V, T_a = –20°C to +75°C; unless otherwise specified)

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Note
Input high voltage	V_{IH}	D_8–D_{10}, R0–R5	0.7V_{CC}	—	V_{CC} + 0.3	V		
Input low voltage	V_{IL}	D_8–D_{10}, R0–R5	–0.3	—	0.3V_{CC}	V		
Output high voltage	V_{OH}	D_8, R0–R5	V_{CC} – 1.0	—	—	V	$–I_{OH}$ = 0.5 mA	
Output low voltage	V_{OL}	D_8, R0–R5	—	—	0.4	V	I_{OL} = 0.4 mA	
I/O leakage current	$\|I_{IL}\|$	D_8, D_9, R0–R5	—	—	1.0	µA	V_{in} = 0 to V_{CC}	*
		D_{10}	—	—	1.0	µA	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{in} = 0 to V_{CC}	*
			—	—	20.0	µA	HD4074329, HD4074329U V_{in} = 0 to V_{CC}	
Pull-up MOS current	$–I_{pu}$	D_8, R0–R5	5	25	90	µA	V_{CC} = 3.0 V, V_{in} = 0.0 V	

Note: * Output buffer current is excluded.

I/O Characteristics for High-Current Pins (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, GND = 0.0 V, T_a = –20°C to +75°C; unless otherwise specified)

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Note
Input high voltage	V_{IH}	D_0–D_7	0.7V_{CC}	—	V_{CC} + 0.3	V		
Input low voltage	V_{IL}	D_0–D_7	–0.3	—	0.3V_{CC}	V		
Output high voltage	V_{OH}	D_0–D_7	V_{CC} – 1.0	—	—	V	$–I_{OH}$ = 0.5 mA	
Output low voltage	V_{OL}	D_0–D_7	—	—	0.4	V	I_{OL} = 0.4 mA	
			—	—	2.0	V	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: I_{OL} = 15 mA, V_{CC} = 4.5 V to 6.0 V	
							HD4074329, HD4074329U: I_{OL} = 15 mA, V_{CC} = 4.5 V to 5.5 V	
I/O leakage current	$\|I_{IL}\|$	D_0–D_7	—	—	1.0	µA	V_{in} = 0 to V_{CC}	*
Pull-up MOS current	$–I_{pu}$	D_0–D_7	5	25	90	µA	V_{CC} = 3.0, V_{in} = 0	

Note: * Output buffer current is excluded.

LCD Circuit Characteristics (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, GND = 0.0 V, T_a = –20°C to +75°C; unless otherwise specified)

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Note
Segment driver voltage drop	V_{DS}	SEG1–SEG24	—	—	0.6	V	I_d = 3.0 µA	1
Common driver voltage drop	V_{DC}	COM1–COM4	—	—	0.3	V	I_d = 3.0 µA	1
LCD power supply division resistor	R_W		100	300	900	kΩ	HD404324, HD404326, HD404328, HD4074329: Between V_1 and GND, $V_1 = V_{CC}$	
LCD voltage	V_{LCD}	V_1	2.7	—	V_{CC}	V	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U	2
			2.9	—	V_{CC}	V	HD4074329, HD4074329U	2

Notes: 1. V_{DS} and V_{DC} are the voltage drops from power supply pins V_1, V_2, and V_3, and GND to each segment pin and each common pin.

2. When V_{LCD} is supplied from an external source, the following relations must be retained: $V_{CC} \geq V_1 \geq V_2 \geq V_3 \geq GND$

A/D Converter Characteristics (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, AV_{SS} = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, AV_{SS} = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, AV_{SS} = 0.0 V, T_a = –20°C to +75°C; unless otherwise specified)

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Note
Analog power voltage	AV_{CC}	AV_{CC}	V_{CC} – 0.3	V_{CC}	V_{CC} + 0.3	V		
Analog input voltage	AV_{in}	AN_0–AN_3	AV_{SS}	—	AV_{CC}	V		
Current between AV_{CC} and AV_{SS}	I_{AD}	—	—	50	—	µA	V_{CC} = AV_{CC} = 5.0 V	
Analog input capacitance	CA_{in}	AN_0–AN_3	—	30	—	pF		
Resolution			8	8	8	Bit		
Number of inputs			0	—	4	Channel		
Absolute accuracy			—	—	±2.0	LSB		*
Conversion period			34	—	67	t_{cyc}		
Analog input impedance		AN_0–AN_3	1	—	—	MΩ	f = 1 MHz, V_{in} = 0.0 V	

Note: * Operating frequency of A/D conversion f_{OSC} is from 1 (MHz) to 4.5 (MHz).

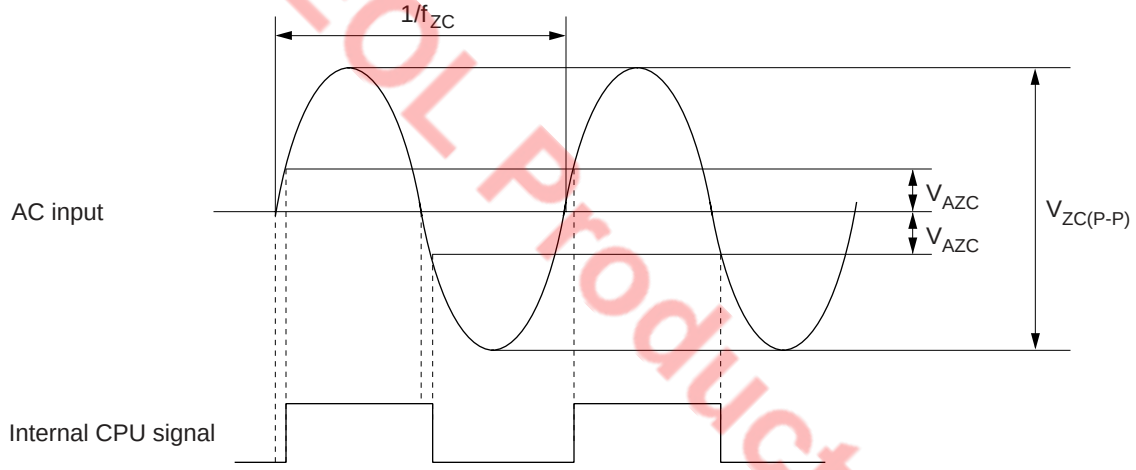
Zero-Crossing Detection Circuit Characteristics

Low Sensitivity Mode (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = 0°C to +70°C; HD4074329, HD4074329U: V_{CC} = 3.0 V to 5.5 V, GND = 0.0 V, T_a = 0°C to +70°C; unless otherwise specified)

Item	Symbol	Pin	Min	Typ	Max	Unit	Test Conditions	Note
Zero-crossing detection input voltage	V_{ZC}	ZCD	2.0	—	3.0	V_{P-P}	AC connection, C = 0.1 µF	
Zero-crossing detection accuracy	V_{AZC}		—	—	±750	mV	f_{ZC} = 50/60 Hz (sine wave), f_{OSC} = 4 MHz	Refer to figure 48
Zero-crossing detection input frequency	f_{ZC}		45	—	250	Hz		

High Sensitivity Mode (V_{CC} = 5.0 V, GND = 0.0 V, T_a = 0°C to 70°C, unless otherwise specified)

Item	Symbol	Pin	Min	Typ	Max	Unit	Test Conditions	Note
Zero-crossing detection input voltage	V_{ZC}	ZCD	2.0	—	3.0	V_{P-P}	AC connection, C = 0.1 µF	
Zero-crossing detection accuracy	V_{AZC}		—	—	±100	mV	f_{ZC} = 50/60 Hz (sine wave), f_{OSC} = 4 MHz, V_{CC} = 5.0 V	Refer to figure 48
Zero-crossing detection input frequency	f_{ZC}		45	—	1000	Hz		



Note: The internal CPU signal is shown lagging behind the original waveform in the figure, but this is not fixed—it could actually lead.

Figure 48 Zero-Crossing Detection

AC Characteristics (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, GND = 0.0 V, T_a = –20°C to +75°C; unless otherwise specified)

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Note
Clock oscillation frequency	f_{OSC}	OSC_1, OSC_2	0.4	4.0	4.5	MHz	1/8 division, 32 kHz used	1
			0.4	4.0	4.5	MHz	1/8 division used, 32 kHz not used	
		X1, X2	—	32.768	—	kHz		
Instruction cycle time	t_{cyc}		—	2	—	µs	f_{OSC} = 4 MHz	
Oscillation stabilization time(crystal)	t_{RC}	OSC_1, OSC_2	—	—	40	ms	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	2
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	
			—	—	60	ms		2
Oscillation stabilization time(ceramic)	t_{RC}	OSC_1, OSC_2	—	—	20	ms	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	2
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	
			—	—	60	ms		2
Oscillation stabilization time	t_{RC}	X1, X2	—	—	3	s		3
External clock high width	t_{CPH}	OSC_1	90	—	—	ns		4
External clock low width	t_{CPL}	OSC_1	90	—	—	ns		4
External clock rise time	t_{CPr}	OSC_1	—	—	20	ns		4
External clock fall time	t_{CPf}	OSC_1	—	—	20	ns		4
$\overline{INT_0}$, INT_1, $\overline{EVENT}$ high width	t_{IH}	$\overline{INT_0}$, INT_1, $\overline{EVENT}$	2	—	—	t_{cyc}/ t_{subcyc}		5
$\overline{INT_0}$, INT_1, $\overline{EVENT}$ width	t_{IL}	$\overline{INT_0}$, INT_1, $\overline{EVENT}$	2	—	—	t_{cyc}/ t_{subcyc}		5

Item	Symbol	Pin(s)	Min	Typ	Max	Unit	Test Conditions	Note
RESET high width	t_{RSTH}	RESET	2	—	—	f_{cyc}		6
RESET fall time	t_{RSTf}	RESET	—	—	20	ms		6
Input capacitance	C_{in}	All pins except D_{10}, AN_0–AN_3	—	—	30	pF	f = 1 MHz, V_{in} = 0.0 V	
		D_{10}	—	—	30	pF	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: f = 1 MHz, V_{in} = 0.0 V	
			—	—	180	pF	HD4074329, HD4074329U: f = 1 MHz, V_{in} = 0.0 V	

Notes:
1. If f_{OSC} = 0.4 MHz to 1.0 MHz, bit 3 of the miscellaneous register (MIS: $00C) must be set to 1; if f_{OSC} = 1.6 MHz to 4.5 MHz, bit 3 must be set to 0. Do not use f_{OSC} = 1.0 MHz to1.6 MHz with 32-kHz oscillation.
2. The oscillation stabilization time is the time required for the oscillator to stabilize after V_{CC} reaches 2.7 V (2.9 V for the HD4074329 and HD4074329U, or 3.5 V if V_{CC} = 3.5 V to 5.5 V) at power-on or after RESET input goes high after stop mode is canceled. At power-on and when stop mode is cancelled, RESET must be input for at least t_{RC} to ensure the oscillation stabilization time. If using a crystal oscillator or a ceramic oscillator, contact its manufacturer to determine what stabilization time is required, since it will depend on the circuit constants and stray capacitances.
3. The oscillation stabilization time is the time required for the oscillator to stabilize after V_{CC} reaches 2.7 V (2.9 V for the HD4074329 and HD4074329U) at power-on—at least t_{RC} must be ensured. If using a 32.768-kHz crystal oscillator, contact its manufacturer to determine what stabilization time is required, since it will depend on the circuit constants and stray capacitances.
4. Refer to figure 49.
5. Refer to figure 50. The t_{cyc} unit applies when the MCU is in standby or active mode.
   The t_{subcyc} unit applies when the MCU is in watch or subactive mode. t_{subcyc} = 244.14 µs (32.768-kHz crystal)
6. Refer to figure 51.

Serial Interface Timing Characteristics (HD404324, HD404326, HD404328: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –20°C to +75°C; HD404324U, HD404326U, HD404328U: V_{CC} = 2.7 V to 6.0 V, GND = 0.0 V, T_a = –40°C to +85°C; HD4074329, HD4074329U: V_{CC} = 2.9 V to 5.5 V, GND = 0.0 V, T_a = –20°C to +75°C; unless otherwise specified)

During Transmit Clock Output

Item	Symbol	Pin	Min	Typ	Max	Unit	Test Conditions	Notes
Transmit clock cycle time	t_{Scyc}	$\overline{SCK}$	1.0	—	—	t_{cyc}, t_{subcyc}	Load shown in figure 53	1, 2
Transmit clock high width	t_{SCKH}	$\overline{SCK}$	0.3	—	—	t_{Scyc}	Load shown in figure 53	1
Transmit clock low width	t_{SCKL}	$\overline{SCK}$	0.3	—	—	t_{Scyc}	Load shown in figure 53	1
Transmit clock rise time	t_{SCKr}	$\overline{SCK}$	—	—	100	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V, load shown in figure 53	1
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V, load shown in figure 53	1
			—	—	200	ns	Load shown in figure 53	1
Transmit clock fall time	t_{SCKf}	$\overline{SCK}$	—	—	100	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V, load shown in figure 53	1
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V, load shown in figure 53	1
			—	—	200	ns	Load shown in figure 53	1
Serial output data delay time	t_{DSO}	SO	—	—	300	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V, load shown in figure 53	1
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V, load shown in figure 53	1
			—	—	500	ns	Load shown in figure 53	1

Notes: 1. Refer to figure 52.
2. The t_{subcyc} unit applies when subactive mode is operating.

Item	Symbol	Pin	Min	Typ	Max	Unit	Test Conditions	Note
Serial input data setup time	t_{SSI}	SI	200	—	—	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	*
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	*
			300	—	—	ns		*
Serial input data hold time	t_{HSI}	SI	150	—	—	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U V_{CC} = 3.5 V to 6.0 V	*
							HD4074329, HD4074329U V_{CC} = 3.5 V to 5.5 V	*
			300	—	—	ns		*

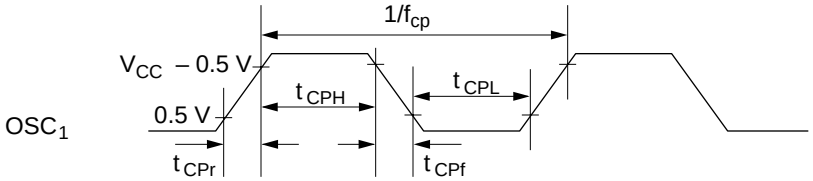
Note: * Refer to figure 52.

During Transmit Clock Input

Item	Symbol	Pin	Min	Typ	Max	Unit	Test Conditions	Notes
Transmit clock cycle time	t_{Scyc}	$\overline{SCK}$	1.0	—	—	t_{cyc}, t_{subcyc}		1, 2
Transmit clock high width	t_{SCKH}	$\overline{SCK}$	0.3	—	—	t_{Scyc}		1
Transmit clock low width	t_{SCKL}	$\overline{SCK}$	0.3	—	—	t_{Scyc}		1
Transmit clock rise time	t_{SCKr}	$\overline{SCK}$	—	—	100	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	1
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	1
			—	—	200	ns		1
Transmit clock fall time	t_{SCKf}	$\overline{SCK}$	—	—	100	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	1
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	1
			—	—	200	ns		1
Serial output data delay time	t_{DSO}	SO	—	—	300	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V, load shown in figure 53	1
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V, load shown in figure 53	1
			—	—	500	ns	Load shown in figure 53	1
Serial input data setup time	t_{SSI}	SI	200	—	—	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	1
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	1
			300	—	—	ns		1
Serial input data hold time	t_{HSI}	SI	150	—	—	ns	HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U: V_{CC} = 3.5 V to 6.0 V	1
							HD4074329, HD4074329U: V_{CC} = 3.5 V to 5.5 V	1
			300	—	—	ns		1

Notes: 1. Refer to figure 52.
2. The t_{subcyc} unit applies when subactive mode is operating.

V_{CC} = 3.5 V to 6.0 V (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
V_{CC} = 3.5 V to 5.5 V (HD4074329, HD4074329U)



V_{CC} = 2.7 V to 3.5 V (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
V_{CC} = 2.9 V to 3.5 V (HD4074329, HD4074329U)

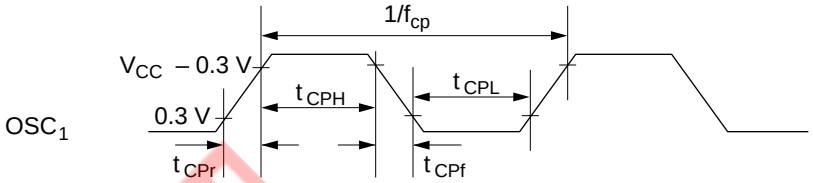
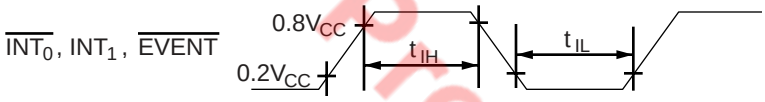


Figure 49 Oscillator Timing

V_{CC} = 3.5 V to 6.0 V (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
V_{CC} = 3.5 V to 5.5 V (HD4074329, HD4074329U)



V_{CC} = 2.7 V to 3.5 V (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
V_{CC} = 2.9 V to 3.5 V (HD4074329, HD4074329U)

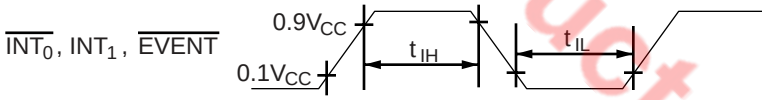
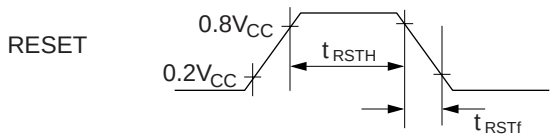


Figure 50 Interrupt Timing

V_{CC} = 3.5 V to 6.0 V (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
V_{CC} = 3.5 V to 5.5 V (HD4074329, HD4074329U)



V_{CC} = 2.7 V to 3.5 V (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
V_{CC} = 2.9 V to 3.5 V (HD4074329, HD4074329U)

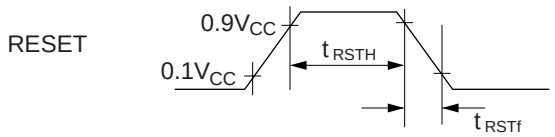
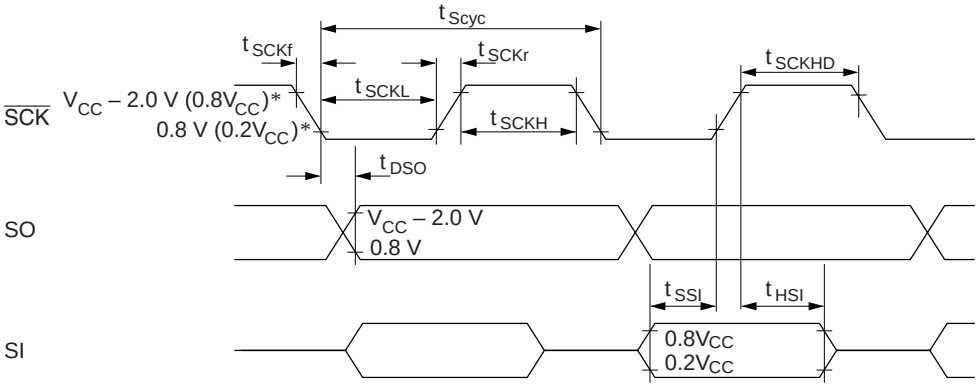


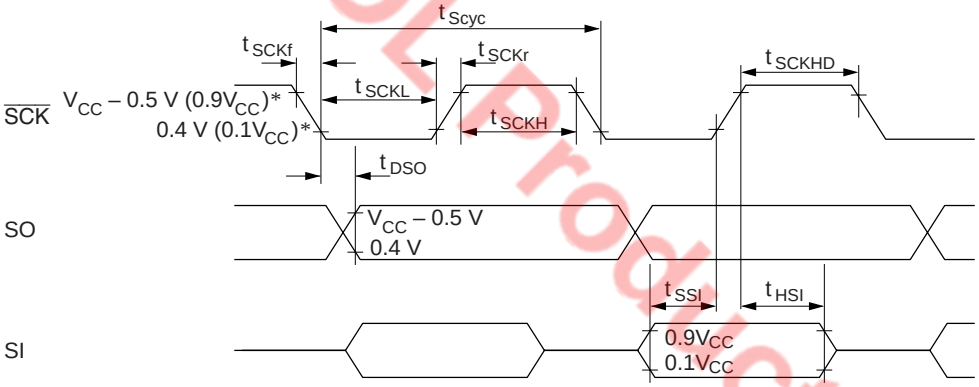
Figure 51 Reset Timing

V_{CC} = 3.5 V to 6.0 V (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
V_{CC} = 3.5 V to 5.5 V (HD4074329, HD4074329U)



Note: * V_{CC} – 2.0 V and 0.8 V are the threshold voltages for transmit clock output, $0.8V_{CC}$ and $0.2V_{CC}$ are the threshold voltages for transmit clock input, and t_{DSO}, t_{SSI}, and t_{HSI} are the timings used with transmit clock input voltages.

V_{CC} = 2.7 V to 3.5 V (HD404324, HD404324U, HD404326, HD404326U, HD404328, HD404328U)
V_{CC} = 2.9 V to 3.5 V (HD4074329, HD4074329U)



Note: * V_{CC} – 0.5 V and 0.4 V are the threshold voltages for transmit clock output, $0.9V_{CC}$ and $0.1V_{CC}$ are the threshold voltages for transmit clock input, and t_{DSO}, t_{SSI}, and t_{HSI} are the timings used with transmit clock input voltages.

Figure 52 Serial Interface Timing

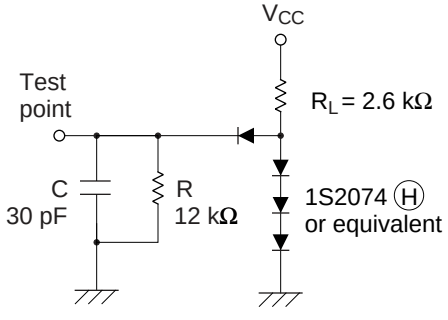


Figure 53 Timing Load Circuit

Option List HD404324, HD404324Li, HD404326, HD404326U, HD404328, HD404328U

Please check off the appropriate applications and enter the necessary information.

Date of order	/ /
Customer	
Department	
ROM code name	
LSI number (to be filled in by Hitachi)	

1. ROM size

☐ HD404324	4-kword	With internal
☐ HD404326	6-kword	LCD voltage
☐ HD404328	8-kword	division registers
☐ HD404324U	4-kword	Without internal
☐ HD404326U	6-kword	LCD voltage
☐ HD404328U	8-kword	division registers

2. Optional Function (1)

*☐ With 32-kHz CPU operation
*☐ Without 32-kHz CPU operation, with time-base for clock
☐ Without 32-kHz CPU operation, without time-base

Note: * Options marked with an asterisk require a subsystem crystal oscillator (X1, X2).

3. Optional Function (2)

☐ With zero-crossing detection function
☐ Without zero-crossing detection function

4. ROM Code Media
Please specify the first type below (the upper bits and lower bits are mixed together), when using the EPROM on-package microcomputer type (including ZTAT™ version).

☐ EPROM: The upper bits and lower bits are mixed together. The upper five bits and lower five bits are programmed to the same EPROM in alternating order (i.e., LULULU...).
☐ EPROM: The upper bits and lower bits are separated. The upper five bits and lower five bits are programmed to different EPROMS.

5. System Oscillator for OSC1 and OSC2

☐ Ceramic oscillator	f =	MHz
☐ Crystal oscillator	f =	MHz
☐ External clock	f =	MHz

6. Stop Mode

☐ Used
☐ Not used

7. Packages

☐ DP-64S
☐ FP-64A
☐ FP-64B

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